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/ADDITION OF BUILT-IN SELF-TESTING CAPABILITY
TO THE INTEL SBC 80/10A SINGLE BOARD COMPUTER/

by

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1. INTRODUCTION

The continuous refinement of digital integrated circuit design and production techniques has made possible the development of microcomputer systems which exhibit functional performance characteristic that had not previously been possible to obtain using a single board. These same techniques which enable the evolution of complicated computer systems with such powerful capabilities have also created challenging opportunities for the test engineer to develop parallel techniques which will provide an adequate data base necessary to insure proper functional performance.

Innovations in computer test methodology in the last decade have come in response to increases in the power and complexity of these complicated computer systems (see Figure. 1), but even then new systems were becoming increasingly tough for tester to handle and programmers have to work hard to generate test exercises that could achieve an adequate level of test comprehensiveness.

Two common approaches are used to diagnose problems at board level [8]. The in-circuit method which isolates each component on the board and test it individually. In the event of failure, the tester will generate a component level diagnostic to assist in repairing the defect. In contrast, the functional test method operates the board as a unit and checks for discrepancies between actual and ideal behavior.

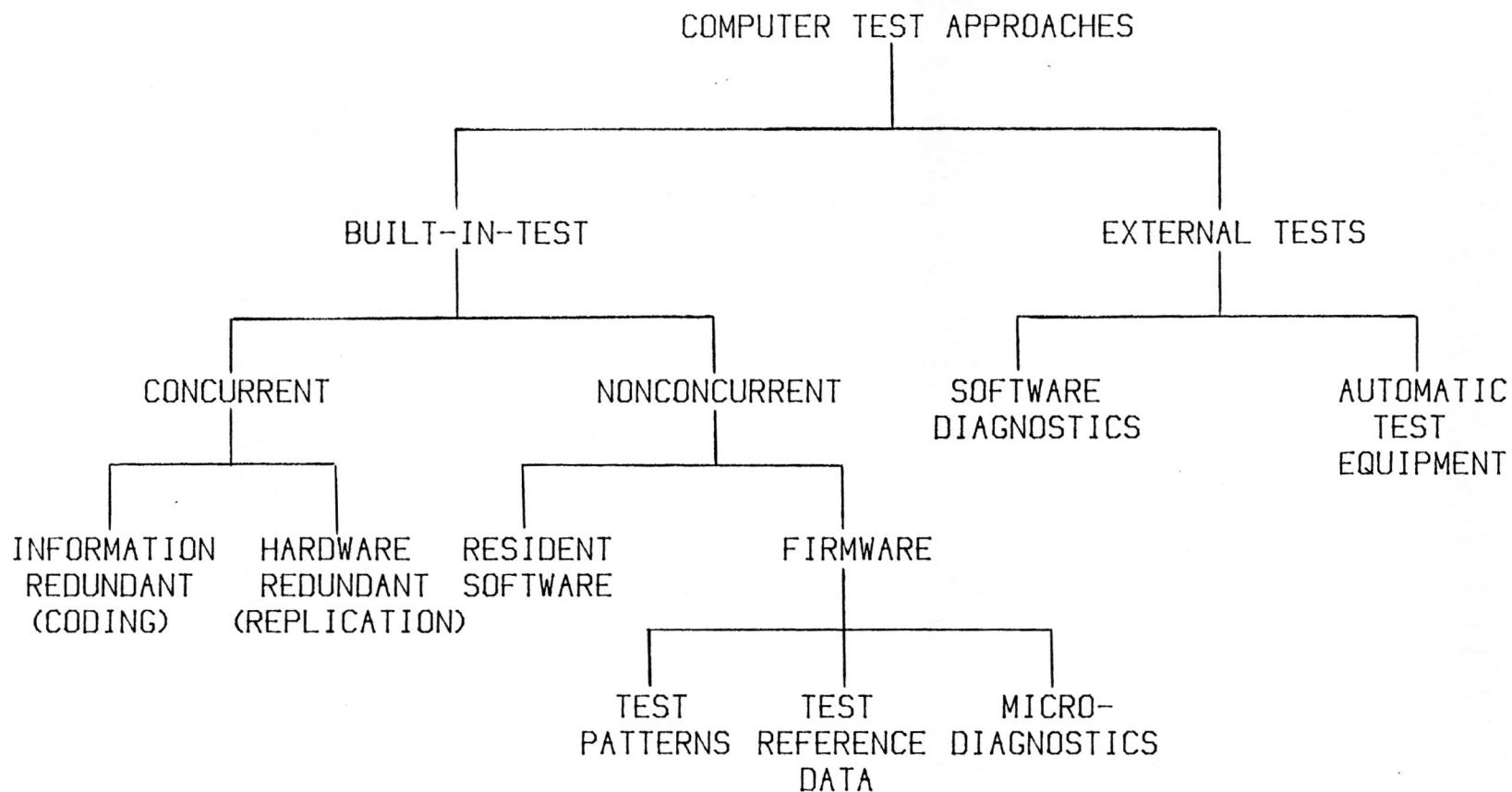


Figure 1. Computer Test Methodology

(Adapted From [11])

Both the in-circuit and functional test methods required external Automatic Test Equipment (ATE) to assist in the testing procedure.

Both in-circuit and functional testers suffer from a common problem [12]: the increasing difficulty of generating a comprehensive test problem due to the growing functional complexity of devices and board. The same complexity, however has provided the impetus for the emergence of new test techniques. Designers of the new boards also face the same complexity issues. Their response has been to impose a structure on their boards in order to make their design decisions manageable. Large scale integration (LSI)-based boards today are characterized by the increasingly pervasive microprocessor. The microprocessor allows much of the board's functionality to be defined in software, allowing designers to spend more effort on defining what that function is and less on its implementation.

Just as the increasing use of microprocessors is helping to structure the task of the board designer, so is it helping to structure the task of the test engineer. One increasingly common test approach that take advantage of this structure is the SELF-TEST, which is in essence the purpose of this project: to design and implement a BUILT-IN SELF-TESTING technique on the Intel SBC 80/10A single board computer . Upon execution or completion of the test, it would have some kind of indication (usually a GO/NO-GO

message) to indicate whether the board under test is good or bad.

2.0 REVIEW OF BUILT-IN-TEST

As computer performance has increased, testing problems have become more difficult because of increased system complexity and decreased circuit controllability and observability. Controllability and observability problems have long been the focus of struggles of the digital test engineer as the density of computer IC increased. New testing approaches have become necessary in many computer applications to provide on-line visibility into computer functional processes. A viable approach to increased on-line computer process visibility is the built-in-test [11].

In general, built-in-test refers to testing approaches which are an integral part of a particular computer design [11]. Built-in-test is therefore distinguished from external testing approaches which are executed when a computer is off-line using external automatic test equipment or software diagnostic loaded from a data storage medium (refer to Figure. 1).

Built-in-test approaches may be implemented in computer hardware, firmware or software. Some schemes can be executed during system run-time, concurrently with on-going functional operations or during convenient system idle time. In real-time applications, particularly where special-purpose processing is done, built-in-test is often implemented in hardware separate from functional computer resources to allow concurrent testing during normal computer

operation.

Concurrent built-in-test techniques are an important subcategory which may be generally classified as information redundant or hardware redundant. Information redundant built-in-tests include popular coding schemes such as parity, cyclic redundancy checks, error-correcting codes, etc. Hardware redundant built-in-test techniques range from self-testing circuits at the gate level, through duplication at the module level, to replicated computer at the system level.

Nonconcurrent built-in-test may conveniently exist in resident software which can be called by a computer operating system when needed. Software built-in-test is usually executed during times when normal functional processing is not being done. This approach to built-in-test is low-cost, since only minimum special purpose hardware is required [14].

2.1 BUILT-IN SELF-TESTING TECHNIQUE

Built-in self-testing is similar in definition to built-in-test and can also be implemented in computer hardware, firmware or software. As we know from section 2.0, built-in-test has such a broad definition that it really depends on what the applications are. We will have a somewhat restricted definition for the built-in self-testing

concept as used in this research or application. It is a test program written in the processor's own language to exercise the board's functions in order to verify that all essential parts are working correctly.

With this method, only minimum hardware is required to generate the large volume of stimulus data [14]. All it needs is some spare memory in ROM for storing the self-test program, some interconnecting logic and edge-connectors for setting up the test; see Section 5.0.

The self-test technique should be able to verify the working condition of the following parts of a computer system (Intel SBC 80/10A in this case):

1. Verify the basic operation of the address and data busses,
2. Verify operation of the central processing unit (CPU),
3. Verify the ROM(s) containing the system software,
4. Verify the ROM containing the self-test program,
5. Check the ability to read or write from RAM,
6. Perform tests to exercise the control logic,
7. Verify operation of the I/O ports (both serial and parallel),
8. Verify the external system bus (multibus interface).

Self-test can radically reduce the amount of ATE needed, because the GO/NO-GO indication can quickly identify

whether the Intel SBC 80/10A board is good or bad. It must be noted that the self-test technique verifies faults, it does not diagnose them. Diagnosis is not the scope of this research.

3.0 FUNCTIONAL DESCRIPTION OF THE INTEL SBC 80/10A BOARD

The Intel SBC 80/10A board is a complete computer system built on a single 6.75" by 12.00" printed circuit board (see Figure A-1 of Appendix A). The CPU, system clock, read/write memory, non-volatile read-only-memory, I/O ports and drivers, serial and parallel communication interface, bus control logic and drivers all reside on the board.

The circuitry on the Intel SBC 80/10A board can be divided into six functional blocks (Figure. 2):

1. CPU set,
2. System bus interface,
3. Random access memory (RAM),
4. Read-only-memory (ROM),
5. Serial I/O port,
6. Parallel I/O port.

3.1 CPU Set

The CPU set consists of the Intel 8080A central processor, the 8224 clock generator and the 8238 system controller (Figure 3). The CPU set is the brain of the Intel SBC 80/10A board. It performs all the system processing functions and provides a stable timing reference for all other circuitry in the system. The CPU set generates all of the address and control signals necessary to access

the memory and the I/O ports both on and external to the Intel SBC 80/10A board.

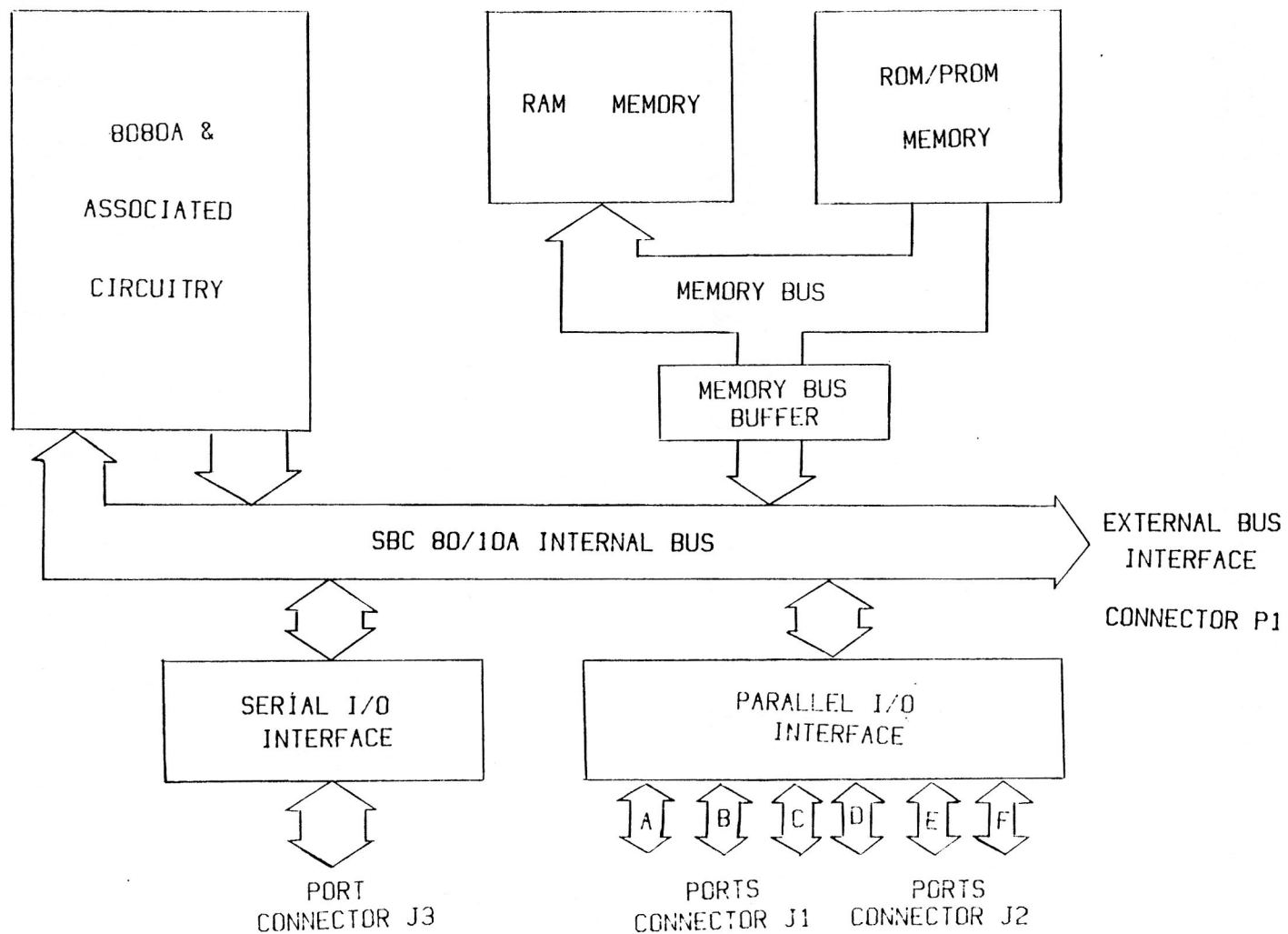


Figure 2. Functional Block Diagram of SBC 80/10A

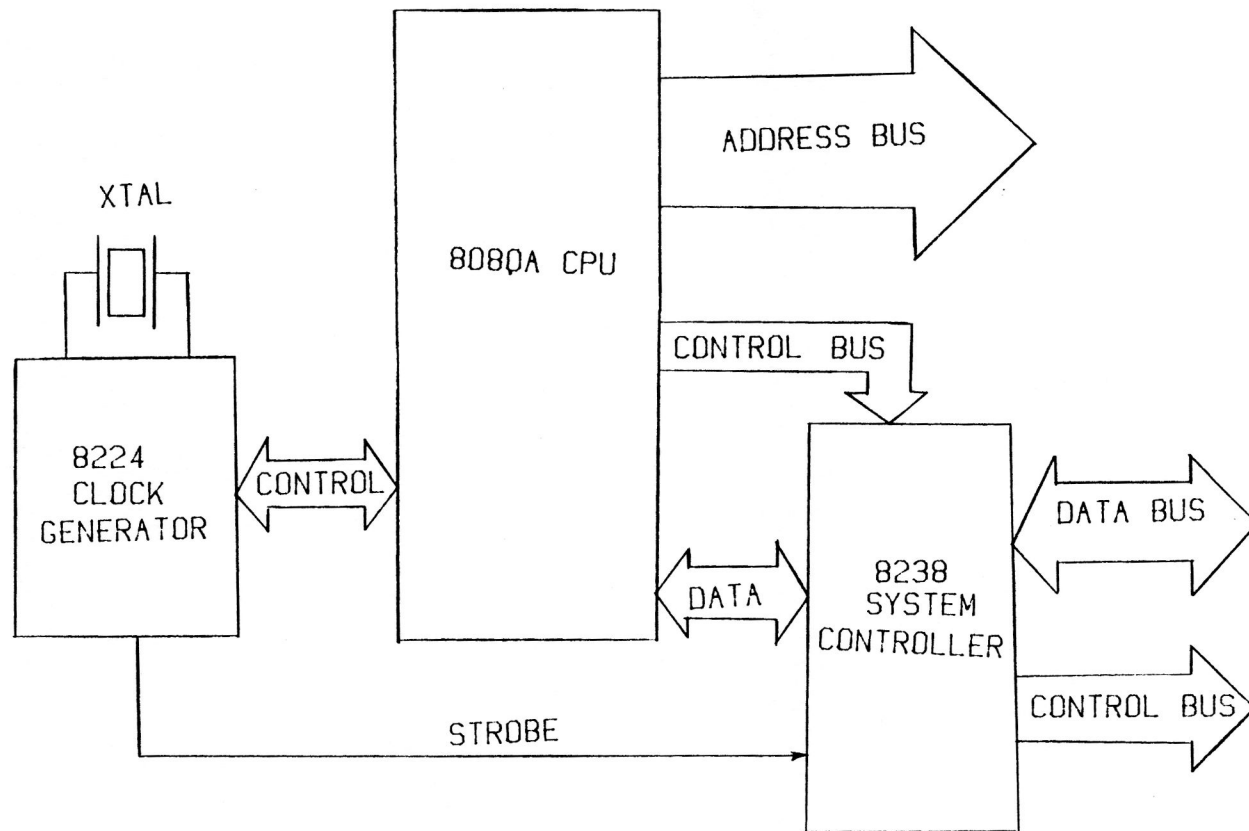


Figure 3. CPU Sets

(Adapted From [1])

3.2 The System Bus Interface

The system bus interface includes all those circuits that drive the various system control signals which also includes two Intel 8216 bi-directional bus drivers and six Intel 8226 devices which drive the memory data bus and the external system data and address busses, respectively.

3.3 The Random Access Memory (RAM)

It provides the Intel SBC 80/10A users with 1024 x 8 bits (1K) of onboard read/write storage, and is made up of eight Intel 8102 low power static RAMs (1024 x 1 bit each).

3.4 The Read-Only-Memory (ROM)

The Intel SBC 80/10A has four 24-pin sockets that can accept either Intel 8708 erasable and electrically reprogrammable ROM (EPROM) chips or Intel 8308 metal masked ROM chips, or Intel 2716 EPROM chips or Intel 2758 EPROM chips or Intel 2316 metal masked ROM chips. The total ROM/EPROM memory capacity using the 8708, 8308 or 2758 is 4K x 8 bits and 8K x 8 bits using the 2716 or 2316 chips.

3.5 The Serial I/O Interface

The Intel 8251 USART device provides a bi-directional serial data communication channel that can be programmed to operate with most of the current serial data transmission protocols: synchronous or asynchronous mode,

baud rate, character length, number of stop bits and the choice of even, odd or no parity are all program selectable.

3.6 The Parallel I/O Interface

Two Intel 8255 Programmable Peripheral interface devices provide 48 I/O lines for the transfer and control of data to or from external peripheral devices. Eight lines already have a bi-directional driver and termination network permanently installed. These bi-directional networks allow the eight lines to be configured as input, output or bi-directional and the remaining 40 lines have sockets provided for the installation of drivers or termination networks as required to meet the specific needs of the users ,see Section 4.3.1 on testing the parallel I/O ports.

4.0 TESTING OF THE INTEL SBC 80/10A SINGLE BOARD COMPUTER

The presence of the CPU on the Intel SBC 80/10A board allows it to exhibit self-testing capabilities (i.e., the intelligence of the microprocessor will be made use of since all the test programs are written in the processor language). All it needs is the addition of a self-test ROM containing all the necessary self-test software, some interfacing logic and connectors. This self-test software can be executed on a regular basis, such as each time the single board computer is powered up. In this application, basic tests such as continuity, power shorts, signal shorts, address and data pins stuck high or low, I/O pins stuck high or low, presence of clock signal, etc., would be performed. After the tests, the self-test routine would give a GO/NO-GO indication as to whether the Intel SBC 80/10A board is good or bad.

The remaining portion of this section will be devoted to detailing how the different parts of the Intel SBC 80/10A board are tested.

The minimum parts of the Intel SBC 80/10A board that are to be tested are:

1. onboard microprocessor,
2. onboard RAM,
3. onboard ROM,
4. address and data lines,

5. serial and parallel I/O ports,
6. external system bus (multibus interface).

4.1 Testing the Onboard Microprocessor

The Intel SBC 80/10A board utilized the 8080A single-chip, N-channel microprocessor for all its system processing functions (example, arithmetic and logic calculations).

The 8080A is a complete 8-bit parallel central processing unit (CPU). It contains six 8-bit general-purpose working registers and an accumulator. The six general-purpose registers may be addressed individually or in pairs, providing both single and double precision operations. The 8080A microprocessor also has an external stack feature wherein any portion of memory may be used as a last in/first out stack to store/retrieve the contents of the accumulator, flags, program counter and all of the six general-purpose registers. The 16-bit stack pointer controls the addressing of this external stack. A brief block diagram of the 8080A is shown in Figure 4.

Most of the test programs are influenced by the internal structure of the microprocessor. Some aim to exercise each functional block in the microprocessor, whereas others aim to test the device pin for stuck-at-0 and stuck-at-1 faults, and still others aim to test only the instruction sets [5]. The structural approach normally

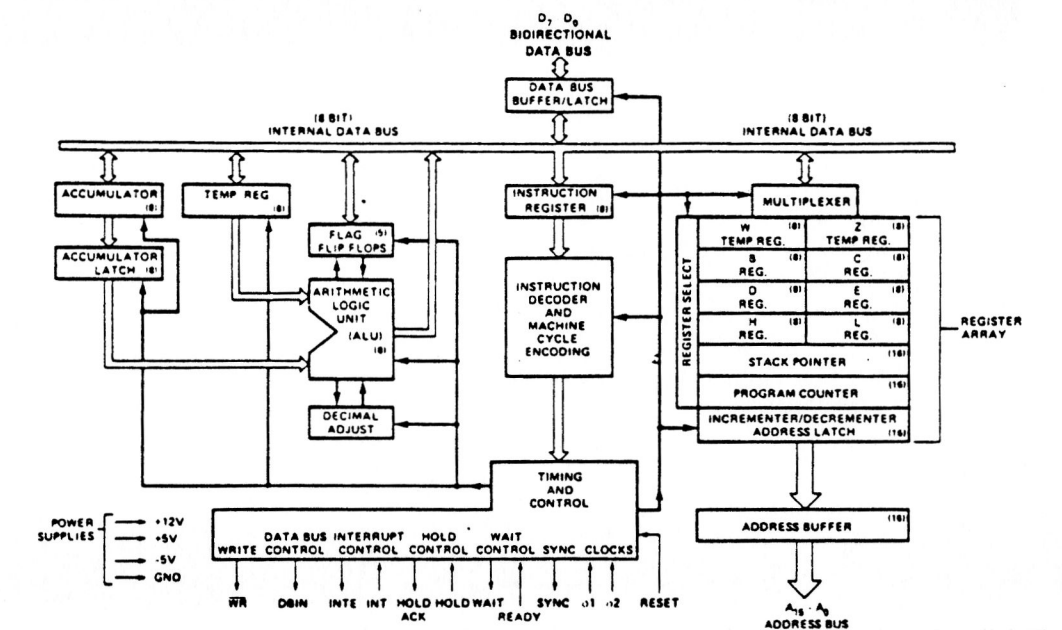


Figure 4. 8080A Functional Block Diagram
(Adapted From [29])

requires a detailed logical description of the microprocessor and this information is usually not available to the user. Even if we know the details of the circuit realization, an enormous amount of computation is needed to generate tests at the gate level, due to the large number of gates on the chip. However, testing of the instruction sets will usually exercise both the structure and most of the pins on the microprocessor. Hence the latter method will be used to test the onboard microprocessor.

There are two possibilities for carrying out the microprocessor test [3]: either the open loop testing or the closed loop testing. In the former case, the instructions come from the tester in a sequence completely under external tester (ATE) control, whereas in the latter case, the microprocessor itself determines the instructions sequencing.

Since we are developing a program for built-in self-testing, the microprocessor can only be executed in a closed loop manner and without an external tester.

One of the most interesting methods for testing a microprocessor, particularly in the user testing environment, was suggested by Brahme and Abraham in [24] and then modified by Abraham and Parker in [23]. This method is easy to set up and we only need to know the register and instruction sets of the microprocessor. Only certain parts of the methods described in [23] and [24] were used for our

testing purposes.

The test designed for the microprocessor has the following purposes:

1. detect stuck-at-0 and stuck-at-1 faults on the microprocessor address and data lines,
2. detect stuck-at-0 and stuck-at-1 faults in the registers,
3. detect stuck-at-0 and stuck-at-1 faults in the Arithmetic and Logic unit,
4. detect stuck-at-0 and stuck-at-1 faults in its supporting circuitry.

4.1.1 Generation of test sequence

The microprocessor instruction sets were divided into four main categories:

1. Data transfer group (example, MOV R_1 R_2 , MVI R_1 #, LXI R_1 address, etc.),
2. Arithmetic and logical group (example, ADD, SUB, DCR, ORA, XRA, etc.),
3. Branch control group (example, JMP, JNZ, CNZ, etc.),
4. I/O group (example, IN, OUT, etc.).

Under a fault in a microprocessor, either or both of the following may happen [23] :

1. an instruction is not executed,

2. the information stored in the microprocessor is incorrectly modified. The incorrect modification of the storage elements or registers will result in their being :

- a. reset to zero,
- b. set to one,
- c. overwritten with the contents of other registers (with the AND or OR function of the registers),
- d. exchanged,
- e. complemented.

At any time during execution of the self-test program, we assume the presence of any number of faults but only in one function described above. This assumption can be justified in our case because of the locality of failures and the frequency of tests. However, even if this assumption is not justified, it is unlikely that a test based on it will fail to detect a fault affecting two functions. Of course, if the additional instruction does not cause anything to be incorrectly modified in the microprocessor, then the fault is undetectable. However, as long as we can detect the faulty behavior (as a result of erroneous data), we really do not care whether it was caused by the execution of another extra instruction or by accessing a register or

by the AND or OR function of any register pair.

4.1.2 Test procedure

To test for the faults just described, we merely have to execute each instruction, make sure that it was correctly executed and none of the internal storage/registers was incorrectly modified.

Note that we have to execute other instructions in order to read the internal storage/registers and these instructions may themselves be faulty. The result may be that the correct (expected) data may be seen at the output pins as a result of interaction between faults. In order to ensure that such fault-masking does not exist, we will apply the tests in the following order [3].

Microprocessor Test Procedures

- A. Test the reading-out and the loading of the internal registers,
- B. Test as many of the "frequently used" instructions as possible.

The above tests will first ensure that the instructions can be executed correctly and that they do not destroy the information in the microprocessor.

Since the registers have to be read out after each instruction, we have to first ensure that all registers can be read out correctly and that the reading-out process

does not cause information to be changed inside the microprocessor. This test can be implemented with the data transfer group instruction.

We start with loading different code words [24] in each register. The property that the code words should satisfy is that any faults (AND or OR function of two registers) operating on code words should produce a non-code word. One of the commonly used codes is the d-out-of-w code. This code word will ensure that the AND or OR function of any set of registers will not be the same as the valid code word.

We illustrate the use of code word with the available 8080A data :

$N = \# \text{ of register} = 7$

$w = \text{width of register in bit} = 8$

$d \geq 1$

$$\frac{w!}{d! (w-d)!} \geq N$$

With the above information and formula, we could use a 1-out-of-8 code. The code words are listed in Table 1.

Table 1. Code Word Assignment to Registers for Test Procedure A

Register	Bit Number							
	0	1	2	3	4	5	6	7
A	0	1	1	1	1	1	1	1
B	1	0	1	1	1	1	1	1
C	1	1	0	1	1	1	1	1
D	1	1	1	0	1	1	1	1
E	1	1	1	1	0	1	1	1
H	1	1	1	1	1	0	1	1
L	1	1	1	1	1	1	0	1

Verification of Faults

CASE1. Consider the fault if register A is AND with register C.

$R_A:01111111$ AND $R_C:11011111$ ---> $R_A:01011111$

CASE 2. Consider the fault if register D is OR with register H.

$R_D:11101111$ OR $R_H:11111011$ ---> $R_D:11111111$

and so on.

Microprocessor Test Procedure A (Register Check Test)

1. Load different code words into each register.

2. For i = 0 to 6 do

For j = 0 to 6 do

begin

Read and compare (i)

Read and compare (j)

Read and compare (i)

Read and compare (j)

end

The error will be detected when the registers are checked against their corresponding code words during the test. If step 1 does not load the registers correctly, we will detect it when the registers are read out. The two reads are necessary to ensure that reading a register does not change the content of another register.

Note that with the above test, if two adjacent cells of a register are bridged, then the fault will not be detected and will probably be propagated to other tests. In order to avoid this undetected fault, a marching 1's or 0's test pattern can be used as the code word, i.e., the rotation of a 1 or 0 around the register. Hence an extra step, rotate the register to the right, will be inserted after step 2.

With the 8080A instruction sets only the accumulator can be read out directly, other registers (B, C, D, E, H and L) have to be read out through the accumulator. Again we have to ensure that the internal transfer instructions do not cause the code words to be modified in other registers. The test conducted will therefore be in stages, with the register which can be read out directly tested first, followed by the registers which can only be read out in two steps.

The above would utilize about 80% of the data transfer group instructions and 10% of the other groups (example, CMP, CPI, RAL, RAR, etc., of the arithmetic and

logical group, and JMP, CALL, CNZ, CZ, etc., of the branch control group).

Once the register read test is completed, we can be sure that all the registers can be safely read out. Although the program counter and the stack pointer are not directly tested, nevertheless it must be pointed out that the correct execution of the test program verifies indirectly or implicitly, at least to some extent, that these registers are functioning properly.

An exhaustive test of all the 8080A instructions is practically impossible because it might make the test several times longer than it should be. Hence we must choose to test only the most frequently used instructions. A list of the frequently used instructions can be found in Table 3-1, page 3-5 in [17]. Of course the term "frequently used" might be subject to different interpretations depending on the kind of application that the 8080A microprocessor is used for, but a lot of the "frequently used" instructions described here constitute at least 90% of any software package [17].

The group of instructions used in microprocessor Test Procedure A is used to test the remainder of the instruction set, each tested instruction is then added to this group, and so on. When testing the other instructions, it is desirable to test the most "reliable" instructions first [5], so that the above group only contains the most "reliable" instructions. One definition of "reliable" is given by [30] and depends upon the minimum sum of the number of machine cycles taken to execute the instruction.

Microprocessor Test Procedure B (other instructions Test)

1. ADD and ADC instructions

(Initial Code Words for Registers)

A = 10000000

B = 01000000

C = 00100000

D = 00010000

E = 00001000

H = 00000100

L = 00000010

Test Sequence

1. STC, ADC B, ADD C, ADD D, ADD E, ADD H, ADD L,
CPI FF.
2. STC, ADD B, ADC C, ADD D, ADD E, ADD H, ADD L,
CMA, CPI 00.

3. STC, ADD B, ADD C, ADC D, ADD E, ADD H, ADD L,
CPI FF.
4. STC, ADD B, ADD C, ADD D, ADC E, ADD H, ADD L,
CMA, CPI 00.
5. STC, ADD B, ADD C, ADD D, ADD E, ADC H, ADD L,
CPI FF,
6. STC, ADD B, ADD C, ADD D, ADD E, ADD H, ADC L,
CMA, CPI 00.

2. SUB and SBB instructions

(Initial Code Words for Registers)

A = 01111111

B = 01000000

C = 00100000

D = 00010000

E = 00001000

H = 00000100

L = 00000010

Test Sequence

1. STC, SBB B, SUB C, SUB D, SUB E, SUB H, SUB L,
CMA, CPI FF.
2. STC, SUB B, SBB C, SUB D, SUB E, SUB H, SUB L,
CPI 00.
3. STC, SUB B, SUB C, SBB D, SUB E, SUB H, SUB L,
CMA, CPI FF.
4. STC, SUB B, SUB C, SUB D, SBB E, SUB H, SUB L,

CPI 00.

5. STC, SUB B, SUB C, SUB D, SUB E, SBB H, SUB L,
CMA, CPI FF.

6. STC, SUB B, SUB C, SUB D, SUB E, SUB H, SBB L,
CPI 00.

3. ANA instruction

(Initial Code Words for Registers)

A = 01111111

B = 10111111

C = 11011111

D = 11101111

E = 11110111

H = 11111011

L = 11111101

Test Sequence

1. ANA B, ANA C, ANA D, ANA E, ANA H, ANA L, ANI 00,
CPI 00, CMA, CPI FF.

4. ORA instruction

(Initial Code Words for Registers)

A = 10000000

B = 01000000

C = 00100000

D = 00010000

E = 00001000

H = 00000100

L = 00000010

Test Sequence

1. ORA B, ORA C, ORA D, ORA E, ORA H, ORA L, ORI 01,
CPI FF, CMA, CPI 0.

5. XRA instruction

(Initial Code Words for Registers)

A = 01111111

B = 10111111

C = 11011111

D = 11101111

E = 11110111

H = 11111011

L = 11111101

Test Sequence

1. XRA B, XRA C, XRA D, XRA E, XRA H, XRA L, XRI 01,
CPI FF, CMA, CPI 00.

Finally, other instructions which are not used in testing the microprocessor are used extensively in other modules tests. These microprocessor tests together with other modules tests have utilized at least 80% of the microprocessor instruction sets. However, if the remaining 20% untested instructions were in fact never used at all, (depending on the applications), then this 80% instructions

coverage should be considered excellent, if not optimal.

4.2 Testing the Onboard Memory

The purpose of this test is two-fold:

1. detect stuck-at-0 and stuck-at-1 faults on data in/data out lines of the RAM chip,
2. detect stuck-at-0 and stuck-at-1 on the address lines,
3. detect stuck-at-0 and stuck-at-1 fault in the row and column (address) decoder of the RAM chip,
4. detect stuck-at-0 and stuck-at-1 fault in the storage elements,
5. to verify that the supporting circuits (interfacing logic), i.e., all logic that ties the memory and the processor together, are functioning properly.

4.2.1 Testing the RAM (address \$3C00 - \$3FFF)

This is accomplished by initializing the address bus to the starting address of the RAM (\$3C00). Each location within the RAM is then sequentially written into and after the memory is fully written into, it is read and the information or pattern being read from each location is compared with the information written into it

earlier. Thus the RAM is verified. In the following section, we will develop an algorithm for testing the RAM. The thoroughness of this test is directly related to the complexity of the patterns stored and read from each location.

4.2.1.1 Generation of test sequence

In the built-in-test structure described in [26] and [27], the authors present a test algorithm which provides a minimal length test for stuck-at-fault in RAM. The test algorithm requires four accesses per addressline, with additional hardware to access the RAM.

The algorithm (named ATS) divides the address into groups of three (modulo-3) and uses the result (0, 1 or 2) to assign each address to one of the three groups GP_0 , GP_1 and GP_2 . The test itself consists of writing and reading the memory in the manner shown in Table 2.

Table 2. Algorithm Test Sequence (ATS)

PART. STEP	GP ₀	GP ₁	GP ₂
1		WrW ₀	WrW ₀
2	WrW ₁		
3		RdW ₀	
4		WrW ₁	
5			RdW ₀
6	RdW ₁	RdW ₁	
7	WrW ₀ RdW ₀		
8			WrW ₁ RdW ₁

W₀ = test data 01010101

Wr = write

W₁ = test data 10101010

Rd = read

This test algorithm is shown to detect all single and multiple stuck-at-faults in memory address register (MAR), memory data register (MDR), decoder and memory array. A summarized proof that the ATS detects these faults will be considered later. For a detailed proof, the reader is referred to [26] and [27].

Derivation of Test Algorithm

Let A_j be the memory address of location j , $0 \leq j < 2^n$,
 n = # of address lines (i.e., width of address lines).

$$GP_0 = \{ A_j | j = 0 \text{ (modulo-3)} \}$$

$$GP_1 = \{ A_j | j = 1 \text{ (modulo-3)} \}$$

$$GP_2 = \{ A_j | j = 2 \text{ (modulo-3)} \}$$

Refer to Table 2

Step 1: Write the W_0 word at all locations

$$A_j \in GP_1 \text{ and } A_k \in GP_2$$

Step 2: Write the W_1 word at all locations

$$A_i \in GP_0$$

Step 3: Read all locations $A_j \in GP_1$

if output = W_0 ; no fault indicated
 $\neq W_0$; RAM fault indicated

Step 4: Write the W_1 word at all locations

$$A_j \in GP_1$$

Step 5: Read all locations $A_k \in GP_2$

if output = W_0 ; no fault indicated
 $\neq W_0$; RAM fault indicated

Step 6: Read all locations $A_i \in GP_0$ and $A_j \in GP_1$

if output = W_1 ; no fault indicated
 $\neq W_1$; RAM fault indicated

Step7: Write and then read the W_0 word at locations $A_i \in GP_0$

if output = W_0 ; no fault indicated

$\neq W_0$; RAM fault indicated

Step 8: Write and then read the W_1 word at all locations

$A_k \in GP_2$

if output = W_1 ; no fault indicated

$\neq W_1$; RAM fault indicated

Verification of Faults

Definition:

Hamming distance - it is the number of binary bits in which two code word or binary memory addresses disagree [26].

Theorem 1:

If A_x and A_y are two distinct binary memory addresses which belong to the same group GP_i , $0 \leq i \leq 2$, then the Hamming distance, denoted $d(A_x, A_y)$, is at least ≥ 2 , [26] and [27].

MAR Faults (Assuming all other sub-units are fault-free)

Assume that the kind of fault caused by the MAR s-a-0 or s-a-1 is the single accessing of the wrong memory array word. Therefore, a faulty bit in the MAR can cause an access to any address that is of Hamming distance 1 from the desired memory location. Therefore the test algorithm required is to write W_0 in one location and W_1 in all locations that are Hamming distance 1 away. This is done many times over in steps 1 through 5 of the ATS algorithm.

Analysis of Fault Using the ATS Algorithm (Refer to Table 2)

- Step 1: Write the W_0 word in all locations belonging to GP_1 and GP_2
- Step 2: Write the W_1 word in all locations belonging to GP_0
- Step 3: Read W_0 at all locations in GP_1 ; this will detect all single MAR faults between all addresses in GP_0 and GP_1
- Step 4: Write the W_1 word at all locations in GP_1
- Step 5: Read the W_0 word at all locations in GP_2 ; this will detect all single MAR faults between all addresses in GP_0 and GP_1 and also between all addresses in GP_1 and GP_2 , etc.

As a matter of fact, this algorithm will also detect multiple MAR faults (i.e., Hamming distance > 1).

Decoder Faults (Assume all other sub-units are fault-free)

Assumption:

1. An address accessing two or more locations will result in the wired-ORing of these locations in the MDR or the data bus,
2. Inputs of decoder are fault-free. Since faults in the input lines of the decoder are indistinguishable from faults in the MAR and any address always accesses some

the ATS algorithm. Thus, we can at this point consider the inputs of the decoder to be fault-free.

3. Decoder circuit is combinational and remains so in the event of multiple stuck-at faults.

Let us illustrate the decoder input/selected memory array word line.

Table 3. Decoder Fault-free Table

LOC. ADDR.	L ₀	L ₁	L ₂	L ₃	L ₄	L ₅	L ₆	L ₇
A ₀	1	0	0	0	0	0	0	0
A ₁	0	1	0	0	0	0	0	0
A ₂	0	0	1	0	0	0	0	0
A ₃	0	0	0	1	0	0	0	0
A ₄	0	0	0	0	1	0	0	0
A ₅	0	0	0	0	0	1	0	0
A ₆	0	0	0	0	0	0	1	0
A ₇	0	0	0	0	0	0	0	1

The following shows the equivalent decoder input/selected memory array.

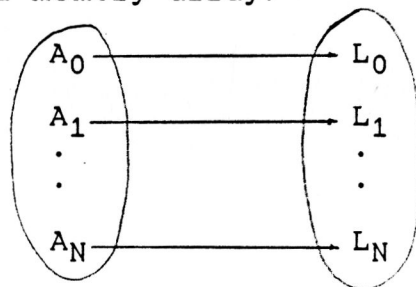


Figure 5. Equivalent Fault-free Diagram

There are 2^{N^2} possible tables (N = number of words in memory), of which $N!$ tables have exactly one 1 in every row and every column. Since these correspond to the cases where each address accesses a unique location and every location is accessed, they can be ignored because the functioning of the memory is not affected by such a fault in the decoder, see Table 4. Table 5 shows a typical fault model for a decoder.

Table 4. Decoder Undetectable Fault

LOC. ADDR.	L ₀	L ₁	L ₂	L ₃	L ₄	L ₅	L ₆	L ₇
A ₀	0	0	1	0	0	0	0	0
A ₁	0	0	0	0	0	0	1	0
A ₂	0	0	0	0	1	0	0	0
A ₃	0	0	0	0	0	1	0	0
A ₄	0	0	0	0	0	0	0	1
A ₅	0	0	0	1	0	0	0	0
A ₆	1	0	0	0	0	0	0	0
A ₇	0	1	0	0	0	0	0	0

Table 5. Decoder Stuck-at-Faults

LOC. ADDR.	L ₀	L ₁	L ₂	L ₃	L ₄	L ₅	L ₆	L ₇
A ₀	0	1	0	0	0	0	0	0
A ₁	0	1	0	0	0	0	0	0
A ₂	0	0	0	0	0	0	0	0
A ₃	0	0	0	1	0	0	0	0
A ₄	0	0	0	0	0	1	0	0
A ₅	0	0	0	0	0	1	0	0
A ₆	0	0	0	0	0	0	0	0
A ₇	0	0	0	0	0	0	0	1

The following is an equivalent diagram of the above decoder stuck-at-fault.

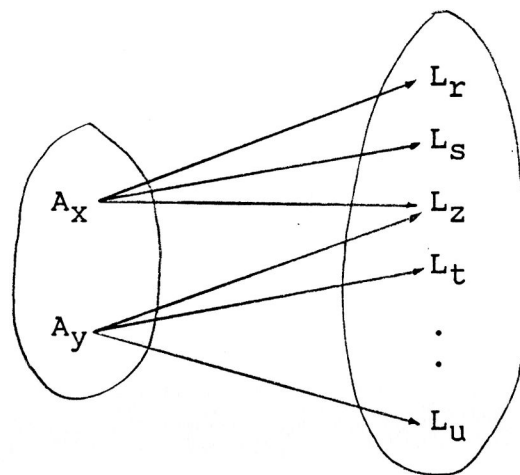


Figure 6. General Fault Model for Decoder

For the above model, there are two kinds of faults :

1. an overwrite condition where the initially stored information is destroyed by a wrong memory address access during input,
2. a logical ORing condition where the stored information is erroneously output due to a multiple memory access,

Analysis of Fault Using the ATS Algorithm (Refer to Table 2)

The following will show how the algorithm in Table 2 detects the decoder stuck-at-fault.

Case 1: $A_x \in GP_0$, then $A_y \in GP_2 \cup GP_1$ by Theorem 1.

If $A_y \in GP_1$, fault will be detected in step 3 due to reading W_1 instead of W_0 (i.e., $A_x \leftrightarrow$

A_y),

If $A_y \in GP_2$, then fault will be detected in step 5 due to reading W_1 instead W_0 ,

Case 2: $A_x \in GP_1$, then $A_y \in GP_0 \cup GP_2$,

If $A_y \in GP_0$, fault will be detected in step 3,

If $A_y \in GP_2$, fault will be detected in step 5,

Case 3: $A_x \in GP_2$, then $A_y \in GP_0 \cup GP_1$. Fault will be detected in step 5.

Memory Array Fault

Faults in the memory imply the various bit positions in some words are at some combination of s-a-1 and s-a-0 faults. Since the algorithm write and read both W_0 and W_1 in all memory locations, the test will also detect faults in the memory array.

Memory Data Register Fault

Faults in the MDR are very much the same as those in the memory array i.e., bit position s-a-0 and s-a-1 faults. Hence the MDR fault is also detected by the ATS algorithm.

4.2.1.2 Final algorithm for RAM

Referring to Table 2 again, [28] makes it clear that capabilities of the ATS algorithm remain unchanged if step 7 is moved to step 1 and step 8 to step 5

(not swapping). From the practical viewpoint, this algorithm seems to be more convenient to implement [28]. Further simplification of the present algorithm is still possible if we examine Theorem 1 again. This Theorem is valid for any partitioning as long as [28]:

$$GP_i = \{ A_j | j = i \text{ (modulo-}k\text{)} \} ; i = 0, 1, \dots, k-1$$

$$j < \log N$$

$$N = \# \text{ of words in memory.}$$

Several values of k satisfy the above equation, but the case when $k = N$ is worth noting.

The validity of the modified ATS algorithm just described does not depend on the number of partitions [28]; hence by increasing the number of partitions to N , we have the following final algorithm for the RAM as shown in Table 6.

Table 6. Final ATS Algorithm for RAM

PART. STEP	A_0	A_1	\dots	A_{N-2}	A_{N-1}
1	WrW_0				
2		WrW_0			
.			.		
.				.	
N-1				WrW_0	
N					WrW_0
N+1	RdW_0				
N+2	WrW_1				
N+3		RdW_0			
N+4		WrW_1			
.			.		
.				.	
3N-3				RdW_0	
3N-2				WrW_1	
3N-1					RdW_0
3N					WrW_1
3N+1	RdW_1				
3N+2		RdW_1			
.			.		
.				.	
4N-1				RdW_1	
4N					RdW_1

Comparing the first ATS algorithm and the final algorithm, we see that the latter algorithm can be implemented in a much simpler way than the former algorithm, which is complicated by the division of 3 scheme.

4.2.2 Testing the ROMs

The verification of the information that a ROM contains is commonly accomplished by sequentially reading each location and generating a 16-bit cumulative sum. After all locations have been read, the 16-bit checksum thus generated is a fairly reliable indicator [21] of the validity of the information contained in the ROM and of the ability of the CPU to access it. The entire system software occupies 1k bytes of memory space and its checksum is \$BB18 (generated by PROMlink).

The checksum is formed by taking the sum of the consecutive memory data. The carry resulting from the summation of this consecutive memory data is taken care of in another register. Thus a 16-bit checksum is formed. The cumulative carry resulting from the LSByte addition forms the MSByte of the checksum. This is called the extended-precision checksum.

The self-test program is placed separately from the system program. The self-test program is placed in the ROM located at A23 (see Figure C-3, Appendix C). When the board is powered up, it will jump to address \$0000

(beginning address of the ROM containing the self-test program). The system program is moved to ROM location A25 (address \$800 - \$FFF). The valid memory addresses are listed in Table 7.

TABLE 7. ROM/PROM Addresses
(Adapted From [1])

	CHIP ADDRESS			
	A23	A24	A25	A26
4K	0 - 3FF	400 - 7FF	800 - BFF	C00 - FFF
8K	0 - 7FF	1000 - 17FF	800 - FFF	1800 - 1FFF

4.3 Testing the I/O ports

There are three I/O ports (three parallel ports and one serial port) on the Intel SBC 80/10A board. The purpose of testing both these ports is two-fold:

1. to verify that the CPU can access these ports,
2. to verify that both the parallel and serial ports are functioning correctly,
3. to verify that there are no stuck-at-0 or stuck-at-1 faults in the data bits of the ports,
4. to verify that the supporting circuit, i.e., all logic that ties the I/O ports and the processor, is functioning properly.

4.3.1 Testing the parallel I/O port

Referring to Figure C-5 of Appendix C, we see that there are two Intel 8255 Programmable Peripheral Interfaces (PPI), one located at A19, the other at A20. For convenience the following device designations will be used: The device at A19 is called the "I/O group 1" device, while the device at A20 is referred to as the "I/O group 2" device. Each device has three eight-bit ports. The "I/O group 1" ports are designated as Ports A, B and C while the "I/O group 2" ports are designated as Ports D, E and F.

The parallel I/O interface logic on the Intel SBC 80/10A provides 48 signal lines for the transfer and control of data to or from external peripheral devices. All the 48 signal lines emanate from the I/O ports on two Intel 8255 PPI (Figure C-2), and are brought out of the Intel SBC 80/10A board via two 50-pin double-sided PC edge connectors (J1 and J2).

The Intel 8255 PPI contains three eight-bit ports (A, B and C); see Figure 7. All can be configured in a wide variety of functional characteristics by the system software and each has its own special features to further enhance its power and flexibility. The Intel 8255 PPI also allows for a wide variety of I/O configurations and its 24 I/O lines can be individually programmed in 2 groups of twelve (see Figure. 7) and used in three major modes of

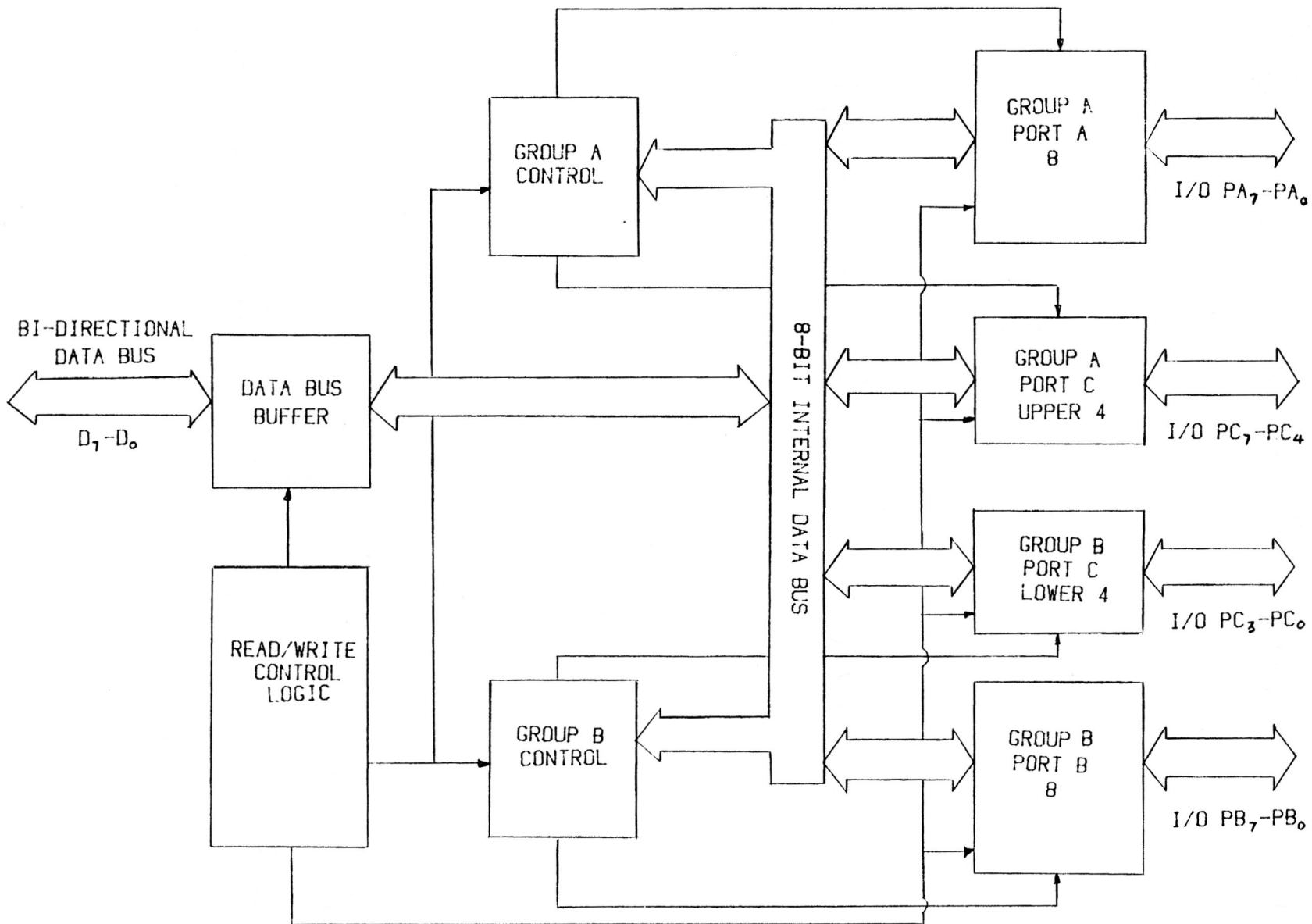


Figure 7. 8255 PPI Functional Block Diagram
(Adapted From [29])

operation. The user is referred to [29] for further detail on the general operational characteristics of the 8255 PPI.

Though both the Intel 8255's maintain the same interface (at different I/O addresses) with the CPU set, the interface between I/O group 1 device and the edge connector (J1) is significantly different from the interface between the I/O group 2 device and its associated edge connector (J2). This gives the user a great deal of flexibility when configuring the system's external parallel I/O devices. Because of these flexible "external" interfaces however, not all ports are capable of operating in each of the 8255's operational modes, though all ports can be programmed as either input or output. The I/O group 1 ports can fully utilize the 8255's multi-mode operation. The I/O group 2 ports, however, are limited to a single mode (mode 0) of operation. The allowable port configurations for both groups are summarized below [1]:

Port A (I/O Group 1)

Mode 0 input

Mode 0 output (latched)

Mode 1 input (strobed)

Mode 1 output (latched)

Mode 2 bi-directional

Port B (I/O Group 1)

Mode 0 input

Mode 0 output (latched)

Mode 1 input (strobed)

Mode 1 output (latched)

Port C (I/O Group 1)

Mode 0 8-bit input

Mode 0 8-bit output

Ports D and E (I/O Group 2)

Mode 0 input

Mode 0 output (latched)

Port F (I/O Group 2)

Mode 0 8-bit input

Mode 0 8-bit output

Mode 1 4-bit input/4-bit output (unlatched/latched)

Mode 1 4-bit output/4-bit input (latched/unlatched)

Since the objective here is to test the I/O lines for stuck-at-0 or stuck-at-1 faults and because of the limitation on the I/O group 2 mode operation [1], the mode 0 configuration seems to fit this testing purpose. All the I/O lines can be configured either as output or input lines. With this configuration, a technique called LOOPBACK [5], i.e., loop I/O port outputs to inputs, can be employed in testing the I/O ports. One group (I/O group 1) of the parallel port can be configured as the output port and the

other group(I/O group 2) as the input port and, with the proper edge connector, a word pattern is output from J1 (which is configured as the output port) and then read by J2 (which is configured as the input port). The pattern output by J1 and pattern input by J2 should agree and any discrepancy would indicate that the port is bad. See Figure 8 for the conceptual idea. Different word patterns can then be used to test the I/O lines for stuck-at-0 or stuck-at-1 faults (see Section 4.3.1.1).

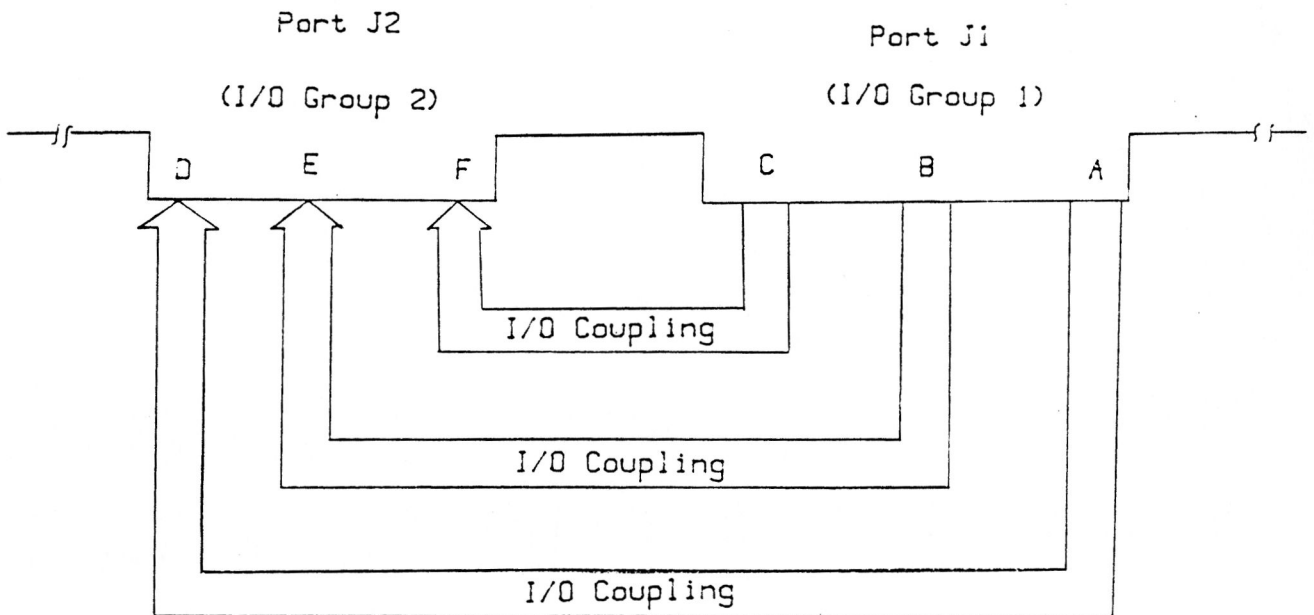


Figure 8. Loopback Technique

It was earlier suggested that the loopback test be done in both directions, i.e., configured J1 as the input port and J2 as the output port (after the first test), so as to verify that both the parallel ports can function as either input or output ports. But due to the different interfacing networks required for different port configurations (see next paragraph), it has proved to be inconvenient to have to swap the interfacing networks every time the test is performed. Therefore the test was instead restricted to one direction only (J1 as the output port and J2 as the input port).

Note that eight lines already have been installed with driver networks (locations A1 and A2) for external interfacing and since all the ports are configured as output, therefore additional driver networks are necessary and are to be installed at locations A3, A4, A5 and A6 for proper interfacing with the outside world. Also termination networks will be installed at locations A7, A8, A9, A10, A11 and A12 (J2 is configured as input port). Typical driver networks will be those listed in Table 8 and the termination network is either the 220 ohm/330 ohm driver or the 1 k-ohm pull up (available in package); see Figure 9.

The drivers, terminators and cables used for our testing purposes will be discussed later in Section 5.0.

Table 8. Drivers (Adapted From [1])

Drivers	Characteristic	Sink Current (mA)
7438	I,OC	48
7437	I	48
7432	NI	16
7426	I,OC	16
7409	NI,OC	16
7408	NI	16
7403	I,OC	16
7400	I	16

I = inverting NI = non-inverting OC = open collector

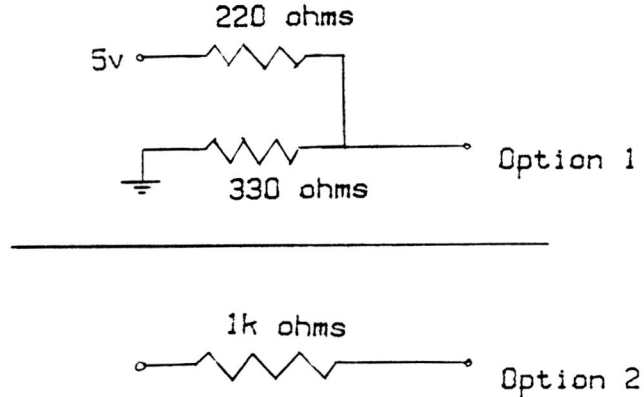


Figure 9. I/O Terminators
(Adapted From [1])

4.3.1.1 Configuring the parallel ports for testing

Tables 9 and 10 depict the pin assignments for connectors J1 and J2 respectively. In order to ensure that ports J1 (I/O group 1) and J2 (I/O group 2) has no stuck-at faults or bridging faults between adjacent bits, J1 (I/O group 1) is first configured as an output port and a word pattern of 101010....10 alternating with 010101....01 is output (one at a time) to J1. These patterns will then be read by J2 (which is configured as the input port) and compared with a known value. This verifies whether port J1 is working correctly or not. The same test is then repeated but this time with the test data 10101010 or 01010101 received at port J2 (I/O group 2). One very important thing to note from Tables 9 and 10 is that the data bits for ports A, B and C are not arranged in such a way that they are all in ascending or proper order i.e., PA0 PA1 ...PB0 PB1 ...PC0 PC1 (see Figure. 10). Hence the word patterns selected for ports A, B and C, when output to J1 should "look" like 101010....10 or 010101....01 or for the second case, when received by ports D, E and F, should also "look" like 1010....10 or 01010....01 at J2.

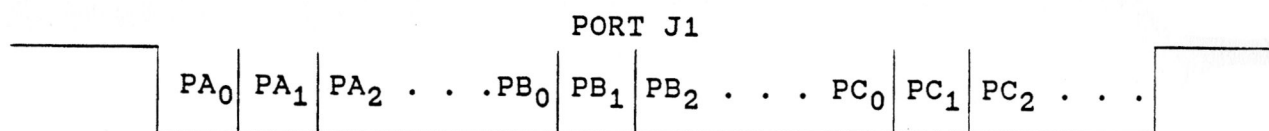


Figure 10. Desired Arrangement of Port J1

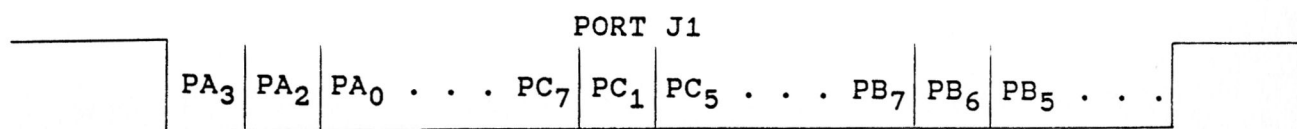


Figure 11. Actual Arrangement of Port J1

Table 9. Pin Assignments for Connector J1
(Adapted From [1])

PIN	SIGNAL	PIN	SIGNAL
1	PORT B - BIT 3	2	GND
3	PORT B - BIT 2	4	GND
5	PORT B - BIT 1	6	GND
7	PORT B - BIT 0	8	GND
9	PORT B - BIT 4	10	GND
11	PORT B - BIT 5	12	GND
13	PORT B - BIT 6	14	GND
15	PORT B - BIT 7	16	GND
17	PORT C - BIT 3	18	GND
19	PORT C - BIT 2	20	GND
21	PORT C - BIT 4	22	GND
23	PORT C - BIT 6	24	GND
25	PORT C - BIT 0	26	GND
27	PORT C - BIT 5	28	GND
29	PORT C - BIT 1	30	GND
31	PORT C - BIT 7	32	GND
33	PORT A - BIT 7	34	GND
35	PORT A - BIT 6	36	GND

37	PORT A - BIT 5	38	GND
39	PORT A - BIT 4	40	GND
41	PORT A - BIT 1	42	GND
43	PORT A - BIT 0	44	GND
45	PORT A - BIT 2	46	GND
47	PORT A - BIT 3	48	GND
49	EXT INTR 1/	50	GND

Table 10. Pin Assignments for Connector J2
(Adapted From [1])

PIN	SIGNAL	PIN	SIGNAL
1	GND	2	GND
3	PORT E - BIT 3	4	GND
5	PORT E - BIT 0	6	GND
7	PORT E - BIT 1	8	GND
9	PORT E - BIT 2	10	GND
11	PORT E - BIT 4	12	GND
13	PORT E - BIT 5	14	GND
15	PORT E - BIT 6	16	GND
17	PORT E - BIT 7	18	GND
19	PORT F - BIT 3	20	GND
21	PORT F - BIT 2	22	GND
23	PORT F - BIT 1	24	GND
25	PORT F - BIT 0	26	GND
27	PORT F - BIT 4	28	GND
29	PORT F - BIT 5	30	GND
31	PORT F - BIT 6	32	GND
33	PORT F - BIT 7	34	GND
35	PORT D - BIT 7	36	GND
37	PORT D - BIT 6	38	GND
39	PORT D - BIT 5	40	GND
41	PORT D - BIT 4	42	GND
43	PORT D - BIT 0	44	GND
45	PORT D - BIT 1	46	GND
47	PORT D - BIT 2	48	GND
49	PORT D - BIT 3	50	GND

Test Patterns for Ports A, B and C (I/O group 1) when:

1. test pattern at J1 is 101010....10

Port A = 9A

Port B = A5

Port C = 27

2. test pattern at J1 is 010101....01

Port A = 65

Port B = 5A

Port C = D8

Test Patterns for Ports A, B and C (I/O group 1) when :

1. test pattern received at J2 is 101010....10

Port A = 5A

Port B = A5

Port C = A5

2. test pattern received at J2 is 010101....01

Port A = A5

Port B = 5A

Port C = 5A

Specific I/O addresses for the six ports where the CPU set can access are listed in Table 11.

Table 11. Parallel I/O Port Addresses
(Adapted From [1])

PORT	8255 DEVICE LOCATION	8-BIT ADDRESSES (HEX)
A	GROUP 1 PORT A	E4
B	GROUP 1 PORT B	E5
C	GROUP 1 PORT C	E6
-	GROUP 1 CONTROL	E7 (WRITE ONLY)
D	GROUP 2 PORT A	E8
E	GROUP 2 PORT B	E9
F	GROUP 2 PORT C	EA
-	GROUP 2 CONTROL	EB (WRITE ONLY)

4.3.1.2 Other cases of testing the parallel ports

In the preceding case, we have an equal number of output ports and I/O lines, so there is no problem in testing all ports or lines for stuck-at faults or bridging faults between adjacent bits.

For the rest of this section, we will discuss two other cases of testing the parallel I/O ports :

Case 1: Input ports or I/O lines more numerous than
output ports or I/O lines,

Case 2: Input ports or I/O lines less numerous than
output ports or I/O lines.

Case 1

When the number of input I/O lines is more than the

number of output I/O lines, the ports (both input and output) can still be easily tested for stuck-at faults or bridging faults. Simply connect all the available output I/O lines to all the input I/O lines as shown in Figure 12.

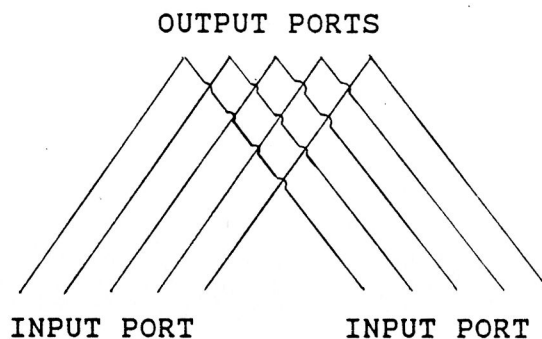


Figure 12. Configuration for Case 1

With the appropriate test data, the ports can be checked for stuck-at faults or bridging faults between adjacent bits.

Case 2

When the number of input I/O lines is less than the number of output I/O lines, then some of the output I/O lines might have to be tied together with some logic gates, so as to keep the number of output I/O lines the same as the number of input I/O lines. Figure 13 shows two possible configurations of case 2.

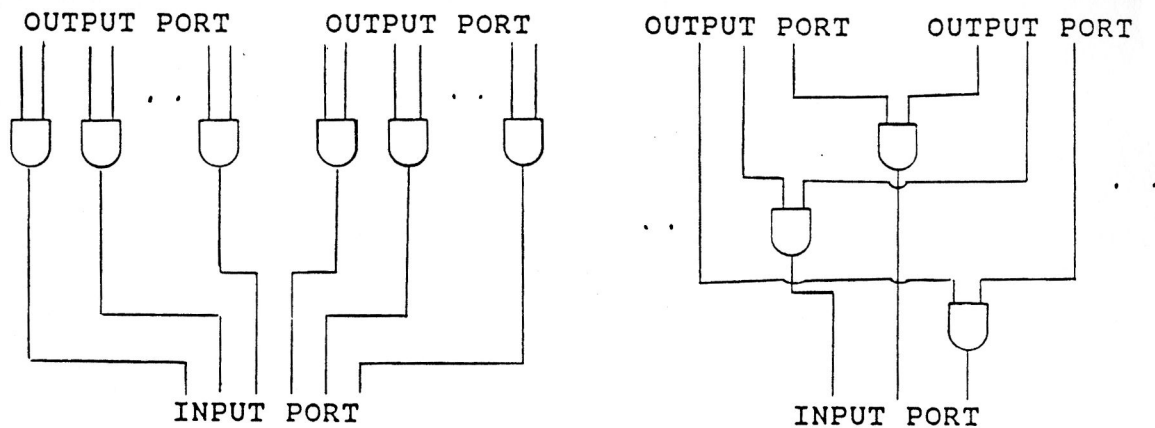


Figure 13. Configuration for Case 2

Again, with the appropriate test data, the input and output ports can be checked for stuck-at faults or bridging faults.

4.3.2 Testing the serial I/O port

The serial I/O interface logic consists primarily of an Intel 8251 USART device located at A22 in Figure C-4 of Appendix C. It is a Universal Synchronous/Asynchronous Receiver/Transmitter (USART) designed specifically for the 8080 microcomputer systems. Like other I/O devices in the 8080 microcomputer system, its functional configuration is programmed by the system software for maximum flexibility. A block diagram of the 8251 is shown in Figure 14.

The Intel 8251 USART device converts

parallel format system data into serial format for transmission and converts incoming serial format data into parallel system data for reception. It also deletes or inserts bits or characters that are functionally unique to the communication technique.

The 8251 USART can also be used for either synchronous or asynchronous data communication. Both these formats require that framing information be added to the data to enable proper detection of the character at the receiving end. The major difference between the two formats is that the asynchronous format requires framing information to be added to each character, while the synchronous format adds framing information to blocks of data or messages. Both these formats can be transmitted in half or full duplex mode.

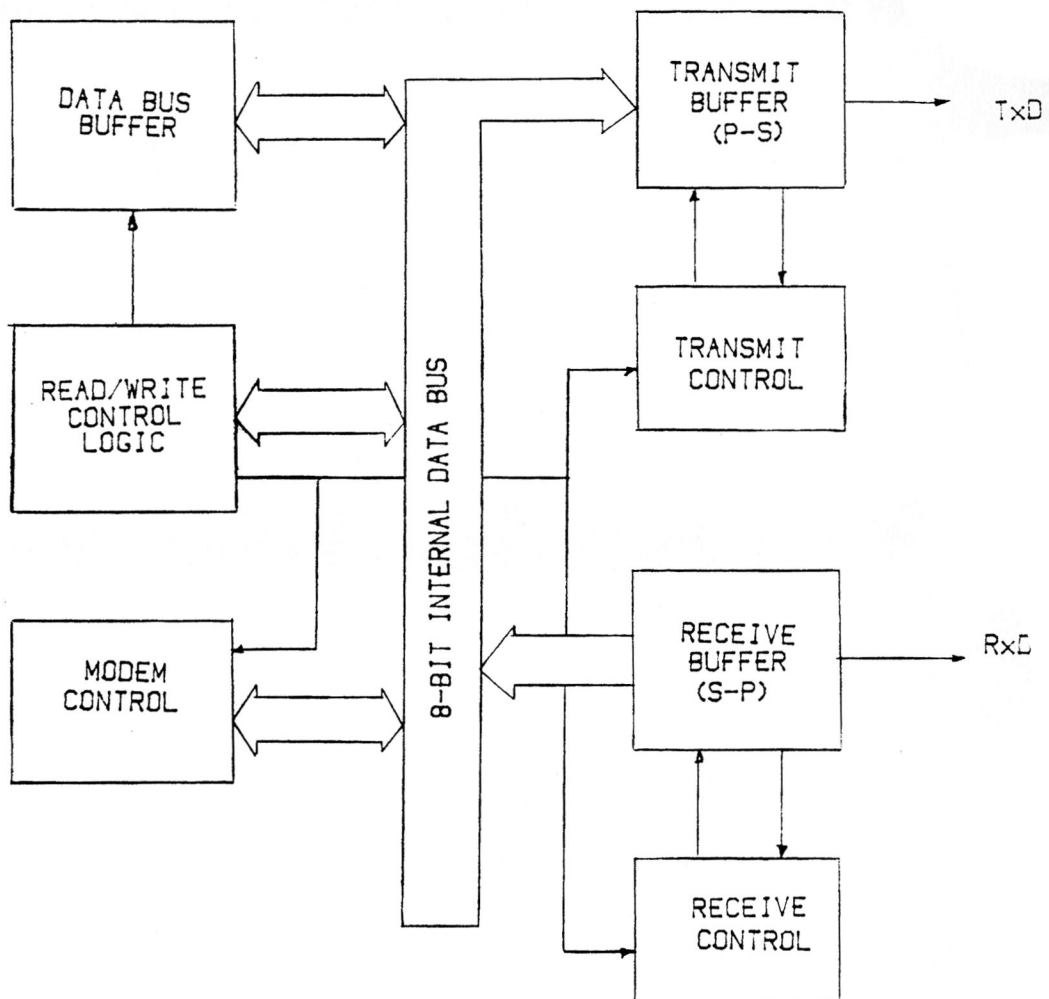


Figure 14. 8251 USART Functional Block Diagram
(Adapted From [29])

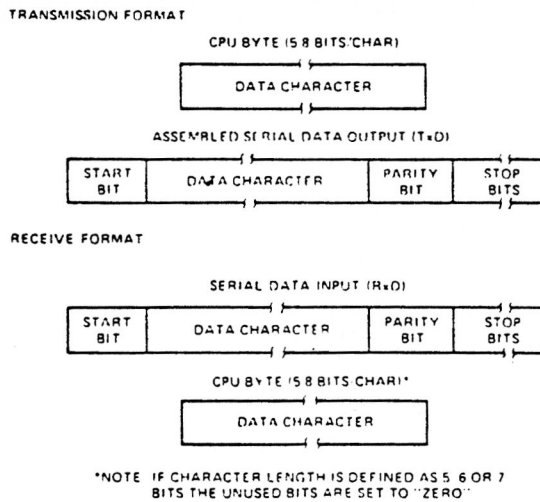


Figure 15. Asynchronous Mode
(Adapted From [1])

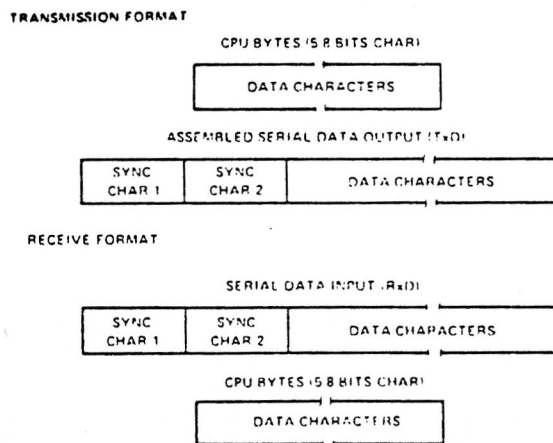


Figure 16. Synchronous Mode
(Adapted From [1])

Prior to starting data transmission or reception, a set of control words generated by the CPU must be sent out to initialize the 8251 USART to support the desired communication format. These control words define the complete functional description of the 8251 USART and must immediately follow a Reset operation (internal or external). These control words will program the: baud rate, character length, number of stop bits, synchronous or asynchronous operation, even/odd parity, etc. In the synchronous mode, options are also provided for selecting either internal or external character synchronization.

The Intel 8251 USART essentially defines the character of the serial I/O interface. The user is referred to [29] for further application notes on the 8251 USART.

4.3.2.1 Configuring the serial port for testing

The serial I/O port interface communicates with an external I/O device via a 26-pin double-sided PC edge connector (J3). Table 12 provides a pin list for connector J3, and Table 13 specifies the I/O addresses which can be accessed by the CPU set.

On the connector J3, the serial I/O port is configured to perform full duplex operation, so the signal line TxD will be tied to RxD so that a closed-loop (loopback) test can be performed. A 1 and a 0 are

placed (a bit at a time) in the most significant bit of the accumulator. Then they are sent out to the serial-output-data pin (TxD) of the 8251. This data is captured by the serial-input-data pin (RxD) of the 8251. Each time the captured data is compared with what was sent earlier. If they agree, the serial port is good, otherwise it is bad.

There are two general schemes for the transmission or reception of data between the serial I/O port and the external world: the asynchronous and the synchronous modes. Both these methods will be tested on the Intel SBC 80/10A board. We will first perform the testing procedure in the asynchronous mode and then follow by the synchronous mode.

Table 12. Pin Assignments for Connector J3
(Adapted From [1])

PIN	SIGNAL NAME	PIN	SIGNAL NAME
1	CHASSIS GND	2	TTY RD CONTROL
3	TRANSMITTED DATA	4	
5	RECEIVE DATA	6	
7	REQ TO SEND	8	
9	CLEAR TO SEND	10	
11	DATA SET READY	12	Tx CLK/DATA TERM READY
13	GND	14	
15	DATA CARRIER RET	16	
17		18	TTY RD CONT RET
19		20	RECEIVE CLK/TTY Rx DATA RET TTY Tx DATA RET GND
21		22	
23		24	
25	TTY Rx DATA	26	
	TTY Tx DATA		

Table 13. Serial I/O Port Addresses
(Adapted From [1])

I/O ADDR. (HEX)	COMMAND	FUNCTION
ED OR EF	OUTPUT	CONTROL WORD
EC OR EE	OUTPUT	DATA
ED OR EF	INPUT	STATUS
EC OR EE	INPUT	DATA

Asynchronous Mode

Control Word

1 1 0 0 1 1 1 0 Mode Instruction

0 0 1 0 0 1 1 1 Command Instruction

Synchronous Mode

Control Word

1 0 0 0 1 1 0 0 Mode Instruction

1 0 1 0 0 1 1 1 Command Instruction

0 0 1 0 1 1 0 Sync Character

In both the asynchronous and synchronous modes, test data 1010101 (01010101) will be sent through TxD and received by RxD. The value received should be checked with the value sent; any discrepancy between

the two values indicates that the serial port is not functioning properly.

The test set-up is shown later in Section 5.0.






















4.4 Testing of the External System Bus (Connector P1)


Table 14 shows each of the external system bus signals and this multibus structure provides a common element for communication between a wide variety of system modules which includes :single board computer, memory, digital and analog I/O expansion boards, and peripheral controllers [29].

These multibus signal lines allow for master-slave relationships between the various system modules described above. A bus master module can drive the command and address bus. An example of a bus master would be a single board computer. A bus slave cannot control the bus. An example of a bus slave would be a memory expansion board.

The SBC 80/10A does not provide the Bus Priority Request signal and therefore it can only be used with one other multibus master [1]. One of our goals here is try to minimize the amount of hardware use and therefore a better choice would be to use an external RAM to test the command signals (only the address, data, write and read signal lines) on the external system bus.

Table 14. Pin Assignment for Connector P1
(Adapted From [1])

	(COMPONENT SIDE)			(CIRCUIT SIDE)		
	PIN	MNEMONIC	DESCRIPTION	PIN	MNEMONIC	DESCRIPTION
POWER SUPPLIES	1	GND	Signal GND	2	GND	Signal GND
	3	VCC	+ 5VDC	4	VCC	+ 5VDC
	5	VCC	+ 5VDC	6	VCC	+ 5VDC
	7	VDD	+12VDC	8	VDD	+12VDC
	9	VBB	- 5VDC	10	VBB	- 5VDC
	11	GND	Signal GND	12	GND	Signal GND
BUS CONTROLS	13	BCLK/	Bus Clock	14	INIT/	Initialize
	15	BPRN	Bus Pri. In	16		
	17	BUSY/	Bus Busy	18		
	19	MRDC/	Mem Read Cmd	20	MWTC/	Mem Write Cmd
	21	IORC/	I/O Read Cmd	22	IOWC/	I/O Write Cmd
	23	XACK/	XFER Acknow	24		
SPARES	25	AACK/	Special	26		
	27			28		
	29			30		
	31	CCLK/	Constant Clock	32		
	33			34		
INTERRUPTS	35			36		
	37			38		
	39			40		
	41			42	INTR1/	Interrupt request
ADDRESS	43	ADRE/	Address Bus	44	ADRF/	Address Bus
	45	ADRC/		46	ADRD/	
	47	ADRA/		48	ADRB/	
	49	ADR8/		50	ADR9/	
	51	ADR6/		52	ADR7/	
	53	ADR4/		54	ADR5/	
	55	ADR2/		56	ADR3/	
	57	ADRO/		58	ADRI/	
DATA	59		Data Bus	60		Data Bus
	61			62		
	63			64		
	65			66		
	67	DAT6/		68	DAT7/	
	69	DAT4/		70	DAT5/	
	71	DAT2/		72	DAT3/	
	73	DATO/		74	DAT1/	
POWER SUPPLIES	75	GND	Signal GND	76	GND	Signal GND
	77	VBB 	-10VDC	78	VBB 	-10VDC
	79	VAA	-12VDC	80	VAA	-12VDC
	81	VCC	+ 5VDC	82	VCC	+ 5VDC
	83	VCC	+ 5VDC	84	VCC	+ 5VDC
	85	GND	Signal GND	86	GND	Signal GND

 Used by Intellec® MDS Bus.

A 2K RAM is used for testing the multibus signal lines. A memory map of the SBC 80/10A board is shown in Figure 17.

UNUSED	\$FFFF
	\$4000
RAM	\$3FFF
	\$3C00
UNUSED	\$3BFF
	\$2000
	\$1FFF
ROM	\$0000

Figure 17. Memory Map of the SBC 80/10A Board

The addresses of the external RAM are set up between \$6800 and \$6FFF. The circuit diagram for the set-up is shown in section 5.0. The test is then carried out the same way as the onboard RAM test.

4.5 Auxiliary Connector P2

Table 5-4 in [1] shows the various auxiliary test points on the SBC 80/10A board. Most of these signals actually have been indirectly tested while performing the other module tests. Hence, this external system bus will not be tested again.

5.0 PRINCIPLE OF OPERATION

The following section describes the test set-up and the sequence of events which occurs during the testing process.

5.1 Test Set Up

The test is set up in the user testing environment and once invoked, becomes automatic, requiring no operator intervention, and upon confronting an error the self-test program will immediately halt.

- The "GO/NO_GO" feature is indicated by an LED pair connected to the outputs of two NAND gates (7400); see Figure 18. When the test begins, LED1 will be ON and LED2 will be OFF. Upon successful execution of the program, the LED pair will toggle and, if for some reason the LED pair remains in its initial state for quite some time, the user should immediately recognize that the self-test program has halted. The location where the program execution stopped can be checked by testing the logic states of the address lines.
- Two 50-pin card edge-connectors (0.1" center) are used for the two parallel ports (I/O group 1 and I/O group 2) at J1 and J2. The I/O lines from port J1 are hard-wired to their corresponding lines at J2 (i.e PA1 to PD1, PA2 to PD2, etc.); see Figure 18.
- A 26-pin card edge-connector (0.1" center) is used for the serial port (J3). TxD and RxD are again hard-wired

together; see Figure 18.

- An 86-pin card edge-connector (0.156" center) with a 40-pin IDC connector (wire-wrap) is used for the external system bus for accessing the necessary signal lines; see Figure 18.
- Driver networks (7408) have already been inserted at locations A1, A2, A3, A4, A5 and A6. Termination networks, SBC-902 (1K-ohm pull-up resistor) are still needed for locations A7, A8, A9, A10, A11 and A21.
- Other hardware needed are : one 7410 3-input NAND gate
two 470 ohms resistors
HM6116P-2 2K x 8 bits RAM

Figure 18 shows the circuit diagram of the whole set-up ready to be tested.

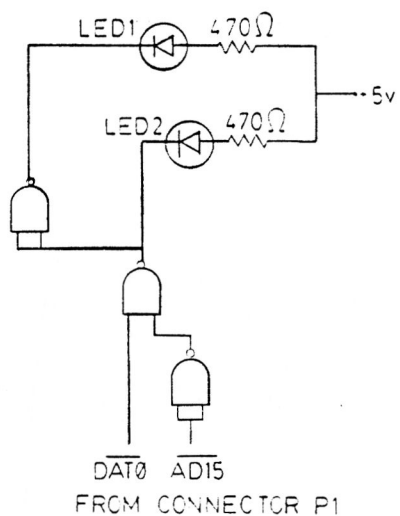
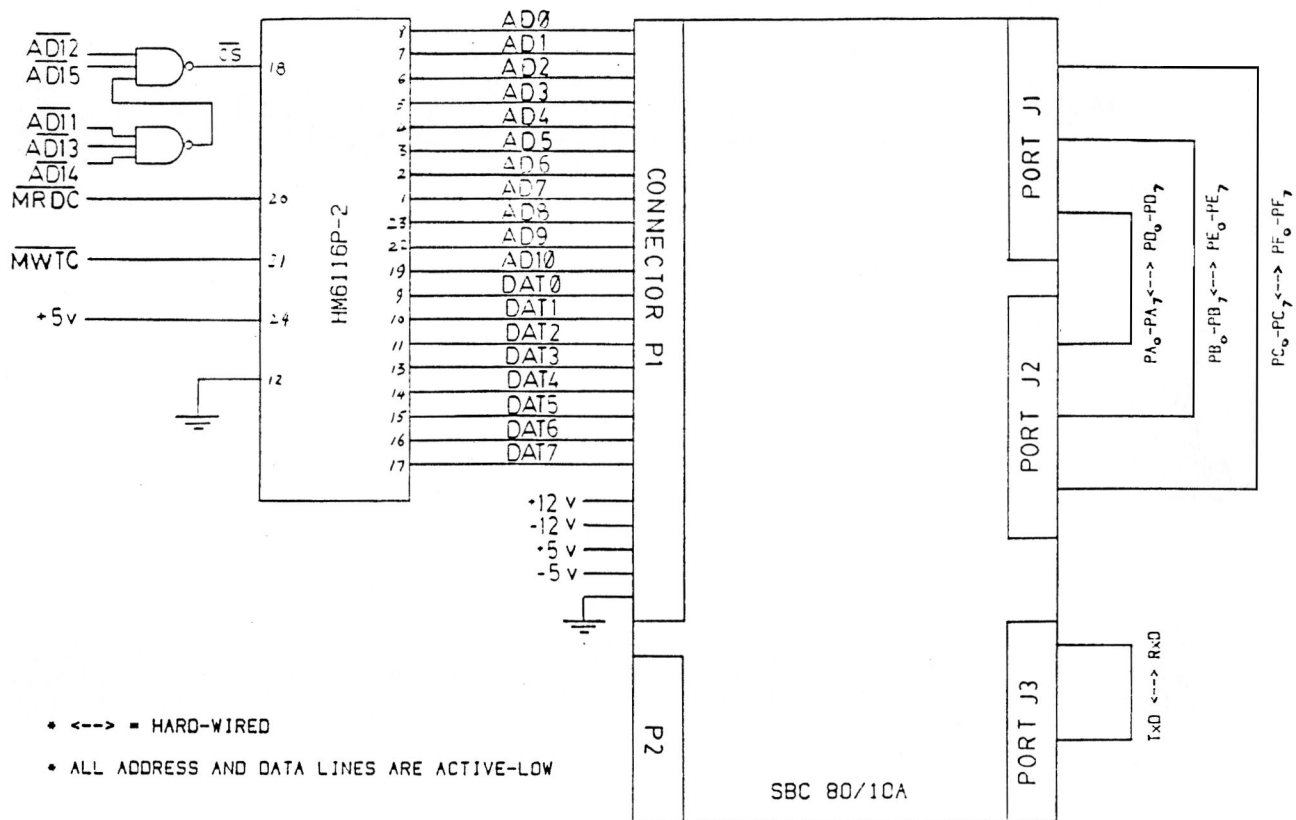


Figure 18. Board Set Up For Testing

5.2 Test Procedure

The following is the sequence of events that should occur during the testing process.

1. The power is turned ON,
2. This action activates the clock and resets the circuit, which in turn generates the Reset signal. The microprocessor automatically executes the instruction in memory location \$0000 which is the beginning address of the self-test program.
3. LED1 is turned ON and LED2 is OFF, indicating that the self-test program is in progress.
4. The first module of the program executes the ROM (containing the self-test program) test.
5. If this module passes the test, program execution is passed to the microprocessor test.
6. If the microprocessor passes the test, program execution is passed to the ROM (containing the system software) test.
7. If the ROM passes the test, program execution is passed to the RAM test.
8. If the RAM passes the test, program execution is passed to the serial I/O ports test.
9. If the serial I/O ports passes the test, program execution is passed on to the parallel I/O port test.
10. If the parallel I/O port passes the test, program execution is passed on to the external system bus test.

11. After the external system bus test module has been completed, then the program will set address line A15 and data line D0 to 1. These signals will be used to toggle the LED pair, indicating that the self-test program has been executed successfully.

6.0 CONCLUSIONS AND POSSIBLE FURTHER EXPANSION

6.1 Conclusions

The basic philosophy behind incorporating a built-in self-testing concept into the Intel SBC 80/10A board is to enable the system to perform self-test and to verify that the system is operational. It is intended to be used either in a production testing environment, where thousands of incoming boards have to be screened before being integrated into more complex systems, or in a user testing environment, where the operator might want to check his malfunctioning board. The "go/no-go" capability/feature of the self-test program is best used for this purpose. It can quickly distinguish the good boards from the bad ones and hence reduce the time and cost involved in isolating the same faults in later more complex systems. The self-test program is driven by software written specially for the processor used on the board. The classes of faults are mostly restricted to pin-level stuck-at-0 and stuck-at-1 type and to the instruction sets of the microprocessor. This self-test technique verifies faults but it does not provide a complete and thorough system diagnostic capability; however, it could be further enhanced to include fault-detection and isolation down to subsystem or component level (see Section 6.2).

The design and implementation of the self-testing

program requires not only an intimate knowledge of the processor software but also an in depth familiarity with the overall system design. For the test engineer who has not been responsible for the system design, and who attempts to generate adequate functional test program for the system, a large amount of time can be spent on familiarizing himself with the operating environment of the microprocessor based system.

Samples of program listings can be found in Appendix B to show their complexity and the amount of ROM space needed. These programs have not been tested; hence how many faults this self-test program will actually detect is yet to be determined.

This project suggested to some extent the feasibility of incorporating the built-in self-testing concept into the Intel SBC 80/10A board and it can possibly be modified and extended to perform the same tasks for more complex systems, including the 16 and 32 bit microcomputers.

Finally, as the complexity of microprocessor-based systems increases, the tasks of testing a system and isolating faults becomes increasingly difficult. Accompanying the increase in complexity is an increase in testing cost, due to the cost of automatic test equipment (ATE). As an attempt to reduce this testing cost and at the same time retain user confidence in the systems, built-in

self-testing techniques should be attracting lots of attention in the 1980s and in the foreseeable future.

6.2 Possible Further Expansion

If, in addition to performing the self-test, we can use a dumb terminal to monitor the testing process instead of the LEDs, the concept can be expanded to include diagnosis for fault-detection and isolation down to subsystem or component levels. The resolution of the fault-location diagnosis is a function of the amount of hardware and software on the system. For the Intel SBC 80/10A board, we can decompose the board into the following subsystems or components:

1. CPU set - 8080A microprocessor
 - 8224 clock generator
 - 8238 system controller
 - and associated circuitry (see Figure C-1, Appendix C)
2. Random Access Memory - Eight 1 bit static RAM (8102)
 - 8226 bi-directional bus driver
 - 3205 address decoder
 - and associated circuitry (see Figure C-2, Appendix C)
3. Read-Only-Memory - ROM/PROM used in locations A23, A24, A25 and A26

- 3205 address decoder
 - 8216 bi-directional bus driver
 - and associated circuitry (see Figure C-3, Appendix C)
4. Parallel I/O Port - two 8255 PPI
- Eight 8226 bi-directional bus drivers
 - 3205 address decoder
 - and associated circuitry (see Figure C-5, Appendix C)
5. Serial I/O Port - 8251 USART
- LM1489 inverters
 - and associated circuitry (see Figure C-4, Appendix C)

With the above subsystems guides, diagnosis of board failure becomes very much a simple "cook-book" procedure. Since the dominant failure mode in the system is a stuck pin, to find this type of fault, it is necessary to start with a board's edge-failure and work back to locate the device with good input and bad outputs. A quicker method would be to replace the component on the path of the failure activity and re-run the self-testing program. This diagnostic algorithm of fault detection and isolation might have to wander all over the board to follow the path leading to the failure.

To alleviate the burden of wandering around the

board, the subsystem or component-level information can be stored in the computer (database) in such a way that it can be retrieved each time a fault is encountered and it can display the set of possible faulty components (depending on which phase the testing process is on).

An expert system (knowledge-based) would be a good application for the above purpose. A file can be created that would contain all the information about all the possible failures that might occur and another file can contain all the possible remedies corresponding to each failure. For example, if a failure occurs during the RAM testing stage, the computer will display all the possible components that may be related to this fault, and the process is repeated until the fault is narrowed down to a bad node.

Finally, the self-testing program can be made general-purpose for use in many systems based on a particular microprocessor. For example, the memory test for the 8080A processor can, except for the starting and the ending address parameters, be the same for every system, only the I/O devices, which tend to be more system-specific, require major modifications of the test program. However, if the I/O driver routine in the self-testing program is written as a module, then it can be called from the main program after the appropriate modifications have

been done. This way the main program won't have to go through major changes each time the program is used in another system, and also if a particular device is absent from the system, the software module for that particular device can be omitted.

Appendix A

Flowcharts and Program Description

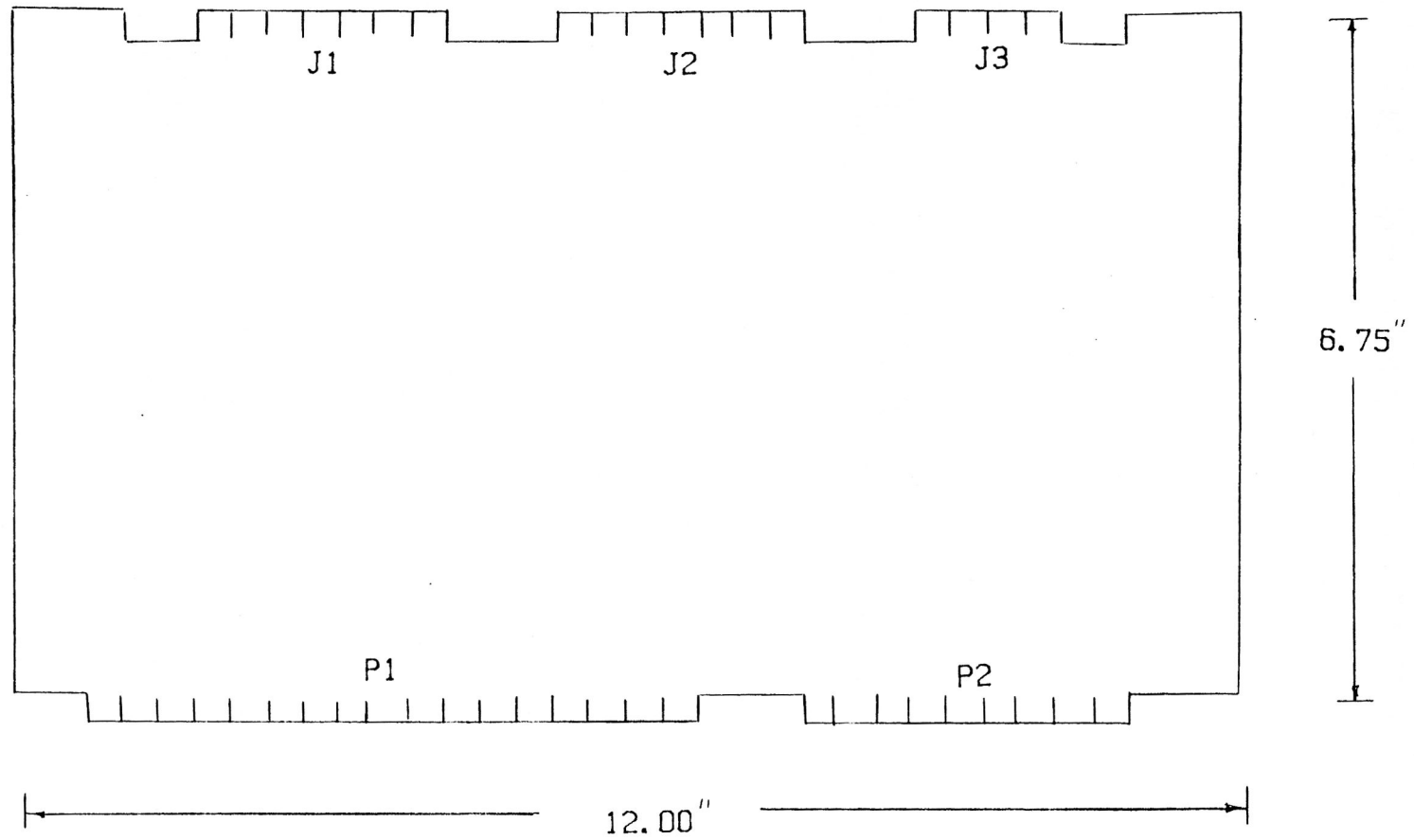


Figure A-1. SBC 80/10A Dimension Drawing

1. MAIN

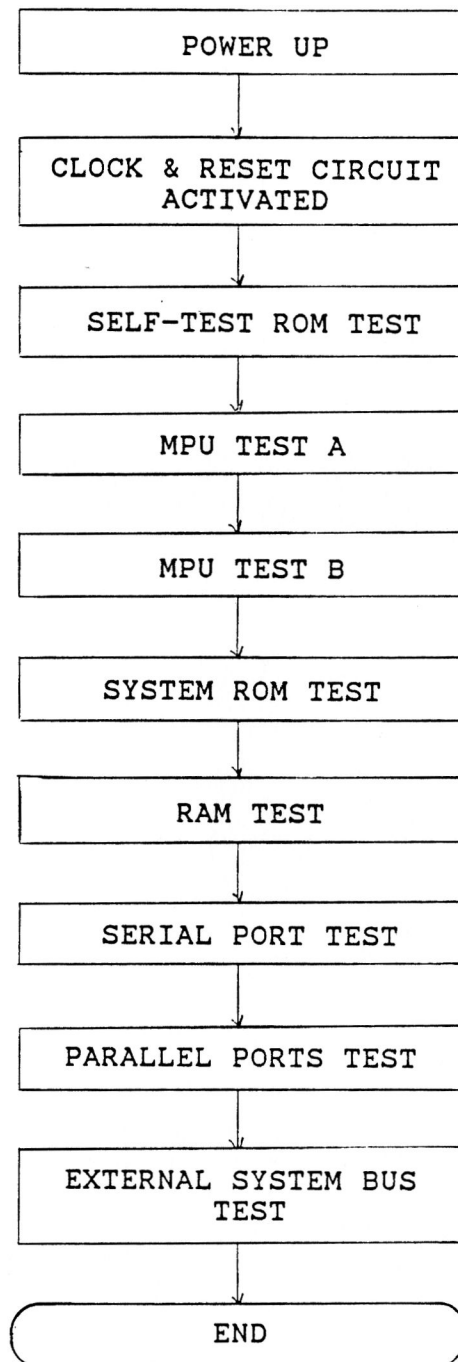


Figure A-2. MAIN Program

MAIN

This is the driver routine which calls all the appropriate routines (SELF-TEST ROM TEST, MPU TEST, SYSTEM ROM TEST, RAM TEST, SERIAL PORT TEST, PARALLEL PORTS TEST AND EXTERNAL SYSTEM BUS TEST) to perform the required tasks.

Upon encountering an error while executing one of the subroutines, the microprocessor operations will be halted until the operator has replaced the faulty component. After the replacement, the circuit is Reset and the self-testing program is re-run.

2. SELF

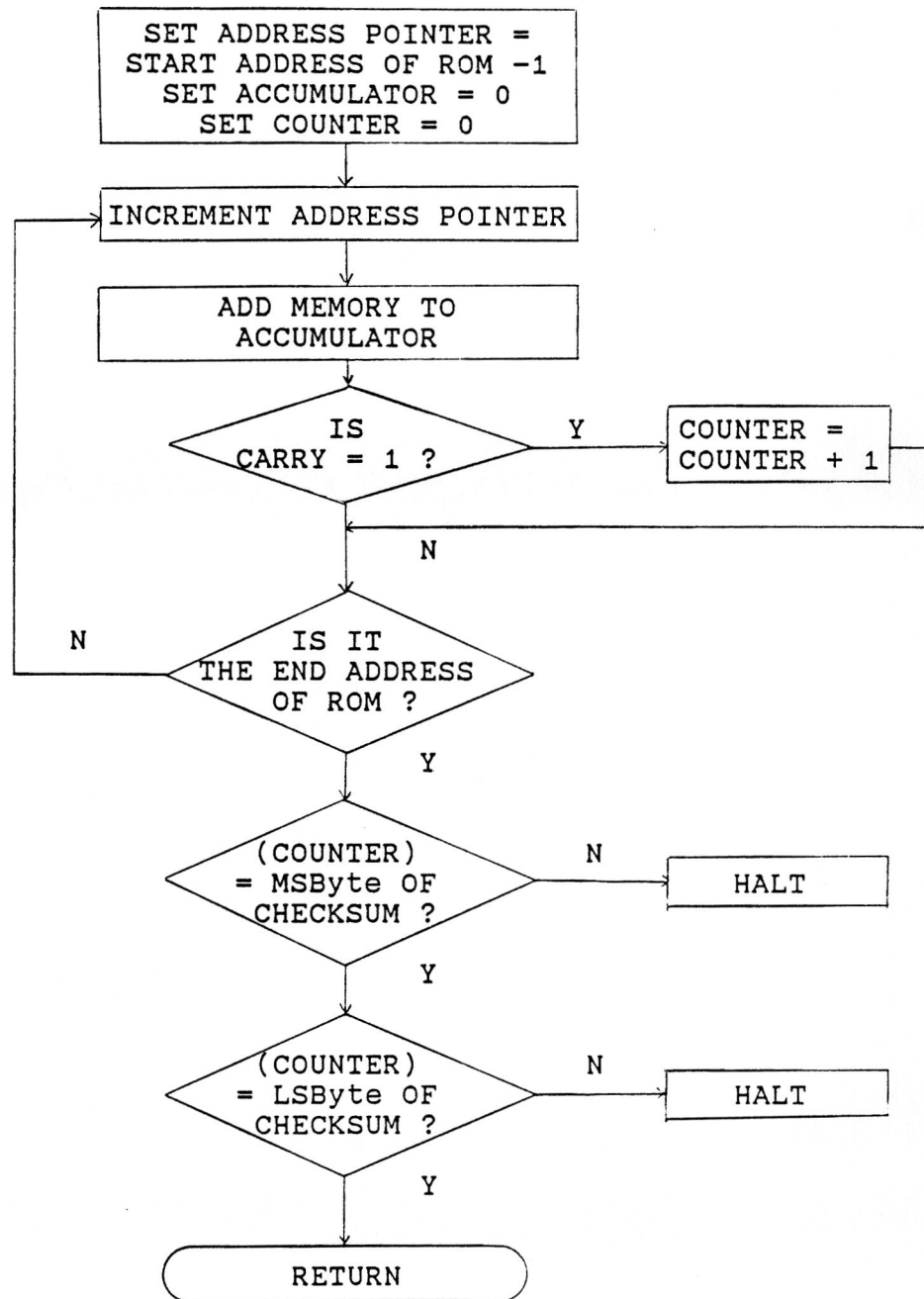


Figure A-3. Subroutine SELF

SELF

This routine constantly reads and adds the contents of the self-testing program. The carry generated from the addition is taken care of in another register and thus forms a 16-bit value checksum. This checksum should check with the predetermined checksum. Any discrepancies between the two values will force the program execution to halt.

3. MPU TEST A

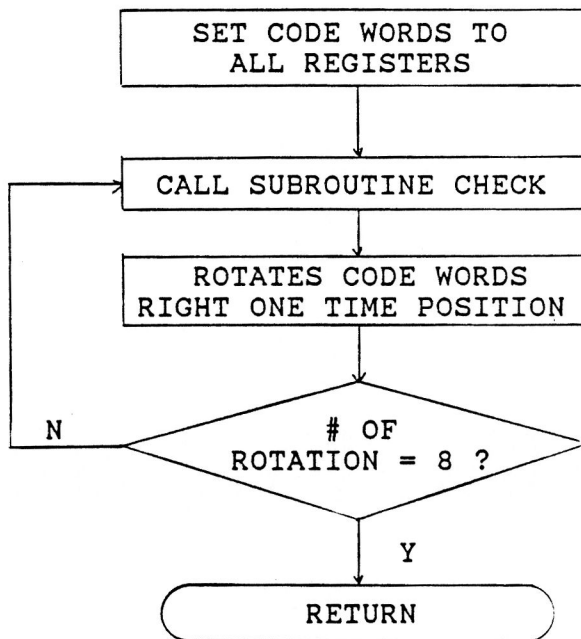


Figure A-4. Subroutine MPU TEST A

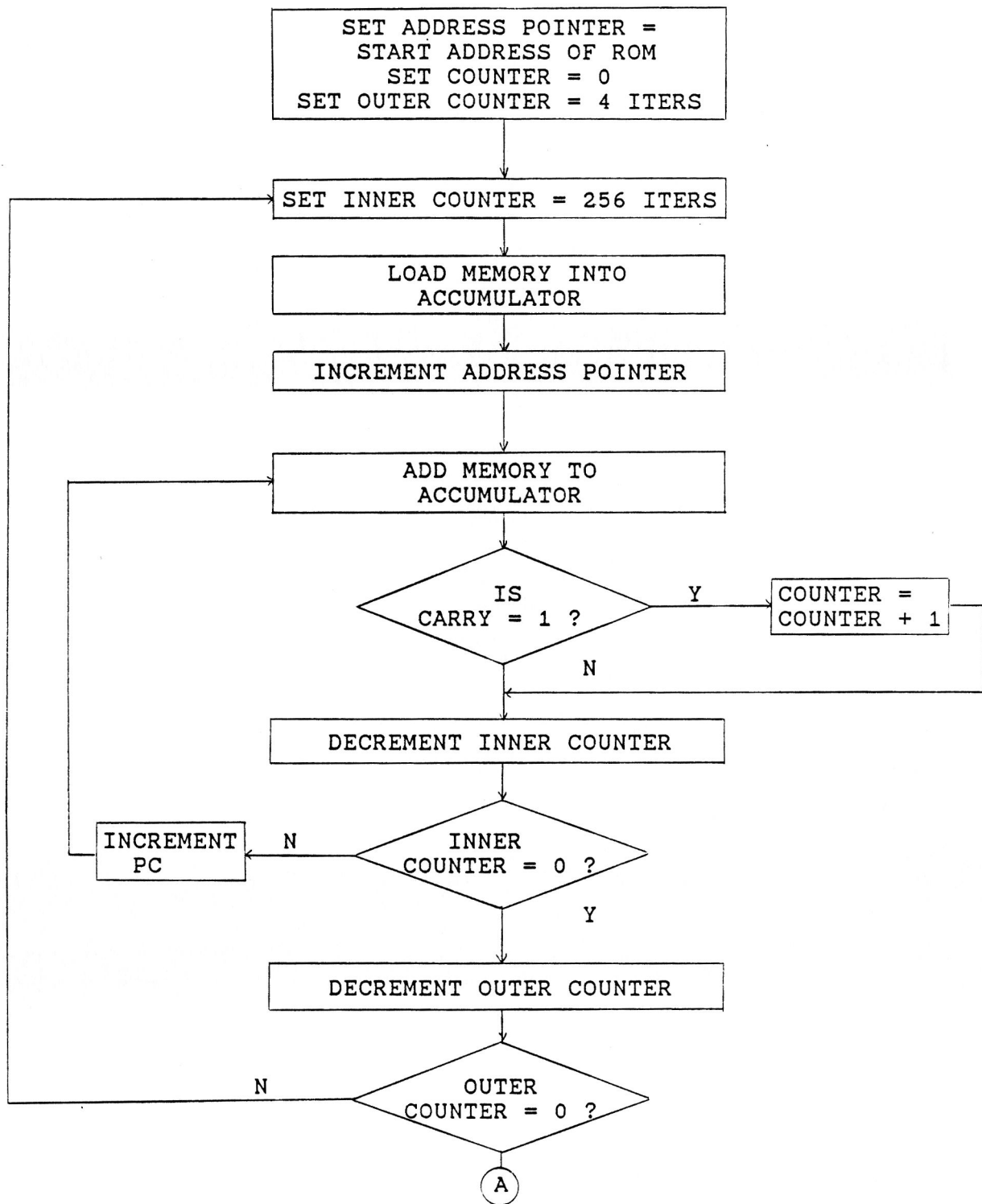
MPU TEST A

See subroutine CHECK.

MPU TEST B

The MPU Test B subroutine is functionally not doing anything except exercising as many of the 8080A instructions as possible.

4. ROM



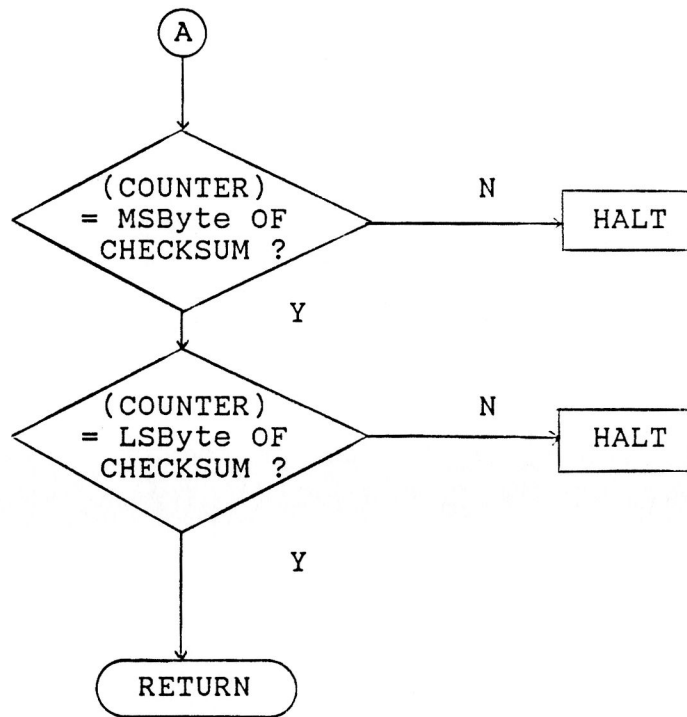
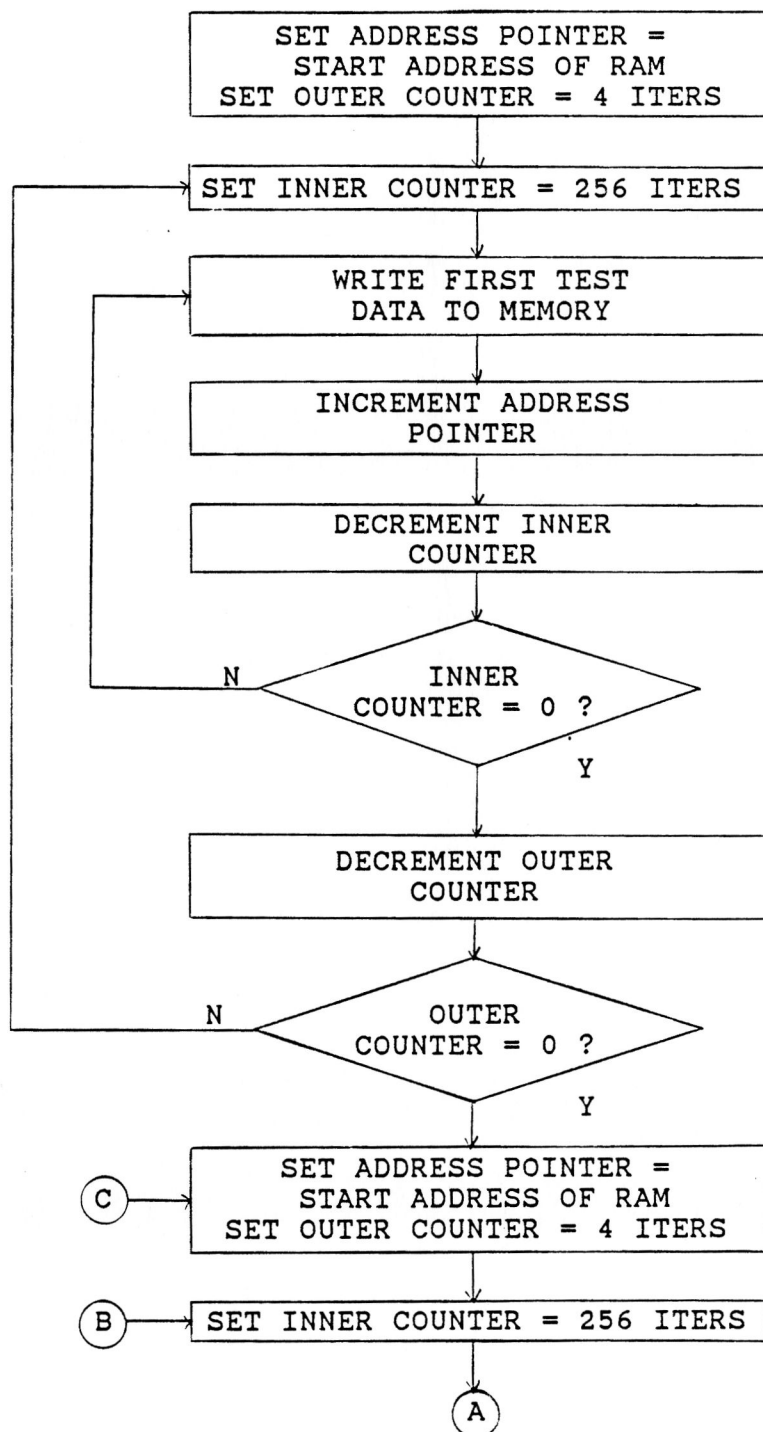


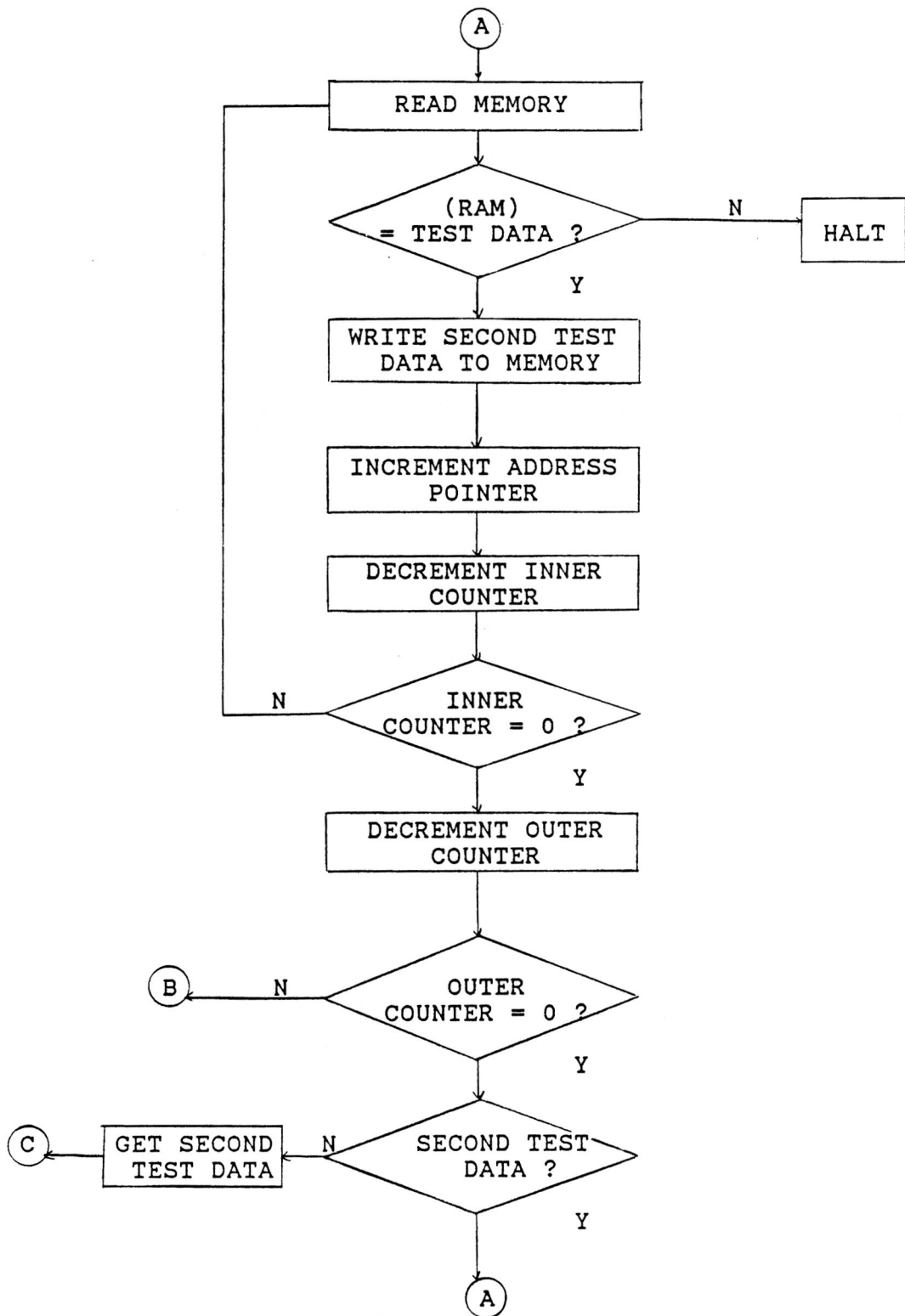
Figure A-5. Subroutine ROM

ROM

This routine constantly reads and adds the contents of the ROM. The carry generated from the addition is taken care of in another register and thus forms a 16-bit value checksum. This checksum should check with the predetermined checksum.

5. RAM





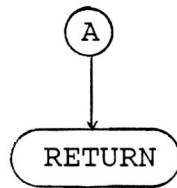


Figure A-6. Subroutine RAM

RAM

This routine constantly writes a test pattern, 01010101, in all the RAM locations. After all the RAM locations have been written into, the routine reads the RAM again and compares with the data it wrote earlier. The two data should be the same if the RAM and its associate circuitry are functioning properly.

The test is then repeated with the test data 10101010.

6. SERIAL

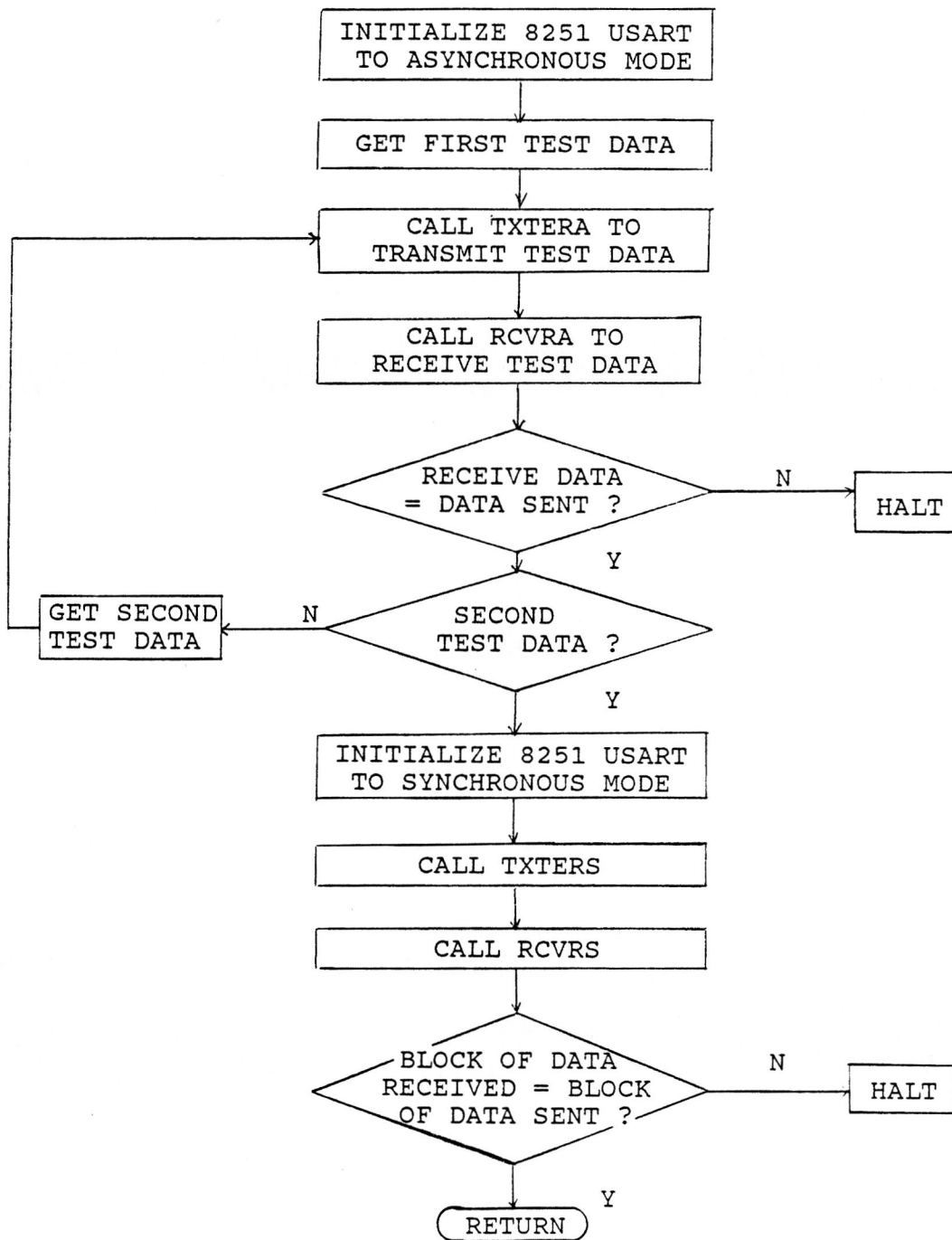


Figure A-7. Subroutine SERIAL

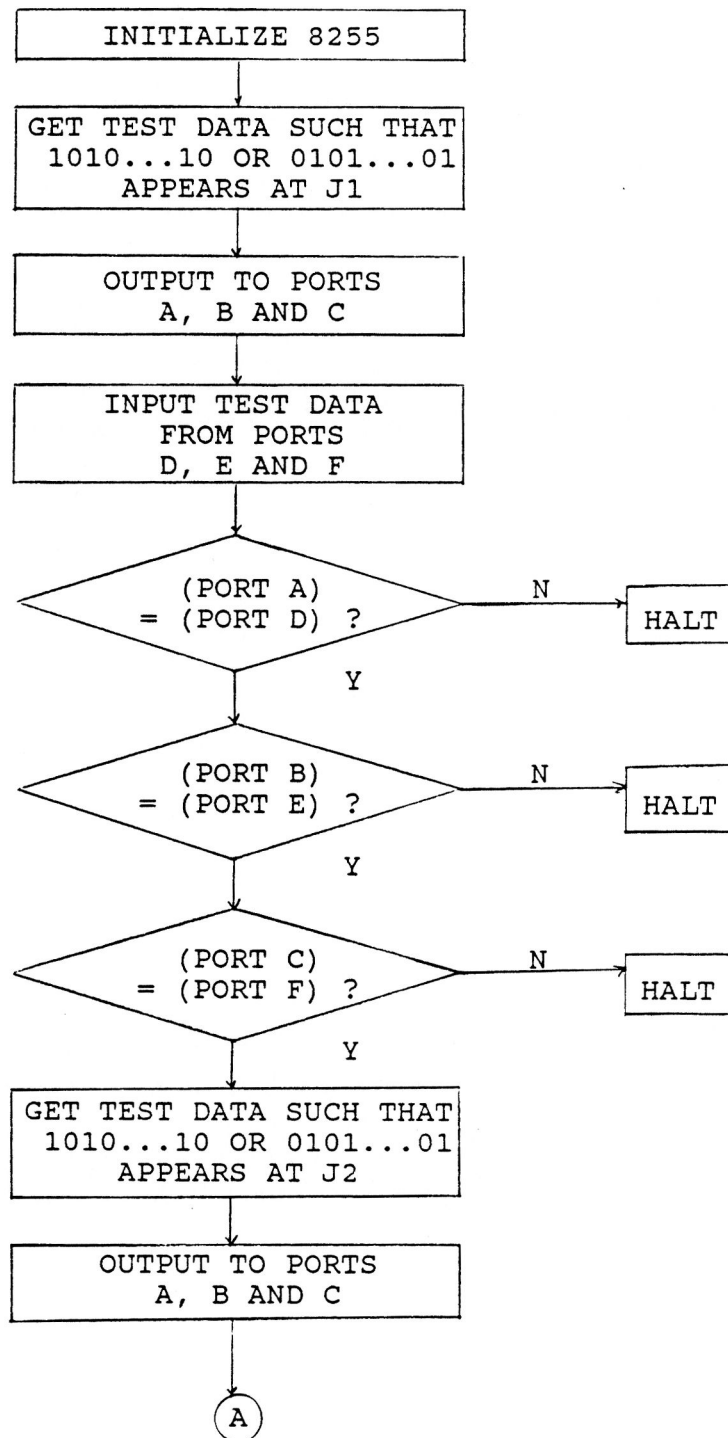
SERIAL

This routine first configures the serial port in the Asynchronous mode, and sends the test data to the TxD pin. This data is then captured by the input pin RxD. If the data sent and data received are different, then program execution will be halted.

The same test is performed with the port configured in Synchronous mode.

Other routines called by this program are TXTERA, RCVRA, TXTERS and RCVRS.

7. PARALL



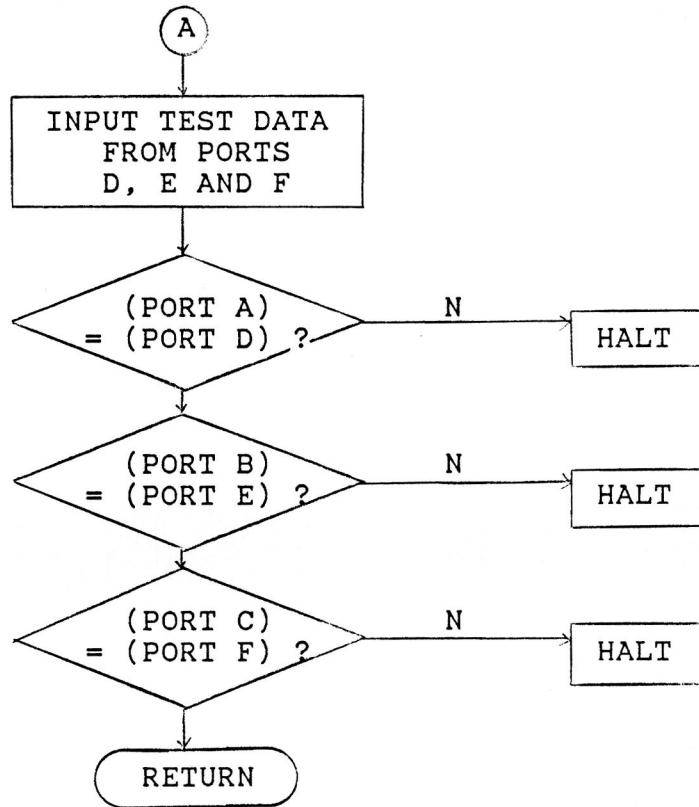


Figure A-8. Subroutine PARALL

PARALL

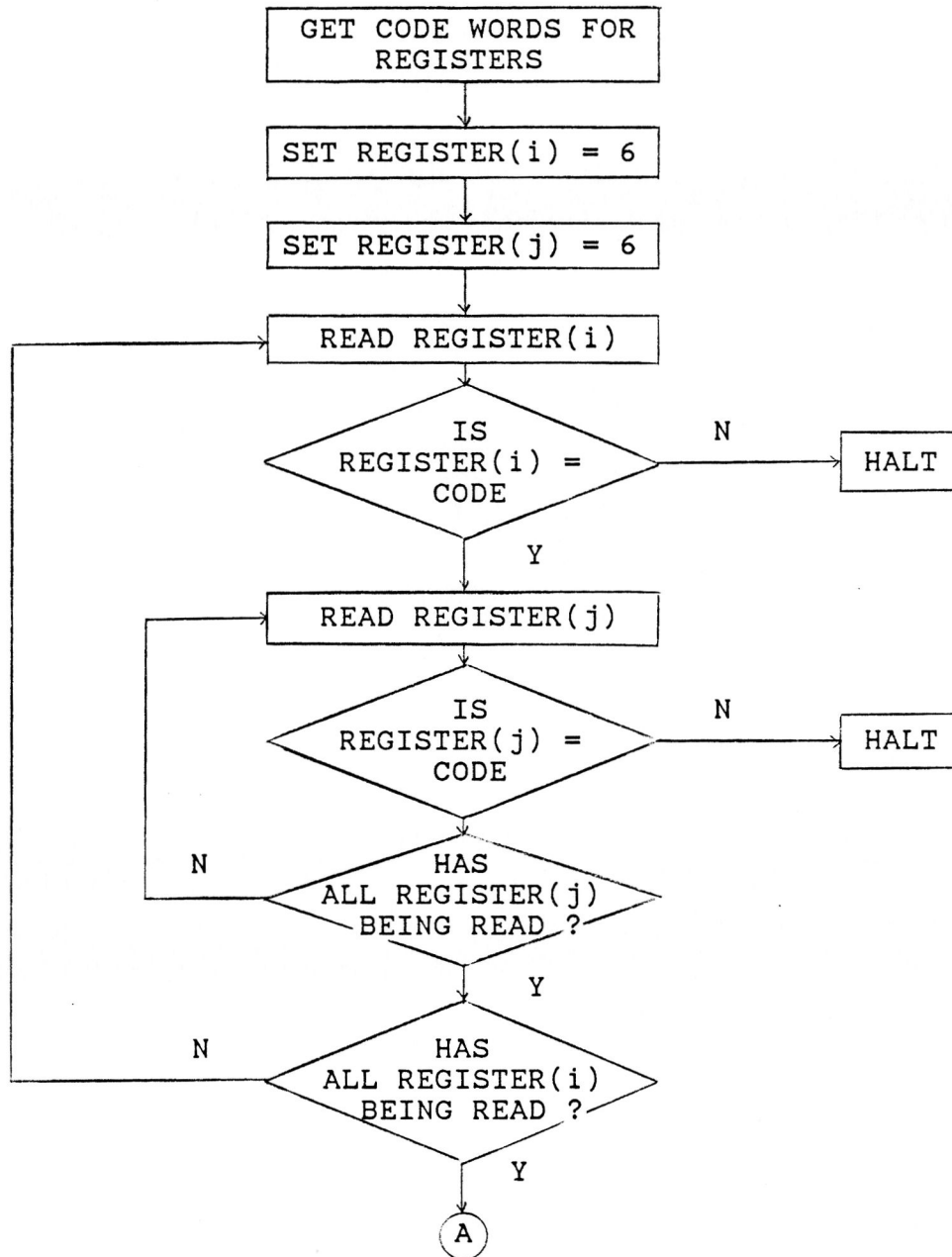
This program configures the I/O group 1 ports as outputs and the I/O group 2 ports as inputs. It then outputs test data (10101010 and 01010101, one at a time) to the I/O group 1 ports. The data sent is captured by the I/O group 2 ports. They are then compared to see if they are the same. Any discrepancies between the data sent and the data received would result in stopping the program execution.

The test is repeated but this time with the test data 1010....10 and 0101...01, one at a time) received at J2 or the I/O group 2 ports.

8. EXBUS

This routine performs the same service as the RAM test except that the address parameters are different. The starting address is \$6800 and the ending address is \$6FFF.

9. CHECK



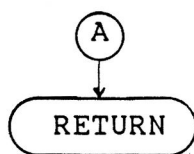


Figure A-9. Subroutine CHECK

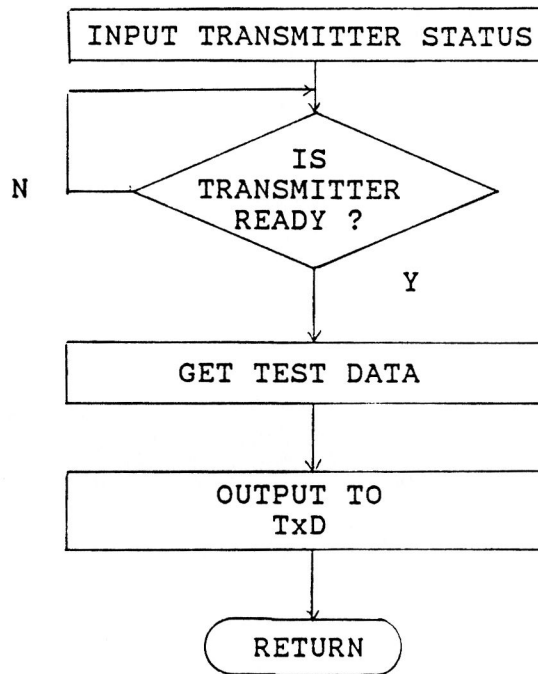
CHECK

The CHECK routine is functionally not doing anything, but merely confirming that all the registers can be written into and read from correctly.

This routine is called by MPU TEST A only.

10. TXTERA & RCVRA

A.



B.

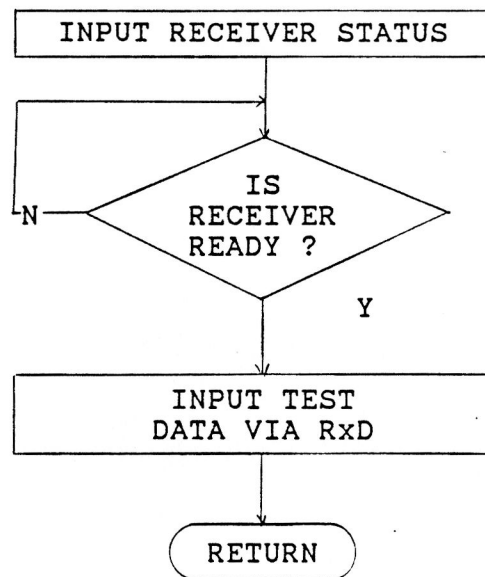


Figure A-10. A. Subroutine TXTERA B. Subroutine RCVRA

TXTERA & TXTERS

These routines are called by SERIAL. They transmit the test data sent by SERIAL to the output pin TxD. They also constantly check to see if the transmitter is ready before transmission occurs.

TXTERA is used when the serial port is configured in the Asynchronous mode, while TXTERS is used for Synchronous mode.

RCVRA & RCVRS

These routines are the same as above except that they are used for data reception.

APPENDIX B
PROGRAM LISTINGS

ASHBO MAIN

ISIS II 8080/8085 MACRO ASSEMBLER, V4.0

MODULE PAGE 1

LOC	OBJ	LINE	SOURCE STATEMENT
		1 ;	
		2 ;*****	
		3 ; PROGRAM NAME : MAIN	*
		4 ; DATE CREATED : JULY, 2 1986	*
		5 ; VERSION : 2.0	*
		6 ; PROGRAM INTENT: THIS IS THE MAIN DRIVER PROGRAM WHICH CALLED ALL	*
		7 ; THE OTHER TESTING ROUTINES LIKE SELF, MPU, ROM, RAM	*
		8 ; SERIAL, PARALL, EXBUS.	*
		9 ;*****	
		10 ;	
		11 ;////////////////////	
		12 ; VARIABLES DECLARATIONS	/
		13 ;////////////////////	
		14 ;	
00EE		15	USART0 EQU 0EEH ; OUTPUT DATA
00EF		16	USARTC EQU 0EFH ; OUTPUT CONTROL
00EE		17	USARTI EQU 0EEH ; INPUT DATA
00EF		18	USARTS EQU 0EFH ; INPUT STATUS
00E4		19	PORTA EQU 0E4H ; PORTA ADDRESS
00E5		20	PORTB EQU 0E5H ; PORTB ADDRESS
00E6		21	PORTC EQU 0E6H ; PORTC ADDRESS
00E7		22	GRP1C EQU 0E7H ; GROUP 1 CONTROL WORD ADDRESS
00E8		23	PORTD EQU 0E8H ; PORTD ADDRESS
00E9		24	PORTE EQU 0E9H ; PORTE ADDRESS
00EA		25	PORTF EQU 0EAH ; PORTF ADDRESS
00EB		26	GRP2C EQU 0EBH ; GROUP 2 CONTROL WORD ADDRESS
3C00		27	START EQU 3C00H ; STARTING ADDRESS OF RAM
0000		28	STARTS EQU 0000H ; STARTING ADDRESS OF SELF-TEST ROM
0000		29	STARTR EQU 0000H ; STARTING ADDRESS OF ROM
6000		30	STARTE EQU 6000H ; STARTING ADDRESS OF EXTERNAL RAM
		31 ;	
		32 ;////////////////////	
		33 ;	
		34	CSEG
0000		35	ORG 0000H
		36 ;	
0000 CD1E00	C	37 MAIN:	CALL SELF ; TEST THE ROM WITH SELF-TEST PROGRAM
0003 CD4D00	C	38	CALL MPU ; MICROPROCESSOR TEST
0006 CDE500	D	39	CALL ROM ; TEST THE ROM WITH SYSTEM PROGRAM
0007 CDAD00	D	40	CALL RAM ; TEST THE ONBOARD RAM
000C CDF905	C	41	CALL SERIAL ; TEST THE SERIAL PORT
000F CD0400	D	42	CALL PARALL ; TEST THE PARALLEL PORT
0012 CD0D01	D	43	CALL EXBUS ; TEST EXTERNAL SYSTEM BUS
		44 LIT:	;
0015 210000		45	LXI H,0000H ; SET ADDRESS LINE #15
0018 3E01		46	MVI A,00000001B ; SET DATA BIT 0
001A 77		47	MOV M,A ; MOVE 00000001 TO ADDR. 0000H
001B C31500	C	48	JMP LIT ; INFINITE LOOP JUST TO LIT LED
		49 ;	
		50 ;*****	
		51 ; SUBROUTINE: SELF	*
		52 ; THIS ROUTINE TESTS THE ROM CONTAINING THE SELF TEST PROGRAM.	*
		53 ;*****	
		54 ;	

LOC	OBJ	LINE	SOURCE STATEMENT
		55	SELF:
001C	21FFFF	56	LXI H,STARTS-1 ; BEGINNING ADDR. OF ROM MINUS ONE
0021	E400	57	ANI 00H ; CLEAR ACC., AND CARRY BIT
0023	47	58	MOV B,A ; CLEAR REGISTER B
0024	4F	59	MOV C,A ; CLEAR REGISTER C
		60	REPETH:
0025	79	61	MOV A,C
0026	23	62	INX H ; INCREMENT ADDR., POINTER
0027	B6	63	ADD H ; ACC. = ACC. + DATA = LSByte OF CHECKSUM
0028	B2C00 C	64	JNC NEXTM
002B	04	65	INR B ; MSByte OF 16 BIT CHECKSUM
		66	NEXTM:
002C	4F	67	MOV C,A ; PUT (A) IN TEMPORARY STORAGE
002D	EB	68	XCHG ; EXCHANGE REGISTER PAIRS HL AND DE
002E	7A	69	MOV A,D
002F	FE01	70	CFI 01H ; IS (A) = MSByte OF ENDING ADDRESS
0031	C22500 C	71	JNZ REPETH ; NO, GO AND FETCH MORE DATA
0034	7B	72	MOV A,E
0035	FE4C	73	CFI 4CH ; IS (A) = LSByte OF ENDING ADDRESS
0037	C22500 C	74	JNZ REPETH ; NO, GO AND FETCH MORE DATA
003A	79	75	MOV A,C ; RESTORE CONTENT OF REGISTER A
003B	FE33	76	CFI 033H ; THIS 16-BIT CHECKSUM IS YET TO BE DETER.,
003D	C24900 C	77	JNZ LED1 ; HALT EXECUTION IF NOT EQUAL
0040	7B	78	MOV A,B
0041	FE33	79	CFI 033H ; THIS 16-BIT CHECKSUM IS YET TO BE DETER.,
0043	C24900 C	80	JNZ LED1
0046	C34A00 C	81	JMP SELEND ; JUMP TO END OF SUBROUTINE SELF
		82	LED1:
0049	76	83	HLT
		84	SELEND:
004A	C9	85	RET ; END OF SUBROUTINE SELF
		86	;
		87	*****
		88	;
		89	SUBROUTINE: MFU *
		90	THIS ROUTINE TESTS THE MICROPROCESSOR IN TWO STEPS: *
		91	MICROPROCESSOR TEST PROCEDURE A: REGISTERS CHECK TEST *
		92	MICROPROCESSOR TEST PROCEDURE B: OTHER INSTRUCTIONS TEST *
		93	*****
		94	MFU:
004B	CD5200 C	95	CALL MFU1 ; MICROPROCESSOR REGISTER READ TEST
004E	CD6B00 C	96	CALL MFU2 ; MICROPROCESSOR OTHER INSTR., TEST
		97	;
0051	C9	98	RET ; EXIST MFU ROUTINE
		99	;
		100	*****
		101	;
		102	SUBROUTINE: MFU1 *
		103	THIS ROUTINE PERFORMS THE REGISTER READ TEST. *
		104	*****
		105	MFU1:
007F		106	CODEA SET 01111111B ; CODE WORD FOR REGISTER A
008F		107	CODEB SET 10111111B ; CODE WORD FOR REGISTER B
009F		108	CODEC SET 11011111B ; CODE WORD FOR REGISTER C
00EF		109	CODED SET 11101111B ; CODE WORD FOR REGISTER D

LOC	OBJ	LINE	SOURCE STATEMENT
00F7		110	CODEE SET 11110111B ; CODE WORD FOR REGISTER E
00FB		111	CODEH SET 11111011B ; CODE WORD FOR REGISTER H
00FD		112	CODEL SET 11111101B ; CODE WORD FOR REGISTER L
		113 ;	
0052	CD7501	C 114	CALL CHECK ; CALL REGISTER TEST ROUTINE
		115 ;	
00BF		116	CODEA SET 10111111B
00DF		117	CODEB SET 11011111B
00EF		118	CODEC SET 11101111B
00F7		119	CODED SET 11110111B
00FB		120	CODEE SET 11111011B
00FD		121	CODEH SET 11111101B
00FE		122	CODEL SET 11111110B
		123 ;	
0055	CD7501	C 124	CALL CHECK
		125 ;	
00BF		126	CODEA SET 11011111B
00EF		127	CODEB SET 11101111B
00F7		128	CODEC SET 11110111B
00FB		129	CODED SET 11111011B
00FD		130	CODEE SET 11111101B
00FE		131	CODEH SET 11111110B
007F		132	CODEL SET 01111111B
		133 ;	
0058	CD7501	C 134	CALL CHECK
		135 ;	
00EF		136	CODEA SET 11101111B
00F7		137	CODEB SET 11110111B
00FB		138	CODEC SET 11111011B
00FD		139	CODED SET 11111101B
00FE		140	CODEE SET 11111110B
007F		141	CODEH SET 01111111B
00BF		142	CODEL SET 10111111B
		143 ;	
005B	CD7501	C 144	CALL CHECK
		145 ;	
00F7		146	CODEA SET 11110111B
00FB		147	CODEB SET 11111011B
00FD		148	CODEC SET 11111101B
00FE		149	CODED SET 11111110B
007F		150	CODEE SET 01111111B
00BF		151	CODEH SET 10111111B
00BF		152	CODEL SET 11011111B
		153 ;	
005E	CD7501	C 154	CALL CHECK
		155 ;	
00FD		156	CODEA SET 11111011B
00FD		157	CODEB SET 11111101B
00FE		158	CODEC SET 11111110B
007F		159	CODED SET 01111111B
00BF		160	CODEE SET 10111111B
00BF		161	CODEH SET 11011111B
00EF		162	CODEL SET 11101111B
		163 ;	
0061	CD7501	C 164	CALL CHECK

LOC	OBJ	LINE	SOURCE STATEMENT
		165 ;	
00FD		166	CODEA SET 11111101B
00FE		167	CODEB SET 11111110B
007F		168	CODEC SET 01111111B
00BF		169	CODED SET 10111111B
00BF		170	CODEE SET 11011111B
00CF		171	CODEH SET 11101111B
00F7		172	CODEL SET 11110111B
		173 ;	
0044	CD7501	174	CALL CHECK
		175 ;	
00FE		176	CODEA SET 11111110B
007F		177	CODEB SET 01111111B
00BF		178	CODEC SET 10111111B
00BF		179	CODED SET 11011111B
00CF		180	CODEE SET 11101111B
00F7		181	CODEH SET 11110111B
00FB		182	CODEL SET 11111011B
		183 ;	
0047	CD7501	184	CALL CHECK
		185 ;	
004A	C9	186	RET ; EXIT THE MPU1 ROUTINE
		187 ;	
		188 ;*****	
		189 ; SUBROUTINE: MPU2 *	
		190 ; THIS ROUTINE TESTS THE OTHER INSTRUCTION SETS OF THE MICROPROCESSOR. *	
		191 ;*****	
		192 ;	
		193 MPU2:	
0090		194	CODEA SET 10000000B ; CODE WORD FOR REGISTER A
0040		195	CODEB SET 01000000B ; CODE WORD FOR REGISTER B
0020		196	CODEC SET 00100000B ; CODE WORD FOR REGISTER C
0010		197	CODED SET 00010000B ; CODE WORD FOR REGISTER D
0008		198	CODEE SET 00001000B ; CODE WORD FOR REGISTER E
0004		199	CODEH SET 00000100B ; CODE WORD FOR REGISTER H
0002		200	CODEL SET 00000010B ; CODE WORD FOR REGISTER L
		201 ;	
004B	3E80	202	MVI A,CODEA
004D	0640	203	MVI B,CODEB
004F	0C20	204	MVI C,CODEC
0071	1610	205	MVI D,CODED
0073	1C00	206	MVI E,CODEE
0075	2604	207	MVI H,CODEH
0077	2C02	208	MVI L,CODEL
		209 ;	
		210 ; THIS PORTION OF THE MPU2 PROGRAM EXERCISE THE ADD AND ADC INSTRUCTIONS	
		211 ;	
0079	37	212	STC ; SET CARRY BIT
007A	09	213	ADC B ; ADD (B) TO ACCUMULATOR WITH CARRY
007B	01	214	ADC C ; ADD (C) TO ACCUMULATOR
007C	02	215	ADC D ; ADD (D) TO ACCUMULATOR
007D	03	216	ADC E ; ADD (E) TO ACCU.,
007E	04	217	ADC H ; ADD (H) TO ACCU.,
007F	05	218	ADC L ; ADD (L) TO ACCU.,
0080	FEFF	219	CFI GTH ; COMPARE (A) WITH 11111111

LOC	OBJ	LINE	SOURCE STATEMENT
0082	C27301	C 220	JNZ ERROR ; IF NOT EQUAL, HALT EXECUTION
		221 ;	
0085	3E80	222	MVI A, CODEA ; RESTORE REGISTER A CODE WORD
0087	37	223	STC ; REPEAT THE ABOVE PROCESS EXCEPT THE
0088	80	224	ADD B ; ADC INSTR., IS SWITCHED TO A DIFFERENT
0089	87	225	ADC C ; REGISTER AND SO ON.
008A	82	226	ADD D
008B	83	227	ADD E
008C	84	228	ADD H
008D	85	229	ADD L
008E	2F	230	CMA
008F	FE00	231	CFI 00H
0091	C27301	C 232	JNZ ERROR
		233 ;	
0094	3E80	234	MVI A, CODEA
0096	37	235	STC
0097	80	236	ADD B
0098	81	237	ADD C
0099	8A	238	ADC D
009A	83	239	ADD E
009B	84	240	ADD H
009C	85	241	ADD L
009D	FEFF	242	CFI 0FFH
009F	C27301	C 243	JNZ ERROR
		244 ;	
00A2	3E80	245	MVI A, CODEA
00A4	37	246	STC
00A5	80	247	ADD B
00A6	81	248	ADD C
00A7	82	249	ADC D
00A8	8B	250	ADC E
00A9	84	251	ADD H
00AA	85	252	ADD L
00AB	2F	253	CMA
00AC	FE00	254	CFI 00H
00AE	C27301	C 255	JNZ ERROR
		256 ;	
00B1	3E80	257	MVI A, CODEA
00B3	37	258	STC
00B4	80	259	ADD B
00B5	81	260	ADD C
00B6	82	261	ADD D
00B7	83	262	ADD E
00B8	8C	263	ADC H
00B9	85	264	ADD L
00BA	FEFF	265	CFI 0FFH
00BC	C27301	C 266	JNZ ERROR
		267 ;	
00BF	3E80	268	MVI A, CODEA
00C1	37	269	STC
00C2	80	270	ADD B
00C3	81	271	ADD C
00C4	82	272	ADD D
00C5	83	273	ADD E
00C6	84	274	ADD H

LOC	OBJ	LINE	SOURCE STATEMENT
00C7	8D	275	ADC L
00C8	2F	276	CHA
00C9	FE00	277	CFI 00H
00CB	C27301	278	JNZ ERROR
		279 ;	
		280 ;	EXERCISE THE SUB AND ADD INSTRUCTIONS
		281 ;	
007F		282	CODEA SET 01111111B ; SET NEW CODE WORD FOR REGISTER A
		283 ;	
00CE	3E7F	284	MVI A,CODEA
00D0	37	285	STC
00D1	78	286	SDB D
00D2	71	287	SUB C
00D3	72	288	SUB D
00D4	73	289	SUB E
00D5	74	290	SUB H
00D6	75	291	SUB L
00D7	2F	292	CHA
00D8	FEFF	293	CFI 0FFH
00DA	C27301	294	JNZ ERROR
		295 ;	
00DB	3E7F	296	MVI A,CODEA
00DF	37	297	STC
00E0	70	298	SUB D
00E1	77	299	SDB C
00E2	72	300	SUB D
00E3	73	301	SUB E
00E4	74	302	SUB H
00E5	75	303	SUB L
00E6	FE00	304	CFI 00H
00E8	C27301	305	JNZ ERROR
		306 ;	
00EB	3E7F	307	MVI A,CODEA
00ED	37	308	STC
00EE	70	309	SUB D
00EF	71	310	SUB C
00F0	7A	311	SDB D
00F1	73	312	SUB E
00F2	74	313	SUB H
00F3	75	314	SUB L
00F4	2F	315	CHA
00F5	FEFF	316	CFI 0FFH
00F7	C27301	317	JNZ ERROR
		318 ;	
00FA	3E7F	319	MVI A,CODEA
00FC	37	320	STC
00FD	70	321	SUB D
00FE	71	322	SUB C
00FF	72	323	SUB D
0100	7B	324	SDB E
0101	74	325	SUB H
0102	75	326	SUB L
0103	FE00	327	CFI 00H
0105	C27301	328	JNZ ERROR
		329 ;	

LOC	OBJ	LINE	SOURCE STATEMENT
0108	3E7F	330	MVI A,CODEA
010A	37	331	STC
010B	70	332	SUB B
010C	71	333	SUB C
010D	72	334	SUB D
010E	73	335	SUB E
010F	7C	336	SUB H
0110	95	337	SUB L
0111	2F	338	CMA
0112	FEFF	339	CFI OFFH
0114	C27301	C 340	JNZ ERROR
		341 ;	
0117	3E7F	342	MVI A,CODEA
0119	37	343	STC
011A	70	344	SUB B
011B	71	345	SUB C
011C	72	346	SUB D
011D	73	347	SUB E
011E	74	348	SUB H
011F	7D	349	SUB L
0120	FE00	350	CFI 00H
0122	C27301	C 351	JNZ ERROR
		352 ;	
		353 ;	EXERCISE THE ORA AND ORI INSTRUCTIONS
		354 ;	
0080		355	CODEA SET 10000000B ; SET NEW CODE WORD FOR REGISTER A
		356 ;	
0125	3E80	357	MVI A,CODEA
0127	B0	358	ORA B
0128	B1	359	ORA C
0129	B2	360	ORA D
012A	B3	361	ORA E
012B	B4	362	ORA H
012C	B5	363	ORA L
012D	F601	364	ORI 01H
012F	FEFF	365	CFI OFFH
0131	C27301	C 366	JNZ ERROR
0134	2F	367	CMA
0135	FE00	368	CFI 00H
0137	C27301	C 369	JNZ ERROR
		370 ;	
007F		371	CODEA SET 01111111B
00BF		372	CODEB SET 10111111B
00DF		373	CODEC SET 11011111B
00EF		374	CODED SET 11101111B
00F7		375	CODEE SET 11110111B
00FB		376	CODEH SET 11111011B
00FD		377	CODEL SET 11111101B
		378 ;	
013A	3E7F	379	MVI A,CODEA
013C	06BF	380	MVI B,CODEB
013E	0EDF	381	MVI C,CODEC
0140	16EF	382	MVI D,CODED
0142	1EF7	383	MVI E,CODEE
0144	26FD	384	MVI H,CODEH

LOC	OBJ	LINE	SOURCE STATEMENT
0146	2EFD	385	MVI L,CODEL
		386	;
		387	EXERCISE THE ANA AND ANI INSTRUCTIONS
		388	;
014B	A0	389	ANA B
0149	A1	390	ANA C
014A	A2	391	ANA D
014B	A3	392	ANA E
014C	A4	393	ANA H
014D	A5	394	ANA L
014E	E400	395	ANI 00H
0150	FE00	396	CPI 00H
0152	C27301	397	JNZ ERROR
0155	2F	398	CMA
0156	FEFF	399	CPI OFFH
015B	C27301	400	JNZ ERROR
		401	;
		402	EXERCISE THE XRA AND XRI INSTRUCTIONS
		403	;
015B	3E7F	404	MVI A,CODEA ; SET NEW CODE WORD FOR REGISTER A
		405	;
015D	AB	406	XRA B
015E	A9	407	XRA C
015F	AA	408	XRA D
0160	AB	409	XRA E
0161	AC	410	XRA H
0162	AD	411	XRA L
0163	EE01	412	XRI 01H
0165	FEFF	413	CPI OFFH
0167	C27301	414	JNZ ERROR
016A	2F	415	CMA
016B	FE00	416	CPI 00H
016D	C27301	417	JNZ ERROR
		418	;
0170	C37401	419	JMP MPUEHD
		420	;
		421	ERROR!
0173	76	422	HLT
		423	MPUEHD!
0174	C9	424	RET ; EXIST THE MPU2 ROUTINE
		425	;
		426	*****
		427	SUBROUTINE: CHECK (CALLED BY MPU)
		428	THIS ROUTINE PERFORMS THE REGISTER CHECK TEST, THE SEQUENCE OF TEST
		429	IS AS FOLLOWS:
		430	1. ABAD,ACAC, . . . ,ALAL 2. DABA,DCBC, . . . ,BLDL
		431	3. CACA,CBCB, . . . ,CLCL 4. DABA,DBDB, . . . ,DLDL
		432	;
		433	ETC
		434	*****
		435	;
		436	CHECK:
0175	3E7F	437	MVI A,CODEA ; MOVE CODEA TO REGISTER A
0177	06DF	438	MVI B,CODEB ; MOVE CODEB TO REGISTER B
0179	0EDF	439	MVI C,CODEC ; MOVE CODEC TO REGISTER C

LOC	OBJ	LINE	SOURCE STATEMENT
017B	16EF	440	MVI D,CODED
017D	1EF7	441	MVI E,CODEE
017F	26FB	442	MVI H,CODEH
0181	2EFD	443	MVI L,CODEL
		444 ;	
		445 ;	ABAD REGISTER READ
		446 ;	
0183	FE7F	447	CFI CODEA ; READ (A) AND COMPARE WITH CODEA
0185	C27605	C 448	JNZ LED
0188	78	449	MOV A,D ; READ (D)
0189	B8	450	CMF B ; COMPARE (B) WITH CODED
018A	C27605	C 451	JNZ LED
018B	47	452	MOV B,A
018E	3E7F	453	MVI A,CODEA ; READ (A)
0190	DF	454	CMF A ; COMPARE (A) WITH CODEA
0191	C27605	C 455	JNZ LED
0194	78	456	MOV A,D ; READ (D)
0195	B8	457	CMF B ; COMPARE (B) WITH CODED
0196	C27605	C 458	JNZ LED
		459 ;	
		460 ;	ACAC REGISTER READ
		461 ;	
0199	3E7F	462	MVI A,CODEA
019B	FE7F	463	CFI CODEA
019D	C27605	C 464	JNZ LED
01A0	79	465	MOV A,C
01A1	B9	466	CMF C
01A2	C27605	C 467	JNZ LED
01A5	4F	468	MOV C,A
01A6	3E7F	469	MVI A,CODEA
01A8	FE7F	470	CFI CODEA
01AA	C27605	C 471	JNZ LED
01AD	79	472	MOV A,C
01AE	B9	473	CMF C
01AF	C27605	C 474	JNZ LED
		475 ;	
		476 ;	ADAD REGISTER READ
		477 ;	
01B2	3E7F	478	MVI A,CODEA
01B4	FE7F	479	CFI CODEA
01B6	C27605	C 480	JNZ LED
01B9	7A	481	MOV A,D
01BA	DA	482	CMF D
01BB	C27605	C 483	JNZ LED
01BE	57	484	MOV D,A
01BF	3E7F	485	MVI A,CODEA
01C1	FE7F	486	CFI CODEA
01C3	C27605	C 487	JNZ LED
01C6	7A	488	MOV A,D
01C7	DA	489	CMF D
01C8	C27605	C 490	JNZ LED
		491 ;	
		492 ;	ACAE REGISTER READ
		493 ;	
01CD	3E7F	494	MVI A,CODEA

LOC	OBJ	LINE	SOURCE STATEMENT
01CD	BF	495	CMF A
01CE	C27605	C 496	JNZ LED
01D1	7D	497	MOV A,E
01D2	BD	498	CMF E
01D3	C27605	C 499	JNZ LED
01D6	5F	500	MOV E,A
01D7	3E7F	501	MVI A,CODEA
01D9	FE7F	502	CFI CODEA
01DB	C27605	C 503	JNZ LED
01DE	7D	504	MOV A,E
01DF	BD	505	CMF C
01E0	C27605	C 506	JNZ LED
		507 ;	
		508 ;	ALAH REGISTER READ
		509 ;	
01E3	3E7F	510	MVI A,CODEA
01E5	FE7F	511	CFI CODEA
01E7	C27605	C 512	JNZ LED
01EA	7C	513	MOV A,H
01EB	BC	514	CMF H
01EC	C27605	C 515	JNZ LED
01EF	67	516	MOV H,A
01F0	3E7F	517	MVI A,CODEA
01F2	BF	518	CMF A
01F3	C27605	C 519	JNZ LED
01F6	7C	520	MOV A,H
01F7	BC	521	CMF H
01F8	C27605	C 522	JNZ LED
		523 ;	
		524 ;	ALAL REGISTER READ
		525 ;	
01FB	3E7F	526	MVI A,CODEA
01FD	FE7F	527	CFI CODEA
01FF	C27605	C 528	JNZ LED
0202	7D	529	MOV A,L
0203	BD	530	CMF L
0204	C27605	C 531	JNZ LED
0207	6F	532	MOV L,A
0208	3E7F	533	MVI A,CODEA
020A	FE7F	534	CFI CODEA
020C	C27605	C 535	JNZ LED
020F	7D	536	MOV A,L
0210	BD	537	CMF L
0211	C27605	C 538	JNZ LED
		539 ;	
		540 ;	DADA REGISTER READ
		541 ;	
0214	7D	542	MOV A,D
0215	BD	543	CMF D
0216	C27605	C 544	JNZ LED
0217	47	545	MOV D,A
021A	3E7F	546	MVI A,CODEA
021C	BF	547	CMF A
021D	C27605	C 548	JNZ LED
0220	7D	549	MOV A,D

LOC	OBJ	LINE	SOURCE STATEMENT
0221	B0	550	CMF B
0222	C27605	551	JNZ LCD
0225	3E7F	552	MVI A,CODEA
0227	B0	553	CMF A
0228	C27605	554	JNZ LCD
		555 ;	
		556 ;	BCRC REGISTER READ
		557 ;	
022B	70	558	MOV A,D
022C	B0	559	CMF B
022D	C27605	560	JNZ LCD
0230	47	561	MOV D,A
0231	79	562	MOV A,C
0232	B0	563	CMF C
0233	C27605	564	JNZ LCD
0236	4F	565	MOV C,A
0237	70	566	MOV A,D
0238	B0	567	CMF D
0239	C27605	568	JNZ LCD
023C	47	569	MOV D,A
023D	79	570	MOV A,C
023E	B0	571	CMF C
023F	C27605	572	JNZ LCD
0242	4F	573	MOV C,A
		574 ;	
		575 ;	BBBB REGISTER READ
		576 ;	
0243	70	577	MOV A,D
0244	B0	578	CMF D
0245	C27605	579	JNZ LCD
0248	47	580	MOV D,A
0249	7A	581	MOV A,D
024A	BA	582	CMF D
024B	C27605	583	JNZ LCD
024E	57	584	MOV D,A
024F	70	585	MOV A,D
0250	B0	586	CMF D
0251	C27605	587	JNZ LCD
0254	47	588	MOV D,A
0255	7A	589	MOV A,D
0256	BA	590	CMF D
0257	C27605	591	JNZ LCD
025A	57	592	MOV D,A
		593 ;	
		594 ;	DEDC REGISTER READ
		595 ;	
025B	70	596	MOV A,D
025C	B0	597	CMF D
025D	C27605	598	JNZ LCD
0260	47	599	MOV D,A
0261	7B	600	MOV A,E
0262	BB	601	CMF E
0263	C27605	602	JNZ LCD
0266	5F	603	MOV E,A
0267	70	604	MOV A,E

LOC	OBJ	LINE	SOURCE STATEMENT
0268	B8	605	CMF B
0269	C27605	606	JNZ LED
026C	47	607	MOV B,A
026D	7D	608	MOV A,C
026E	BB	609	CMF C
026F	C27605	610	JNZ LED
0272	5F	611	MOV C,A
		612 ;	
		613 ;	BH register READ
		614 ;	
0273	78	615	MOV A,B
0274	B8	616	CMF B
0275	C27605	617	JNZ LED
0278	47	618	MOV B,A
0279	7C	619	MOV A,H
027A	BC	620	CMF H
027B	C27605	621	JNZ LED
027C	67	622	MOV H,A
027F	78	623	MOV A,B
0280	B8	624	CMF B
0281	C27605	625	JNZ LED
0284	47	626	MOV B,A
0285	7C	627	MOV A,H
0286	BC	628	CMF H
0287	C27605	629	JNZ LED
028A	67	630	MOV H,A
		631 ;	
		632 ;	BL register READ
		633 ;	
028B	78	634	MOV A,B
028C	B8	635	CMF B
028D	C27605	636	JNZ LED
0290	47	637	MOV B,A
0291	7D	638	MOV A,L
0292	B8	639	CMF L
0293	C27605	640	JNZ LED
0296	6F	641	MOV L,A
0297	78	642	MOV A,B
0298	B8	643	CMF B
0299	C27605	644	JNZ LED
029C	47	645	MOV B,A
029D	7D	646	MOV A,L
029E	B8	647	CMF L
029F	C27605	648	JNZ LED
02A2	6F	649	MOV L,A
		650 ;	
		651 ;	CACA register READ
		652 ;	
02A3	77	653	MOV A,C
02A4	B7	654	CMF C
02A5	C27605	655	JNZ LED
02A8	4F	656	MOV C,A
02A9	3E7F	657	MVI A,CODEA
02AB	BF	658	CMF A
02AC	C27605	659	JNZ LED

LOC	OBJ	LINE	SOURCE STATEMENT
02AF	79	660	MOV A,C
02B0	B9	661	CMF C
02B1	C27605	662	JNZ LED
02B4	4F	663	MOV C,A
02B5	3E7F	664	MVI A,CODEA
02B7	B9	665	CMF A
02B8	C27605	666	JNZ LED
		667 ;	
		668 ;	CCCD REGISTER READ
		669 ;	
02BB	79	670	MOV A,C
02BC	B9	671	CMF C
02BD	C27605	672	JNZ LED
02C0	4F	673	MOV C,A
02C1	7B	674	MOV A,B
02C2	B0	675	CMF B
02C3	C27605	676	JNZ LED
02C6	47	677	MOV B,A
02C7	79	678	MOV A,C
02C8	B9	679	CMF C
02C9	C27605	680	JNZ LED
02CC	4F	681	MOV C,A
02CD	7B	682	MOV A,B
02CE	B8	683	CMF B
02CF	C27605	684	JNZ LED
02D2	47	685	MOV B,A
		686 ;	
		687 ;	CCCD REGISTER READ
		688 ;	
02D3	79	689	MOV A,C
02D4	B9	690	CMF C
02D5	C27605	691	JNZ LED
02D8	4F	692	MOV C,A
02D9	7A	693	MOV A,B
02DA	BA	694	CMF B
02DB	C27605	695	JNZ LED
02DE	57	696	MOV B,A
02DF	79	697	MOV A,C
02E0	B9	698	CMF C
02E1	C27605	699	JNZ LED
02E4	4F	700	MOV C,A
02E5	7A	701	MOV A,B
02E6	BA	702	CMF B
02E7	C27605	703	JNZ LED
02EA	57	704	MOV B,A
		705 ;	
		706 ;	CECE REGISTER READ
		707 ;	
02EB	79	708	MOV A,C
02EC	B9	709	CMF C
02ED	C27605	710	JNZ LED
02F0	4F	711	MOV C,A
02F1	7B	712	MOV A,C
02F2	B0	713	CMF C
02F3	C27605	714	JNZ LED

LOC	OBJ	LINE	SOURCE STATEMENT
02F3	5F	715	MOV E,A
02F7	79	716	MOV A,C
02F8	B9	717	CMF C
02F9	C27605	C 718	JNZ LED
02FC	4F	719	MOV C,A
02FD	7D	720	MOV A,C
02FE	BD	721	CMF C
02FF	C27605	C 722	JNZ LED
0302	5F	723	MOV E,A
		724 ;	
		725 ;	CHCH REGISTER READ
		726 ;	
0303	79	727	MOV A,C
0304	B9	728	CMF C
0305	C27605	C 729	JNZ LED
0308	4F	730	MOV C,A
0309	7C	731	MOV A,H
030A	BC	732	CMF H
030B	C27605	C 733	JNZ LED
030E	67	734	MOV H,A
030F	79	735	MOV A,C
0310	B9	736	CMF C
0311	C27605	C 737	JNZ LED
0314	4F	738	MOV C,A
0315	7C	739	MOV A,H
0316	BC	740	CMF H
0317	C27605	C 741	JNZ LED
031A	67	742	MOV H,A
		743 ;	
		744 ;	CLCL REGISTER READ
		745 ;	
031B	79	746	MOV A,C
031C	B9	747	CMF C
031D	C27605	C 748	JNZ LED
0320	4F	749	MOV C,A
0321	7D	750	MOV A,L
0322	BD	751	CMF L
0323	C27605	C 752	JNZ LED
0326	6F	753	MOV L,A
0327	79	754	MOV A,C
0328	B9	755	CMF C
0329	C27605	C 756	JNZ LED
032C	4F	757	MOV C,A
032D	7D	758	MOV A,L
032E	BD	759	CMF L
032F	C27605	C 760	JNZ LED
0332	6F	761	MOV L,A
		762 ;	
		763 ;	BABA REGISTER READ
		764 ;	
0335	7A	765	MOV A,B
0338	BA	766	CMF B
0339	C27605	C 767	JNZ LED
033B	67	768	MOV B,A
0339	5E7F	769	HVI A,CODE

LOC	OBJ	LINE	SOURCE STATEMENT
033B	BF	770	CHF A
033C	C27605	C 771	JNZ LED
033F	7A	772	MOV A,B
0340	BA	773	CHF B
0341	C27605	C 774	JNZ LED
0344	57	775	MOV D,A
0345	3E7F	776	HVI A,CODEA
0347	BF	777	CHF A
0348	C27605	C 778	JNZ LED
		779 ;	
		780 ;	DEDB REGISTER READ
		781 ;	
034B	7A	782	MOV A,D
034C	BA	783	CHF D
034D	C27605	C 784	JNZ LED
0350	57	785	MOV D,A
0351	70	786	MOV A,B
0352	B0	787	CHF B
0353	C27605	C 788	JNZ LED
0356	47	789	MOV B,A
0357	7A	790	MOV A,D
0358	BA	791	CHF D
0359	C27605	C 792	JNZ LED
035C	57	793	MOV D,A
035E	70	794	MOV A,B
035F	B0	795	CHF B
0360	C27605	C 796	JNZ LED
0362	47	797	MOV B,A
		798 ;	
		799 ;	DEEC REGISTER READ
		800 ;	
0363	7A	801	MOV A,D
0364	BA	802	CHF D
0365	C27605	C 803	JNZ LED
0368	57	804	MOV D,A
0369	72	805	MOV A,C
036A	B9	806	CHF C
036B	C27605	C 807	JNZ LED
036E	4F	808	MOV C,A
036F	7A	809	MOV A,D
0370	BA	810	CHF D
0371	C27605	C 811	JNZ LED
0374	57	812	MOV D,A
0375	72	813	MOV A,C
0376	B9	814	CHF C
0377	C27605	C 815	JNZ LED
037A	4F	816	MOV C,A
		817 ;	
		818 ;	DEDE REGISTER READ
		819 ;	
037B	7A	820	MOV A,D
037C	BA	821	CHF D
037D	C27605	C 822	JNZ LED
0380	57	823	MOV D,A
0381	7B	824	MOV A,E

LOC	OBJ	LINE	SOURCE STATEMENT
0302	BD	025	CMF E
0303	C27605	C 026	JNZ LED
0306	5F	027	MOV E,A
0307	7A	028	MOV A,D
0308	BA	029	CMF D
0309	C27605	C 030	JNZ LED
030C	57	031	MOV D,A
030D	7D	032	MOV A,E
030E	BB	033	CMF E
030F	C27605	C 034	JNZ LED
0392	5F	035	MOV E,A
		036 ;	
		037 ;	DIIDH REGISTER READ
		038 ;	
0393	7A	039	MOV A,D
0394	BA	040	CMF D
0395	C27605	C 041	JNZ LED
039D	57	042	MOV D,A
0399	7C	043	MOV A,H
039A	BC	044	CMF H
039B	C27605	C 045	JNZ LED
039E	67	046	MOV H,A
039F	7A	047	MOV A,D
03A0	BA	048	CMF D
03A1	C27605	C 049	JNZ LED
03A4	57	050	MOV D,A
03A5	7C	051	MOV A,H
03A6	BC	052	CMF H
03A7	C27605	C 053	JNZ LED
03AA	67	054	MOV H,A
		055 ;	
		056 ;	DIDL REGISTER READ
		057 ;	
03AB	7A	058	MOV A,D
03AC	BA	059	CMF D
03AD	C27605	C 060	JNZ LED
03B0	57	061	MOV D,A
03B1	7D	062	MOV A,L
03B2	BD	063	CMF L
03B3	C27605	C 064	JNZ LED
03B6	6F	065	MOV L,A
03B7	7A	066	MOV A,D
03B8	BA	067	CMF D
03B9	C27605	C 068	JNZ LED
03BC	57	069	MOV D,A
03BD	7D	070	MOV A,L
03BE	BD	071	CMF L
03BF	C27605	C 072	JNZ LED
03C2	6F	073	MOV L,A
		074 ;	
		075 ;	EAEA REGISTER READ
		076 ;	
03C3	7B	077	MOV A,E
03C4	BB	078	CMF E
03C5	C27605	C 079	JNZ LED

LOC	OBJ	LINE	SOURCE STATEMENT
03C8	5F	880	MOV E,A
03C9	3E7F	881	MVI A,CODEA
03CD	BF	882	CMF A
03CC	C27605	C 883	JNZ LED
03CF	7B	884	MOV A,E
03D0	BB	885	CMF E
03D1	C27605	C 886	JNZ LED
03D4	5F	887	MOV E,A
03D5	3E7F	888	MVI A,CODEA
03D7	BF	889	CMF A
03D8	C27605	C 890	JNZ LED
		891 ;	
		892 ;	EDEB REGISTER READ
		893 ;	
03DB	7B	894	MOV A,E
03DC	BB	895	CMF E
03DD	C27605	C 896	JNZ LED
03E0	5F	897	MOV E,A
03E1	7B	898	MOV A,B
03E2	BB	899	CMF B
03E3	C27605	C 900	JNZ LED
03E6	47	901	MOV B,A
03E7	7B	902	MOV A,E
03E8	BB	903	CMF E
03E9	C27605	C 904	JNZ LED
03EC	5F	905	MOV E,A
03ED	7B	906	MOV A,B
03EE	BB	907	CMF B
03EF	C27605	C 908	JNZ LED
03F2	47	909	MOV B,A
		910 ;	
		911 ;	EDEC REGISTER READ
		912 ;	
03F3	7B	913	MOV A,E
03F4	BB	914	CMF E
03F5	C27605	C 915	JNZ LED
03F8	5F	916	MOV E,A
03F9	79	917	MOV A,C
03FA	B9	918	CMF C
03FB	C27605	C 919	JNZ LED
03FE	4F	920	MOV C,A
03FF	7B	921	MOV A,E
0400	BB	922	CMF E
0401	C27605	C 923	JNZ LED
0404	5F	924	MOV E,A
0405	79	925	MOV A,C
0406	B9	926	CMF C
0407	C27605	C 927	JNZ LED
040A	4F	928	MOV C,A
		929 ;	
		930 ;	EDED REGISTER READ
		931 ;	
040B	7B	932	MOV A,E
040C	BB	933	CMF E
040D	C27605	C 934	JNZ LED

LOC	OBJ	LINE	SOURCE STATEMENT
0410	5F	935	MOV E,A
0411	7A	936	MOV A,D
0412	BA	937	CMF D
0413	C27605	C 938	JNZ LED
0416	57	939	MOV D,A
0417	7B	940	MOV A,E
0418	BB	941	CMF E
0419	C27605	C 942	JNZ LED
041C	5F	943	MOV E,A
041D	7A	944	MOV A,D
041E	BA	945	CMF D
041F	C27605	C 946	JNZ LED
0422	57	947	MOV D,A
		948 ;	
		949 ;	EIEH REGISTER READ
		950 ;	
0423	7B	951	MOV A,E
0424	BB	952	CMF E
0425	C27605	C 953	JNZ LED
0428	5F	954	MOV E,A
0429	7C	955	MOV A,H
042A	BC	956	CMF H
042B	C27605	C 957	JNZ LED
042E	67	958	MOV H,A
042F	7B	959	MOV A,E
0430	BB	960	CMF E
0431	C27605	C 961	JNZ LED
0434	5F	962	MOV E,A
0435	7C	963	MOV A,H
0436	BC	964	CMF H
0437	C27605	C 965	JNZ LED
043A	67	966	MOV H,A
		967 ;	
		968 ;	ELEL REGISTER READ
		969 ;	
043B	7B	970	MOV A,E
043C	BB	971	CMF E
043D	C27605	C 972	JNZ LED
0440	5F	973	MOV E,A
0441	7D	974	MOV A,L
0442	BD	975	CMF L
0443	C27605	C 976	JNZ LED
0446	6F	977	MOV L,A
0447	7D	978	MOV A,E
0448	BB	979	CMF E
0449	C27605	C 980	JNZ LED
044C	5F	981	MOV E,A
044D	7D	982	MOV A,L
044E	BD	983	CMF L
044F	C27605	C 984	JNZ LED
0452	6F	985	MOV L,A
		986 ;	
		987 ;	HAHA REGISTER READ
		988 ;	
0453	7C	989	MOV A,H

LOC	OBJ	LINE	SOURCE STATEMENT
0454	BC	990	CMF H
0455	C27605	C 991	JNZ LED
0458	67	992	MOV H,A
0459	3E7F	993	MVI A,CODEA
045B	BF	994	CMF A
045C	C27605	C 995	JNZ LED
045F	7C	996	MOV A,H
0460	BC	997	CMF H
0461	C27605	C 998	JNZ LED
0464	67	999	MOV H,A
0465	3E7F	1000	MVI A,CODEA
0467	BF	1001	CMF A
0468	C27605	C 1002	JNZ LED
		1003 ;	
		1004 ;	HDHB REGISTER READ
		1005 ;	
046D	7C	1006	MOV A,H
046C	BC	1007	CMF H
046D	C27605	C 1008	JNZ LED
0470	67	1009	MOV H,A
0471	78	1010	MOV A,B
0472	B8	1011	CMF B
0473	C27605	C 1012	JNZ LED
0476	47	1013	MOV B,A
0477	7C	1014	MOV A,H
0478	BC	1015	CMF H
0479	C27605	C 1016	JNZ LED
047C	67	1017	MOV H,A
047D	78	1018	MOV A,B
047E	B8	1019	CMF B
047F	C27605	C 1020	JNZ LED
0482	47	1021	MOV B,A
		1022 ;	
		1023 ;	HCHC REGISTER READ
		1024 ;	
0483	7C	1025	MOV A,H
0484	BC	1026	CMF H
0485	C27605	C 1027	JNZ LED
0488	67	1028	MOV H,A
0489	79	1029	MOV A,C
048A	B9	1030	CMF C
048B	C27605	C 1031	JNZ LED
048E	4F	1032	MOV C,A
048F	7C	1033	MOV A,H
0490	BC	1034	CMF H
0491	C27605	C 1035	JNZ LED
0494	67	1036	MOV H,A
0495	79	1037	MOV A,C
0496	B9	1038	CMF C
0497	C27605	C 1039	JNZ LED
049A	4F	1040	MOV C,A
		1041 ;	
		1042 ;	HDHB REGISTER READ
		1043 ;	
049D	7C	1044	MOV A,H

LOC	OBJ	LINE	SOURCE STATEMENT
049C	BC	1045	CHF H
049D	C27605	C 1046	JNZ LED
04A0	67	1047	MOV H,A
04A1	7A	1048	MOV A,D
04A2	BA	1049	CHF D
04A3	C27605	C 1050	JNZ LED
04A6	57	1051	MOV D,A
04A7	7C	1052	MOV A,H
04A8	BC	1053	CHF H
04A9	C27605	C 1054	JNZ LED
04AC	67	1055	MOV H,A
04AD	7A	1056	MOV A,D
04AE	BA	1057	CHF D
04AF	C27605	C 1058	JNZ LED
04B2	57	1059	MOV D,A
		1060 ;	
		1061 ;	HEHE REGISTER READ
		1062 ;	
04B3	7C	1063	MOV A,H
04B4	BC	1064	CHF H
04B5	C27605	C 1065	JNZ LED
04B8	67	1066	MOV H,A
04B9	7B	1067	MOV A,E
04BA	BB	1068	CHF E
04BB	C27605	C 1069	JNZ LED
04BE	5F	1070	MOV E,A
04BF	7C	1071	MOV A,H
04C0	BC	1072	CHF H
04C1	C27605	C 1073	JNZ LED
04C4	67	1074	MOV H,A
04C5	7D	1075	MOV A,E
04C6	BD	1076	CHF E
04C7	C27605	C 1077	JNZ LED
04CA	5F	1078	MOV E,A
		1079 ;	
		1080 ;	HLHL REGISTER READ
		1081 ;	
04CB	7C	1082	MOV A,H
04CC	BC	1083	CHF H
04CD	C27605	C 1084	JNZ LED
04D0	67	1085	MOV H,A
04D1	7D	1086	MOV A,L
04D2	BD	1087	CHF L
04D3	C27605	C 1088	JNZ LED
04D6	6F	1089	MOV L,A
04D7	7C	1090	MOV A,H
04D8	BC	1091	CHF H
04D9	C27605	C 1092	JNZ LED
04DC	67	1093	MOV H,A
04DD	7D	1094	MOV A,L
04DE	BD	1095	CHF L
04DF	C27605	C 1096	JNZ LED
04E2	6F	1097	MOV L,A
		1098 ;	
		1099 ;	LALA REGISTER READ

LOC	OBJ	LINE	SOURCE STATEMENT
		1100 ;	
04E3	7D	1101	MOV A,L
04E4	BD	1102	CMF L
04E5	C27605	C 1103	JNZ LED
04E8	6F	1104	MOV L,A
04E9	3E7F	1105	MVI A,CODEA
04EB	BF	1106	CMF A
04EC	C27605	C 1107	JNZ LED
04EF	7D	1108	MOV A,L
04F0	BD	1109	CMF L
04F1	C27605	C 1110	JNZ LED
04F4	6F	1111	MOV L,A
04F5	3E7F	1112	MVI A,CODEA
04F7	BF	1113	CMF A
04F8	C27605	C 1114	JNZ LED
		1115 ;	
		1116 ;	LDLB REGISTER READ
		1117 ;	
04FB	7D	1118	MOV A,L
04FC	BD	1119	CMF L
04FD	C27605	C 1120	JNZ LED
0500	6F	1121	MOV L,A
0501	78	1122	MOV A,B
0502	BD	1123	CMF B
0503	C27605	C 1124	JNZ LED
0506	47	1125	MOV D,A
0507	7D	1126	MOV A,L
0508	BD	1127	CMF L
0509	C27605	C 1128	JNZ LED
050C	6F	1129	MOV L,A
050D	78	1130	MOV A,B
050E	BD	1131	CMF B
050F	C27605	C 1132	JNZ LED
0512	47	1133	MOV D,A
		1134 ;	
		1135 ;	LCLC REGISTER READ
		1136 ;	
0513	7D	1137	MOV A,L
0514	BD	1138	CMF L
0515	C27605	C 1139	JNZ LED
0518	6F	1140	MOV L,A
0519	79	1141	MOV A,C
051A	B9	1142	CMF C
051B	C27605	C 1143	JNZ LED
051E	4F	1144	MOV C,A
051F	7D	1145	MOV A,L
0520	BD	1146	CMF L
0521	C27605	C 1147	JNZ LED
0524	6F	1148	MOV L,A
0525	79	1149	MOV A,C
0526	B9	1150	CMF C
0527	C27605	C 1151	JNZ LED
052A	4F	1152	MOV C,A
		1153 ;	
		1154 ;	LDLD REGISTER READ

LOC	OBJ	LINE	SOURCE STATEMENT
		1155 ;	
052B	7D	1156	MOV A,L
052C	BD	1157	CMF L
052D	C27605	C 1158	JNZ LED
0530	6F	1159	MOV L,A
0531	7A	1160	MOV A,D
0532	BA	1161	CMF D
0533	C27605	C 1162	JNZ LED
0536	57	1163	MOV D,A
0537	7D	1164	MOV A,L
053B	BD	1165	CMF L
0539	C27605	C 1166	JNZ LED
053C	6F	1167	MOV L,A
053D	7A	1168	MOV A,D
053E	BA	1169	CMF D
053F	C27605	C 1170	JNZ LED
0542	57	1171	MOV D,A
		1172 ;	
		1173 ;	LELE REGISTER READ
		1174 ;	
0543	7D	1175	MOV A,L
0544	BD	1176	CMF L
0545	C27605	C 1177	JNZ LED
054B	6F	1178	MOV L,A
0549	7B	1179	MOV A,E
054A	BB	1180	CMF E
054B	C27605	C 1181	JNZ LED
054E	5F	1182	MOV E,A
054F	7D	1183	MOV A,L
0550	BD	1184	CMF L
0551	C27605	C 1185	JNZ LED
0554	6F	1186	MOV L,A
0555	7B	1187	MOV A,E
0556	BB	1188	CMF E
0557	C27605	C 1189	JNZ LED
055A	5F	1190	MOV E,A
		1191 ;	
		1192 ;	LHLH REGISTER READ
		1193 ;	
055B	7D	1194	MOV A,L
055C	BD	1195	CMF L
055D	C27605	C 1196	JNZ LED
0560	6F	1197	MOV L,A
0561	7C	1198	MOV A,H
0562	BC	1199	CMF H
0563	C27605	C 1200	JNZ LED
0566	67	1201	MOV H,A
0567	7D	1202	MOV A,L
056B	BD	1203	CMF L
0569	C27605	C 1204	JNZ LED
056C	6F	1205	MOV L,A
056D	7C	1206	MOV A,H
056E	BC	1207	CMF H
056F	C27605	C 1208	JNZ LED
0572	67	1209	MOV H,A

LOC	OBJ	LINE	SOURCE STATEMENT
0573	C37705	C 1210	JMP CHKEND
		1211 ;	
		1212 LED1	
0576	76	1213	HLT
		1214 CHKEND1	
0577	C9	1215	RET ; EXIST THE CHECK ROUTINE
		1216 ;	
		1217 ;*****	
		1218 ; SUBROUTINE: SERIAL	
		1219 ;THIS ROUTINE TESTS INTEL 80/10A SERIAL PORT. THE TRANSMITTER	
		1220 ;OUTPUT IS ROUTED TO THE RECEIVER. THE TEST DATA ARE 1010101010 AND	
		1221 ;01010101, TO ENSURE THAT THE PORT IS ABLE TO FUNCTION IN DIFFERENT	
		1222 ;MODE OF OPERATIONS AND THERE IS NO STUCK-AT FAULTS.	
		1223 ;*****	
		1224 ;	
		1225 ;////////////////////////////////////	
		1226 ; TEST PART 1	
		1227 ; THIS PORTION INITIALIZES THE SERIAL PORT TO ASYNCHRONOUS MODE.	
		1228 ;////////////////////////////////////	
		1229 ;	
		1230 SERIAL:	
0578	3E40	1231	HVI A,01000000B ; RESET/RETURN TO MODE INPUT
057A	D3EF	1232	OUT USARTC
057C	3ECE	1233	HVI A,11001110B ; 2 STOP/16X RATE/8-BIT DATA (MODE INSTR.)
057E	D3EF	1234	OUT USARTC
0580	3E27	1235	HVI A,00100111B ; ENABLE TREN/DTR/RXE/RTS (COMMAND INSTR.)
0582	D3EF	1236	OUT USARTC
		1237 BEGIN1:	
0584	3A0000	D 1238	LDA DATA ; GET TEST PATTERN
0587	4F	1239	MOV C,A ; STORE IN REGISTER
0588	CDC705	C 1240	CALL TXTERA ; SERIAL PORT TRANSMIT
058B	CDD205	C 1241	CALL RCVR A ; SERIAL PORT RECEIVE
058E	FEAA	1242	CFI 0AAH ; COMPARE TxD AND RxD DATA
0590	C20200	D 1243	JNZ LED4 ; IF NOT EQUAL, DISPLAY ERROR MESSAGE
0593	3A0100	D 1244	LDA DATA+1 ; GET NEXT TEST PATTERN
0596	CDC705	C 1245	CALL TXTERA
0599	CDD205	C 1246	CALL RCVR A
059C	FE55	1247	CFI 55H
059E	C20200	D 1248	JNZ LED4
		1249 ;	
		1250 ;////////////////////////////////////	
		1251 ; TEST PART 2	
		1252 ; THIS PORTION INITIALIZES THE SERIAL PORT TO SYNCHRONOUS MODE.	
		1253 ;////////////////////////////////////	
		1254 ;	
		1255 INIT2:	
05A1	3E40	1256	HVI A,01000000B ; RESET/RETURN TO MODE INPUT
05A3	D3EF	1257	OUT USARTC
05A5	3EBC	1258	HVI A,10001100B ; 1 SYNC CHAR/SYNDET OUTPUT/8-BIT DATA
05A7	D3EF	1259	OUT USARTC
05A9	3E16	1260	HVI A,00010110B ; SYNC CHARACTER
05AB	D3EF	1261	OUT USARTC
05AD	3EA7	1262	HVI A,10100111B ; ENABLE HUNT/RXE/DTR/TREN/RTS
05AF	D3EF	1263	OUT USARTC
		1264 BEGIN2:	

LOC	OBJ	LINE	SOURCE STATEMENT
05B1	3A0000	D 1265	LDA DATA ; GET TEST PATTERN
05B4	4F	1266	MOV C,A
05B5	CDDC05	C 1267	CALL TXTERS
05B8	CDE405	C 1268	CALL RCVRS
05BD	3A0100	D 1269	LDA DATA+1 ; GET NEXT TEST PATTERN
05BC	CDDC05	C 1270	CALL TXTERS
05C1	CDE405	C 1271	CALL RCVRS
05C4	C30300	D 1272	JMP SEREND
		1273 ;	
		1274 ;	////////////////////////////////////
		1275 ;	SUBROUTINES: TXTERA - THIS ROUTINE CHECKS TO SEE IF THE TRANSMITTER /
		1276 ;	IS READY, THEN OUTPUT THE TEST DATA TO TxD. /
		1277 ;	RCVRA - THIS ROUTINE CHECKS TO SEE IF THE RECEIVER IS /
		1278 ;	IS READY, THEN INPUT THE DATA OUTPUT BY TxD VIA /
		1279 ;	RxD. /
		1280 ;	BOTH THESE ROUTINES ARE CALLED SERIAL ONLY. /
		1281 ;	////////////////////////////////////
		1282 ;	
		1283	TXTERA:
05C7	DDEF	1284	IN USARTS ; CHECK INPUT STATUS
05C9	E401	1285	ANI 00000001B ; IS TXTER READY ?
05CB	CAC705	C 1286	JZ TXTERA ; KEEP CHECKING UNTIL IT'S READY
05CE	79	1287	MOV A,C ; GET DATA
05CF	D3EE	1288	OUT USART0 ; OUTPUT DATA TO TxD
05D1	C9	1289	RET
		1290 ;	
		1291	RCVRA:
05D2	DDEF	1292	IN USARTS
05D4	E402	1293	ANI 00000010B ; IS RCVR READY ?
05D6	CAD205	C 1294	JZ RCVRA
05D9	DDEE	1295	IN USART1 ; INPUT DATA
05DB	C9	1296	RET
		1297 ;	
		1298 ;	////////////////////////////////////
		1299 ;	SUBROUTINES: TXTERS - SAME AS ABOVE EXCEPT OPERATE IN SYNCHRONOUS MODE /
		1300 ;	RCVRS - SAME AS ABOVE EXCEPT OPERATE IN SYNCHRONOUS MODE /
		1301 ;	BOTH THESE ROUTINES ARE CALLED BY SERIAL ONLY. /
		1302 ;	////////////////////////////////////
		1303 ;	
		1304	TXTERS:
05DC	DDEF	1305	IN USARTS
05DE	E401	1306	ANI 00000001B
05E0	CADC05	C 1307	JZ TXTERS
05E3	C9	1308	RET
		1309	RCVRS:
05E4	DDEF	1310	IN USARTS
05E6	E402	1311	ANI 00000010B
05E8	CAE405	C 1312	JZ RCVRS
		1313	AGAIN:
05EB	DDEF	1314	IN USARTS ; CHECK FOR SYNC CHARACTER
05ED	E440	1315	ANI 01000000B
05EF	CAED05	C 1316	JZ AGAIN
05F2	DDEE	1317	IN USART1 ; INPUT DATA
05F4	FEAA	1318	CP1 0AAH ; COMPARE WITH TEST DATA 10101010
05F6	C20306	C 1319	JNZ SYNERR

LOC	OBJ	LINE	SOURCE STATEMENT
05F9	DDEE	1320	IN USARTI ; INPUT DATA
05FD	FE55	1321	CPI 55H ; COMPARE WITH TEST DATA 01010101
05FD	C20306	C 1322	JNZ SYNERR
0600	C30406	C 1323	JMP SYNEND
		1324	;
		1325	SYNERR:
0603	76	1326	HLT
		1327	SYNEND:
0604	C9	1328	RET
		1329	;
		1330	DSEG
		1331	;
		1332	DATA:
0000	AA	1333	DB 0AAH,55H
0001	55		
		1334	;
		1335	LED4:
0002	76	1336	HLT
		1337	SEREND:
0003	C9	1338	RET ; EXIST SERIAL ROUTINE
		1339	;
		1340	*****
		1341	;
		1342	SUBROUTINE: PARALL *
		1343	THIS ROUTINE TESTS THE INTEL SBC 80/10A PARALLEL PORTS. ALL THE GROUP *
		1344	1 PORTS ARE CONFIGURED AS OUTPUTS AND GROUP 2 PORTS AS INPUTS. *
		1345	*****
		1346	PARALL:
0004	3E80	1347	MVI A,10000000B ; MODE 0/PORTS A, D AND C OUTPUTS
0006	D3E7	1348	OUT GRP1C ; OUTPUT TO GROUP 1 CONTROL WORD
0008	3E9B	1349	MVI A,10011011B ; MODE 0/PORTS D, E AND F INPUTS
000A	D3EB	1350	OUT GRP2C ; OUTPUT TO GROUP 2 CONTROL WORD
		1351	;
000C	3AA000	D 1352	LDA DATAJ1 ; GET FIRST TEST DATA
000F	D3E4	1353	OUT PORTA ; OUTPUT TO PORT A
0011	3AA100	D 1354	LDA DATAJ1+1
0014	D3E5	1355	OUT PORTB
0016	3AA200	D 1356	LDA DATAJ1+2
0019	D3E6	1357	OUT PORTC
001B	DDEB	1358	IN PORTD
001D	FE7A	1359	CPI 09AH ; COMPARE OUTPUT AND RECEIVED DATA
001F	C29F00	D 1360	JNZ LED5 ; IF NOT EQUAL, DISPLAY ERROR MESSAGE
0022	DDE7	1361	IN PORTE
0024	FEA5	1362	CPI 0A5H
0026	C29F00	D 1363	JNZ LED5
0029	DDEA	1364	IN PORTF
002B	FE27	1365	CPI 027H
002D	C20200	D 1366	JNZ LED4
0030	3AA300	D 1367	LDA DATAJ2 ; GET SECOND TEST DATA
0033	D3E4	1368	OUT PORTA ; OUTPUT TO PORT A
0035	3AA400	D 1369	LDA DATAJ2+1
0038	D3E5	1370	OUT PORTB
003A	3AA500	D 1371	LDA DATAJ2+2
003D	D3E6	1372	OUT PORTC
003F	DDEB	1373	IN PORTD

LOC	OBJ	LINE	SOURCE STATEMENT
0041	FE65	1374	CFI 065H
0043	C29F00	D 1375	JNZ LED5
0046	DDE9	1376	IN FORTE
0048	FE5A	1377	CFI 05AH
004A	C29F00	D 1378	JNZ LED5
004D	DDEA	1379	IN PORTF
004F	FED8	1380	CFI 0DBH
0051	C29F00	D 1381	JNZ LED5
0054	3AA600	D 1382	LDA DATAJ3
0057	D3E4	1383	OUT PORTA
0059	3AA700	D 1384	LDA DATAJ3+1
005C	D3E5	1385	OUT PORTB
005E	3AA800	D 1386	LDA DATAJ3+2
0061	D3E6	1387	OUT PORTC
0063	DDE8	1388	IN PORTD
0065	FE5A	1389	CFI 05AH
0067	C29F00	D 1390	JNZ LED5
006A	DDE9	1391	IN FORTE
006C	FEA5	1392	CFI 0A5H
006E	C29F00	D 1393	JNZ LED5
0071	DDEA	1394	IN PORTF
0073	FE5A	1395	CFI 05AH
0075	C29F00	D 1396	JNZ LED5
0078	3AA900	D 1397	LDA DATAJ4
007B	D3E4	1398	OUT PORTA
007D	3AAA00	D 1399	LDA DATAJ4+1
0080	D3E5	1400	OUT PORTB
0082	3A0200	D 1401	LDA DATA+2
0085	D3E6	1402	OUT PORTC
0087	DDE8	1403	IN PORTD
0089	FEA5	1404	CFI 0A5H
008B	C29F00	D 1405	JNZ LED5
008E	DDE9	1406	IN FORTE
0090	FE5A	1407	CFI 05AH
0092	C29F00	D 1408	JNZ LED5
0095	DDEA	1409	IN PORTF
0097	FE5A	1410	CFI 05AH
0099	C29F00	D 1411	JNZ LED5
009C	C3AC00	D 1412	JMP FAREND
		1413 ;	
		1414 LED5:	
009F	76	1415	IHLT
		1416 ;	
		1417	DSEG
		1418 ;	
		1419 DATAJ1:	
00A0	9A	1420	DB 09AH,0A5H,027H
00A1	A5		
00A2	27		
		1421 DATAJ2:	
00A3	65	1422	DB 065H,05AH,0DBH
00A4	5A		
00A5	D0		
		1423 DATAJ3:	
00A6	5A	1424	DB 05AH,0A5H,0A5H

LOC	OBJ	LINE	SOURCE STATEMENT
00A7	A5		
00AB	A5		
		1425	DATAJ41
00A9	A5	1426	DB 0A5H,05AH,05AH
00AA	5A		
00AB	5A		
		1427	;
		1428	PAREND:
00AC	C9	1429	RET ; EXIST PARALL ROUTINE
		1430	
		1431	
		1432	*****
		1433	;
		1434	SUBROUTINE: RAM *
		1435	THIS ROUTINE TESTS THE 1K BYTES OF RAM ON THE INTEL SBC 80/10A BOARD. *
		1436	THE FIRST TEST DATA 10101010 IS WRITTEN TO ALL THE RAM LOCATIONS AND *
		1437	THEN IS READ AGAIN. THE TEST IS REPEATED WITH THE SECOND TEST DATA *
		1438	101010101. THESE TESTS ARE DONE TO ENSURE THAT ALL RAM MEMORY CELLS *
		1439	ARE ACCESSIBLE AND THAT THERE IS NO STUCK AT FAULT. *
		1439	*****
		1440	;
		1441	RAM:
00AD	21003C	1442	LXI H,START ; STARTING ADDRESS OF RAM
00E0	3E55	1443	MVI A,01010101B ; FIRST TEST DATA
		1444	OUTER:
00B2	0604	1445	MVI B,04H ; 4 ITERATIONS OF OUTER LOOP
		1446	INNER:
00D4	0C00	1447	MVI C,00H ; 256 ITERATIONS OF INNER LOOP
		1448	WRITE:
00B6	77	1449	MOV M,A ; WRITE TEST DATA TO MEMORY
00B7	23	1450	INX H ; INCREMENT ADDRESS POINTER
00B8	0B	1451	DCR C ; DECREMENT INNER LOOP
00B9	C2B300	D 1452	JNZ WRITE ; REPEAT WRITE PROCEDURE
00BC	05	1453	DCR B ; DECREMENT OUTER LOOP
00BD	C2B400	D 1454	JNZ INNER
		1455	READ:
00C0	21003C	1456	LXI H,START
		1457	LOOP1:
00C3	0604	1458	MVI B,04H
		1459	LOOP2:
00C5	0E00	1460	MVI C,00H
		1461	COMP:
00C7	BE	1462	CMF M ; IS (MEMORY) = TEST DATA ?
00C8	C2C300	D 1463	JNZ LED3 ; NO, DISPLAY ERROR MESSAGE
00CB	36AA	1464	MVI M,10101010B ; WRITE SECOND TEST DATA TO MEMORY AFTER READ
00CD	23	1465	INX H ; NEXT MEMORY CELL
00CE	0B	1466	DCR C
00CF	C2C700	D 1467	JNZ COMP
00D2	05	1468	DCR B
00D3	C2C500	D 1469	JNZ LOOP2
00D6	FEAA	1470	CPI 10101010B
00D8	C2BC00	D 1471	JNZ GET
00DB	C3E400	D 1472	JMP RAMEND
		1473	GET:
00E1	3EAA	1474	MVI A,10101010B ; SECOND TEST DATA
00E0	C3C0C0	D 1475	JMP READ

LOC	OBJ	LINE	SOURCE STATEMENT
		1476	;
		1477	LED3:
00E3	76	1478	HLT
		1479	RAMEND:
00E4	C9	1480	RET ; EXIST RAM ROUTINE
		1481	;
		1482	*****
		1483	SUBROUTINE: ROM *
		1484	THIS ROUTINE TESTS THE ROM ON THE INTEL SRC 80/10A BOARD. THE EXTENDED*
		1485	PRECISION CHECKSUM IS GENERATED BY SUMMING ALL THE DATA BYTE IN THE *
		1486	ROM PLUS ANY CARRY IN A DIFFERENT REGISTER. THIS FORMED A 16 BIT VALUE*
		1487	CHECKSUM. THE GENERATED CHECKSUM IS THEN COMPARED WITH A PREDETERMINED*
		1488	VALUE DD10. *
		1489	*****
		1490	ROM:
00E5	21FF07	1491	LXI H,STARTR-1 ; STARTING ADDRESS OF ROM MINUS ONE
00E6	C600	1492	ANI 00H ; CLEAR ACC., AND CARRY BIT OF PSW
00EA	47	1493	MOV B,A ; HOLD CARRY
00EB	0E04	1494	MVI C,04H
		1495	ITER:
00EB	1600	1496	MVI D,00H
		1497	REPEAT:
00EF	23	1498	INX H
00F0	86	1499	ADD H ; ACC., = ACC., I DATA = LSByte OF CHECKSUM
00F1	D2F500	D 1500	JNC NEXT
00F4	04	1501	INR D
		1502	NEXT:
00F5	15	1503	DCR D
00F6	C2EF00	D 1504	JNZ REPEAT
00F7	0B	1505	DCR C
00FA	C2ED00	D 1506	JNZ ITER
00FD	FE10	1507	CPI 010H ; COMPARE LSByte OF CHECKSUM
00FF	C20B01	D 1508	JNZ LED2
0102	7B	1509	MOV A,B
0103	FE0B	1510	CPI 0DDH ; COMPARE HSByte OF CHECKSUM
0105	C20B01	D 1511	JNZ LED2
0108	C30C01	D 1512	JMP ROMEND
		1513	;
		1514	LED2:
		1515	
010B	76	1516	HLT
		1517	ROMEND:
010C	C9	1518	RET ; EXIST ROM ROUTINE
		1519	;
		1520	*****
		1521	SUBROUTINE: EXBUS *
		1522	THIS ROUTINE TESTS THE 2K BYTES OF EXTERNAL RAM CONNECTED TO THE EXTER- *
		1523	NAL BUS. THE FIRST TEST DATA 01010101 IS WRITTEN TO ALL THE RAM LOCAT- *
		1524	IONS AND THEN IS READ AGAIN. THE TEST IS REPEAT WITH THE SECOND TEST *
		1525	DATA 10101010. THESE TESTS ARE DONE TO ENSURE SOME OF THE COMMAND *
		1526	SIGNALS EXTERNAL SYSTEM BUS ARE FUNCTIONING PROPERLY. *
		1527	*****
		1528	;
		1529	EXBUS:
010D	21006B	1530	LXI H,STARTE ; BEGINNING ADDRESS OF EXTERNAL RAM

LOC	OBJ	LINE	SOURCE STATEMENT	
0110	3E55	1531	MVI A,01010101B	; FIRST TEST DATA
0112	1602	1532	MVI D,02H	; 2 ITERATIONS OF OUTERE LOOP
		1533	OUTERE:	
0114	0604	1534	MVI B,04H	; 4 ITERATIONS OF INNERE LOOP
		1535	INNERE:	
0116	0E00	1536	MVI C,00H	; 256 ITERATIONS OF WRITEE LOOP
		1537	WRITEE:	
0118	77	1538	MOV M,A	; WRITE FIRST TEST DATA TO MEMORY
0119	23	1539	INX H	; INCREMENT ADDRESSPOINTER
011A	0D	1540	DCR C	; DECREMENT INNERE LOOP
011B	C21801	D 1541	JNZ WRITEE	; REPEAT WRITEE LOOP IF C IS NOT ZERO
011E	05	1542	DCR B	
011F	C21601	D 1543	JNZ INNERE	
0122	15	1544	DCR D	
0123	C21401	D 1545	JNZ OUTERE	
		1546	READE:	
0126	21006B	1547	LXI H,STARTE	
0129	1602	1548	MVI D,02H	
		1549	LOOP1E:	
012B	0604	1550	MVI B,04H	
		1551	LOOP2E:	
012D	0E00	1552	MVI C,00H	
		1553	COMPE:	
012F	BE	1554	CMP M	; IS (MEMORY) = TEST DATA ?
0130	C24F01	D 1555	JNZ LED6	; NO, DISPLAY ERROR
0133	36AA	1556	MVI M,10101010B	
0135	23	1557	INX H	; INCREMENT ADDRESS POINTER
0136	0D	1558	DCR C	
0137	C22F01	D 1559	JNZ COMPE	
013A	05	1560	DCR B	
013B	C22D01	D 1561	JNZ LOOP2E	
013E	15	1562	DCR D	
013F	C22B01	D 1563	JNZ LOOP1E	
0142	FEAA	1564	CFI 10101010B	
0144	C24A01	D 1565	JNZ GETE	
0147	C35001	D 1566	JMP BUSEND	
		1567	GETE:	
014A	3EAA	1568	MVI A,10101010B	
014C	C32601	D 1569	JMP READE	
		1570	;	
		1571	LED6:	
014F	76	1572	HLT	
		1573	BUSEND:	
0150	C9	1574	RET	; EXIST EXBUS ROUTINE
		1575	;	
		1576	END	; END OF MAIN PROGRAM

PUBLIC SYMBOLS

EXTERNAL SYMBOLS

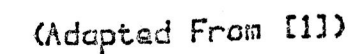
USER SYMBOLS

AGAIN C 05EB	BEGIN C 0504	BEGIN2 C 05B1	BUSEND D 0150	CHECK C 0175	CHKEND C 0577	CODCA A 007F
CODEB A 00BF	CODEC A 00DF	CODED A 00EF	CODEE A 00F7	CODEH A 00FB	CODEL A 00FD	COMP D 00C7
COMPE D 012F	DATA D 0000	DATAJ1 D 00A0	DATAJ2 D 00A3	DATAJ3 D 00A6	DATAJ4 D 00A9	ERROR C 0173
EXBUS D 010D	GET D 00DE	GETE D 014A	GRF1C A 00E7	GRF2C A 00EB	INIT2 C 05A1	INNER D 00B4
INNERE D 0116	ITER D 00ED	LED C 0576	LED1 C 0049	LED2 D 010B	LED3 D 00E3	LED4 D 0002
LED5 D 009F	LED6 D 014F	LIT C 0015	LOOP1 D 00C3	LOOP1E D 012B	LOOP2 D 00C5	LOOP2E D 012D
MAIN C 0000	MFU C 004B	MFU1 C 0052	MFU2 C 006B	MFUEND C 0174	NEXT D 00F5	NEXTH C 002C
OUTER D 00B2	OUTERE D 0114	PARALL D 0004	PAREND D 00AC	PORTA A 00E4	PORTB A 00E5	PORTC A 00E6
PORTD A 00EB	FORTE A 00E9	PORTF A 00EA	RAM D 00AD	RAMEND D 00E4	RCVRA C 05D2	RCVRS C 05E4
READ D 00C0	READE D 0126	REPEAT D 00EF	REFETH C 0025	ROM D 00E5	ROMEND D 010C	SELEND C 004A
SELF C 001E	SEREND D 0003	SERIAL C 057B	START A 3C00	STARTE A 6800	STARTR A 0B00	STARTS A 0000
SYNEND C 0604	SYNERR C 0603	TXTERA C 05C7	TXTERS C 05DC	USARTC A 00EF	USARTI A 00EE	USARTO A 00EE
USARTS A 00EF	WRITE D 00B6	WRITEE D 011B				

ASSEMBLY COMPLETE, NO ERRORS

APPENDIX C

SCHEMATICS FOR THE INTEL SBC 80/10A



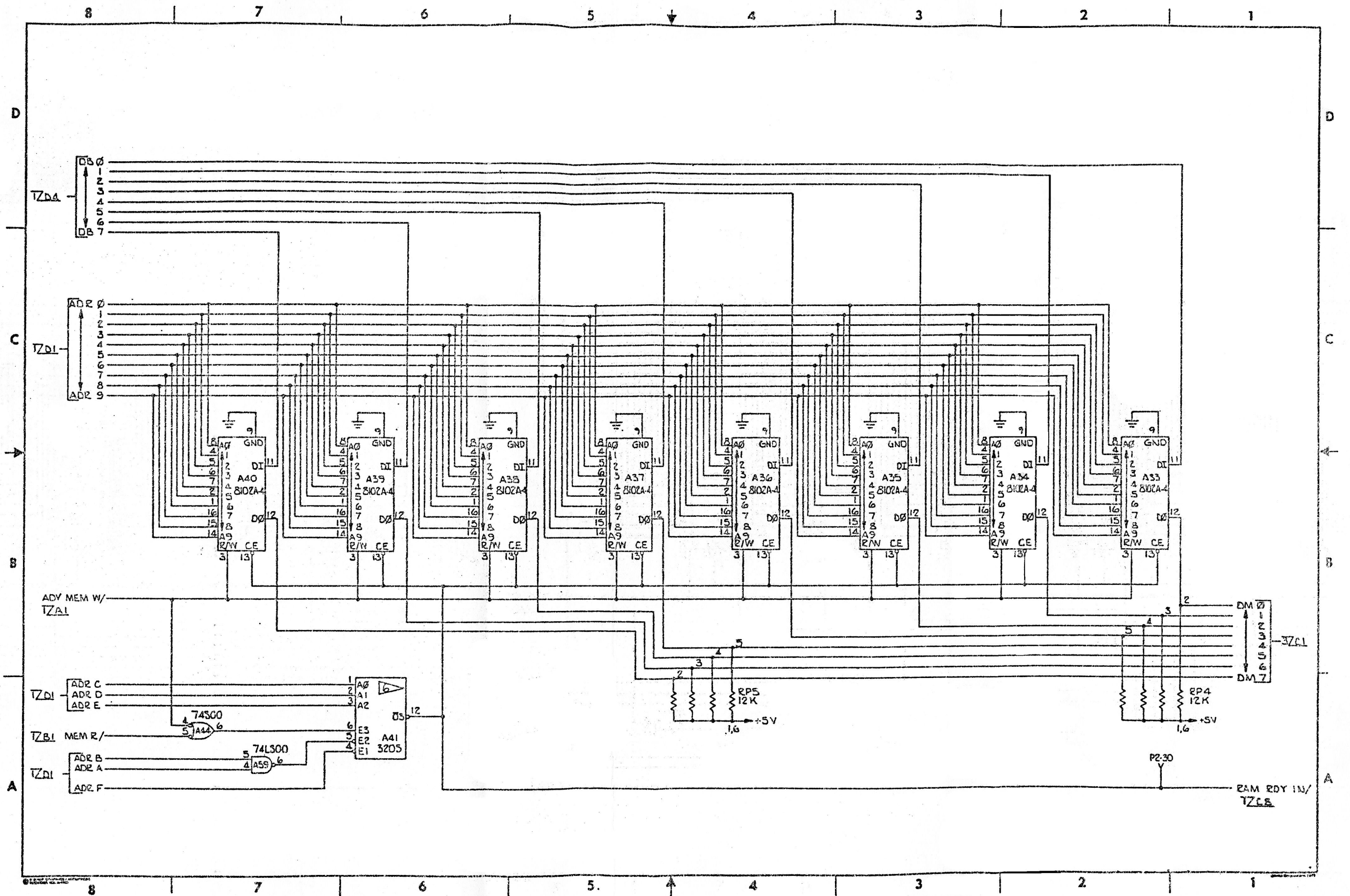
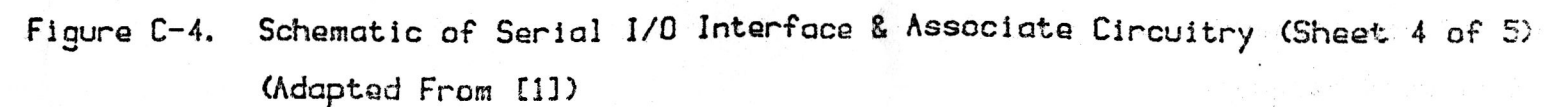


Figure C-2. Schematic of RAM & Associate Circuitry (Sheet 2 of 5)
(Adapted From [1])



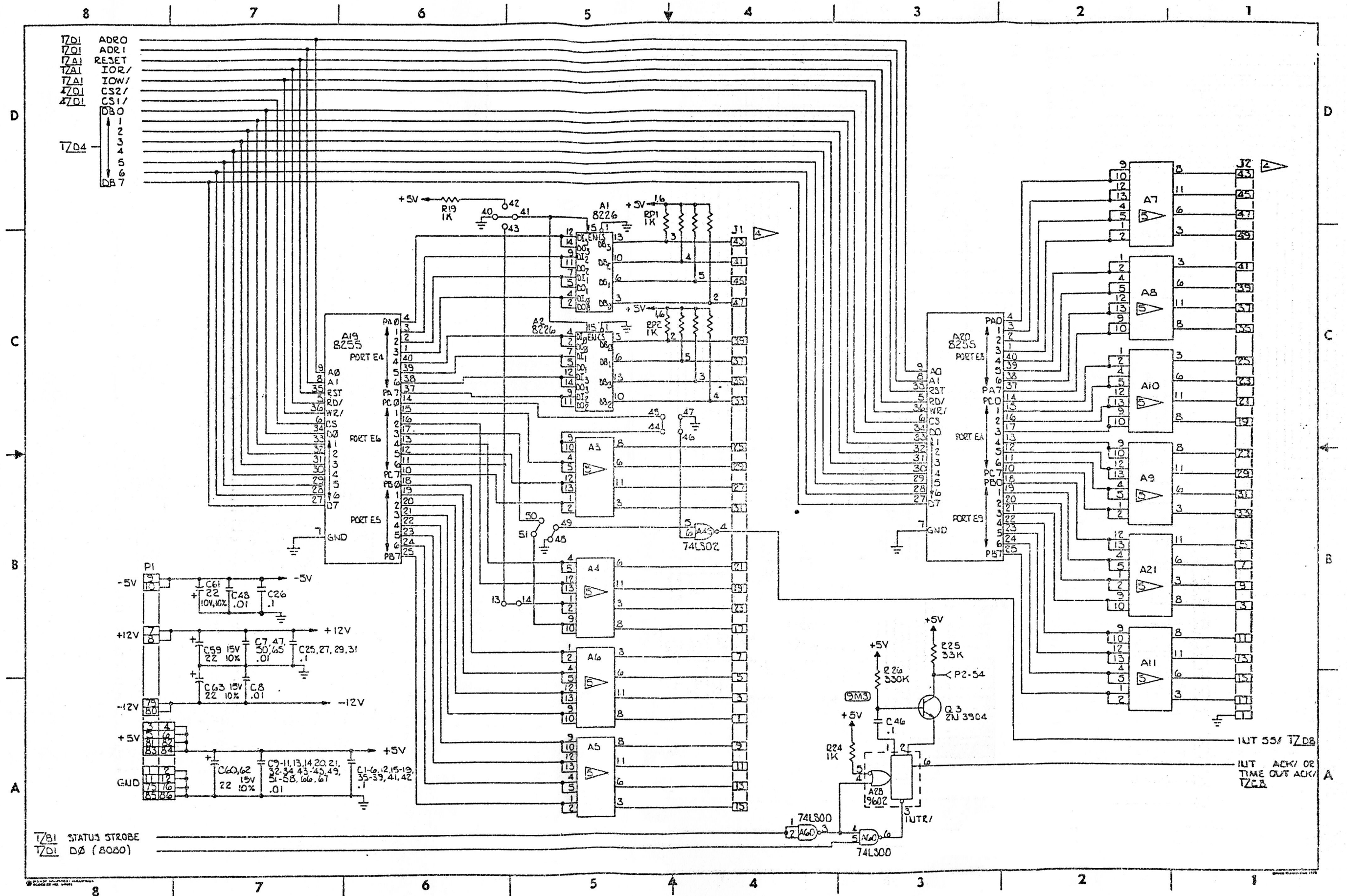


Figure C-5. Schematic of Parallel I/O Interface & Associate Circuitry (Sheet 5 of 5)

(Adapted From [1])

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ADDITION OF BUILT-IN SELF-TESTING CAPABILITY
TO THE INTEL SBC 80/10A SINGLE BOARD COMPUTER

by

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AN ABSTRACT OF A MASTER'S THESIS

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ABSTRACT

This thesis discusses the application of built-in self-testing technique at the board level (Intel SBC 80/10A single board computer). The test technologies used in testing microprocessor-based boards are briefly explained. It examines a spectrum of problems which are presenting the test engineers with some very formidable testing challenges and are also becoming increasingly hard for current automatic test equipment (ATE) test technology to deal with.

A functional description of the Intel SBC 80/10A board was briefly studied so that every essential part of the board is tested. The concept of built-in self-testing was then introduced and it was later explained why this concept is becoming an increasingly attractive solution to the complex problem of testing microprocessor-based boards.

Different testing methods were then designed to test the board's microprocessor, self-test ROM, system software ROM, RAM, parallel I/O ports, serial I/O port and the external system bus.

A summary of the test set up in the user testing environment was given and it also listed a series of events that should occur when the test was run.

Finally, fault-detection and isolation capability were explored as an expansion to the existing self-testing program.